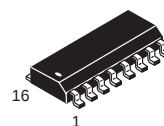




The MC13175 and MC13176 are one chip FM/AM transmitter subsystems designed for AM/FM communication systems. They include a Colpitts crystal reference oscillator, UHF oscillator, $\div 8$ (MC13175) or $\div 32$ (MC13176) prescaler and phase detector forming a versatile PLL system. Targeted applications are in the 260 to 470 MHz band and 902 to 928 MHz band covered by FCC Title 47; Part 15. Other applications include local oscillator sources in UHF and 900 MHz receivers, UHF and 900 MHz video transmitters, RF Local Area Networks (LANs), and high frequency clock drivers. The MC13175/76 offer the following features:

- UHF Current Controlled Oscillator
- Uses Easily Available 3rd Overtone or Fundamental Crystals for Reference
- Fewer External Parts Required
- Low Operating Supply Voltage (1.8 to 5.0 Vdc)
- Low Supply Drain Currents
- Power Output Adjustable (Up to +10 dBm)
- Differential Output for Loop Antenna or Balun Transformer Networks
- Power Down Feature
- ASK Modulated by Switching Output On and Off
- (MC13175) $f_0 = 8 \times f_{ref}$; (MC13176) $f_0 = 32 \times f_{ref}$

SEMICONDUCTOR
TECHNICAL DATA

D SUFFIX
PLASTIC PACKAGE
CASE 751B
(SO-16)

AM Modulator

Osc Tank

Coilcraft 150-05308

0.165 μ

V_{EE}

0.1 μ

150p

1.0k

f/N

VC

1.0k

MC13175-30p
MC13176-180p

MC13175
Crystal
3rd Overtone
40.000 MHz

0.01 μ

1.0k

0.82 μ

MC13176
Crystal
Fundamental
10 MHz

V_{CC}

100p (MC13176)

30p (MC13175)

1.3k

0.01 μ

V_{EE}

(1)

Z = 50 Ω

150p

RFC₁

V_{CC}

27k

S₁

V_{EE}

0.1 μ

S₂

RFout

SMA

- NOTES:**
1. 50 Ω coaxial balun, 1/10 wavelength at 320 MHz equals 1.5 inches.
 2. Pins 5, 10 & 15 are ground and connected to V_{EE} which is the component/DC ground plane side of PCB. These pins must be decoupled to V_{CC} ; decoupling capacitors should be placed as close as possible to the pins.
 3. The crystal oscillator circuit may be adjusted for frequency with the variable inductor (MC13175); recommended source is Coilcraft "slot seven" 7mm tuneable inductor, Part #7M3-821. 1.0k resistor. Shunting the crystal prevents it from oscillating in the fundamental mode

Osc 1	1	16	I _{mod}
NC	2	15	Out Gnd
NC	3	14	Out 2
Osc 4	4	13	Out 1
V _{EE}	5	12	V _{CC}
I _{Cont}	6	11	Enable
PD _{out}	7	10	Reg. Gnd
Xtaleb	8	9	Xtaleb

Device	Operating Temperature Range	Package
MC13175D	T _A = − 40° to +85°C	SO−16
MC13176D		SO−16

MC13175 MC13176

MAXIMUM RATINGS ($T_A = 25^{\circ}\text{C}$, unless otherwise noted.)

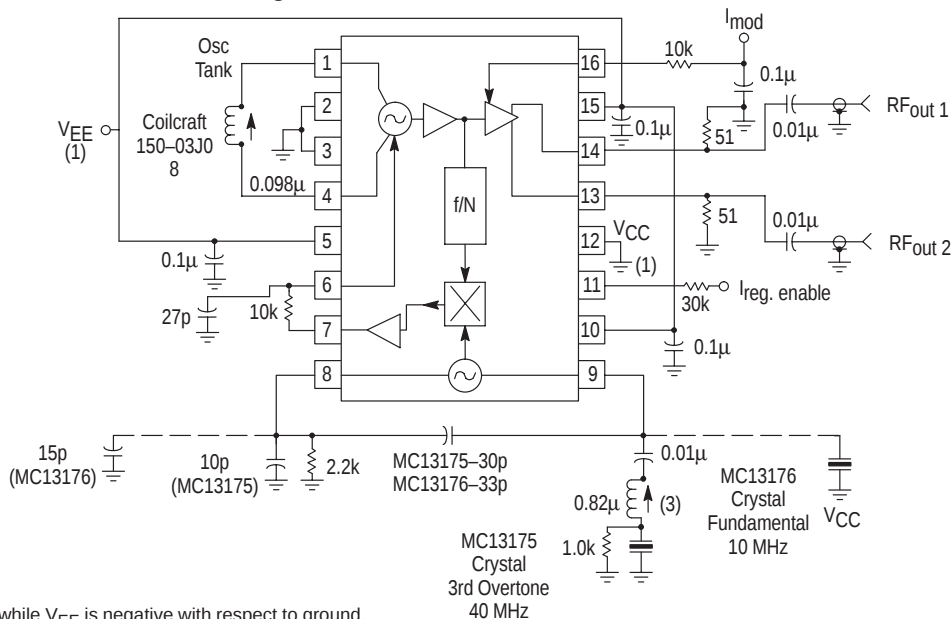
Rating	Symbol	Value	Unit
Power Supply Voltage	V_{CC}	7.0 (max)	Vdc
Operating Supply Voltage Range	V_{CC}	1.8 to 5.0	Vdc
Junction Temperature	T_J	+150	°C
Operating Ambient Temperature	T_A	− 40 to + 85	°C
Storage Temperature	T_{stg}	− 65 to +150	°C

ELECTRICAL CHARACTERISTICS (Figure 2; $V_{EE} = -3.0$ Vdc, $T_A = 25^\circ\text{C}$, unless otherwise noted.)*

Characteristic	Pin	Symbol	Min	Typ	Max	Unit
Supply Current (Power down: I_{11} & $I_{16} = 0$)	–	I_{EE1}	– 0.5	–	–	μA
Supply Current (Enable [Pin 11] to V_{CC} thru 30 k, $I_{16} = 0$)	–	I_{EE2}	–18	–14	–	mA
Total Supply Current (Transmit Mode) ($I_{mod} = 2.0$ mA; $f_0 = 320$ MHz)	–	I_{EE3}	– 39	– 34	–	mA
Differential Output Power ($f_0 = 320$ MHz; V_{ref} [Pin 9] = 500 mV _{p-p} ; $f_0 = N \times f_{ref}$) $I_{mod} = 2.0$ mA (see Figure 7, 8) $I_{mod} = 0$ mA	13 & 14	P_{out}	2.0 –	+ 4.7 – 45	– –	dBm
Hold-in Range ($\pm \Delta f_{ref} \times N$) MC13175 (see Figure 7) MC13176 (see Figure 8)	13 & 14	$\pm \Delta f_H$	3.5 4.0	6.5 8.0	– –	MHz
Phase Detector Output Error Current MC13175 MC13176	7	I_{error}	20 22	25 27	– –	μA
Oscillator Enable Time (see Figure 22b)	11 & 8	t_{enable}	–	4.0	–	ms
Amplitude Modulation Bandwidth (see Figure 24)	16	BW_{AM}	–	25	–	MHz
Spurious Outputs ($I_{mod} = 2.0$ mA) Spurious Outputs ($I_{mod} = 0$ mA)	13 & 14 13 & 14	P_{son} P_{soff}	– –	– 50 – 50	– –	dBc
Maximum Divider Input Frequency Maximum Output Frequency	– 13 & 14	f_{div} f_0	– –	950 950	– –	MHz

* For testing purposes, V_{CC} is ground (see Figure 2).

Figure 2. 320 MHz Test Circuit



- NOTES:** 1. V_{CC} is ground; while V_{EE} is negative with respect to ground. 40 MHz
2. Pins 5, 10 and 15 are brought to the circuit side of the PCB via plated through holes.
They are connected together with a trace on the PCB and each Pin is decoupled to V_{CC} (ground).
3. Recommended source is Coilcraft "slot seven" inductor, part number 7M3-821.

PIN FUNCTION DESCRIPTIONS

Pin	Symbol	Internal Equivalent Circuit	Description/External Circuit Requirements
1 & 4	Osc 1, Osc 4		CCO Inputs The oscillator is a current controlled type. An external oscillator coil is connected to Pins 1 and 4 which forms a parallel resonance LC tank circuit with the internal capacitance of the IC and with parasitic capacitance of the PC board. Three base-emitter capacitances in series configuration form the capacitance for the parallel tank. These are the base-emitters at Pins 1 and 4 and the base-emitter of the differential amplifier. The equivalent series capacitance in the differential amplifier is varied by the modulating current from the frequency control circuit (see Pin 6, internal circuit). A more thorough discussion is found in the Applications Information section.
5	V _{EE}		Supply Ground (V_{EE}) In the PCB layout, the ground pins (also applies to Pins 10 and 15) should be connected directly to chassis ground. Decoupling capacitors to V _{CC} should be placed directly at the ground returns.
6	I _{Cont}		Frequency Control For V _{CC} = 3.0 Vdc, the voltage at Pin 6 is approximately 1.55 Vdc. The oscillator is current controlled by the error current from the phase detector. This current is amplified to drive the current source in the oscillator section which controls the frequency of the oscillator. Figures 9 and 10 show the Δf_{osc} versus I _{Cont} . Figure 5 shows the Δf_{osc} versus I _{Cont} at -40°C, +25°C and +85°C for 320 MHz. The CCO may be FM modulated as shown in Figure 17, MC13176 320 MHz FM Transmitter. A detailed discussion is found in the Applications Information section.
7	PD _{out}		Phase Detector Output The phase detector provides $\pm 30 \mu A$ to keep the CCO locked at the desired carrier frequency. The output impedance of the phase detector is approximately 53 k Ω . Under closed loop conditions there is a DC voltage which is dependent upon the free running oscillator and the reference oscillator frequencies. The circuitry between Pins 7 and 6 should be selected for adequate loop filtering necessary to stabilize and filter the loop response. Low pass filtering between Pin 7 and 6 is needed so that the corner frequency is well below the sum of the divider and the reference oscillator frequencies, but high enough to allow for fast response to keep the loop locked. Refer to the Applications Information section regarding loop filtering and FM modulation.

PIN FUNCTION DESCRIPTIONS

Pin	Symbol	Internal Equivalent Circuit	Description/External Circuit Requirements
8	Xtale		Crystal Oscillator Inputs The internal reference oscillator is configured as a common emitter Colpitts. It may be operated with either a fundamental or overtone crystal depending on the carrier frequency and the internal prescaler. Crystal oscillator circuits and specifications of crystals are discussed in detail in the applications section. With $V_{CC} = 3.0$ Vdc, the voltage at Pin 8 is approximately 1.8 Vdc and at Pin 9 is approximately 2.3 Vdc. 500 to 1000 mVp-p should be present at Pin 9. The Colpitts is biased at 200 μ A; additional drive may be acquired by increasing the bias to approximately 500 μ A. Use 6.2 k from Pin 8 to ground.
9	Xtalb		
10	Reg. Gnd		Regulator Ground An additional ground pin is provided to enhance the stability of the system. Decoupling to the V_{CC} (RF ground) is essential; it should be done at the ground return for Pin 10.
11	Enable		Device Enable The potential at Pin 11 is approximately 1.25 Vdc. When Pin 11 is open, the transmitter is disabled in a power down mode and draws less than 1.0 μ A I_{CC} if the MOD at Pin 16 is also open (i.e., it has no current driving it). To enable the transmitter a current source of 10 μ A to 90 μ A is provided. Figures 3 and 4 show the relationship between I_{CC} , V_{CC} and $I_{reg. enable}$. Note that I_{CC} is flat at approximately 10 mA for $I_{reg. enable} = 5.0$ to 100 μ A ($I_{mod} = 0$).
12	V_{CC}		Supply Voltage (V_{CC}) The operating supply voltage range is from 1.8 Vdc to 5.0 Vdc. In the PCB layout, the V_{CC} trace must be kept as wide as possible to minimize inductive reactances along the trace; it is best to have it completely fill around the surface mount components and traces on the circuit side of the PCB.
13 & 14	Out 1 and Out 2		Differential Output The output is configured differentially to easily drive a loop antenna. By using a transformer or balun, as shown in the application schematic, the device may then drive an unbalanced low impedance load. Figure 6 shows how much the Output Power and Free-Running Oscillator Frequency change with temperature at 3.0 Vdc; $I_{mod} = 2.0$ mA.
15	Out_Gnd		Output Ground This additional ground pin provides direct access for the output ground to the circuit board V_{EE} .
16	I_{mod}		AM Modulation/Power Output Level The DC voltage at this pin is 0.8 Vdc with the current source active. An external resistor is chosen to provide a source current of 1.0 to 3.0 mA, depending on the desired output power level at a given V_{CC} . Figure 23 shows the relationship of Power Output to Modulation Current, I_{mod} . At $V_{CC} = 3.0$ Vdc, 3.5 dBm power output can be acquired with about 35 mA I_{CC} . For FM modulation, Pin 16 is used to set the desired output power level as described above. For AM modulation, the modulation signal must ride on a positive DC bias offset which sets a static (modulation off) modulation current. External circuitry for various schemes is further discussed in the Applications Information section.

Figure 3. Supply Current versus Supply Voltage

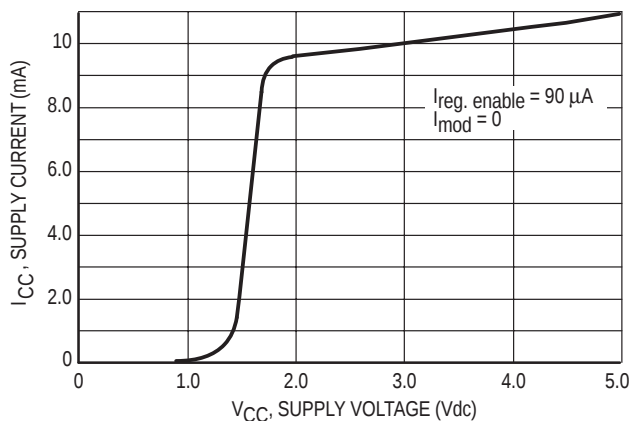


Figure 4. Supply Current versus Regulator Enable Current

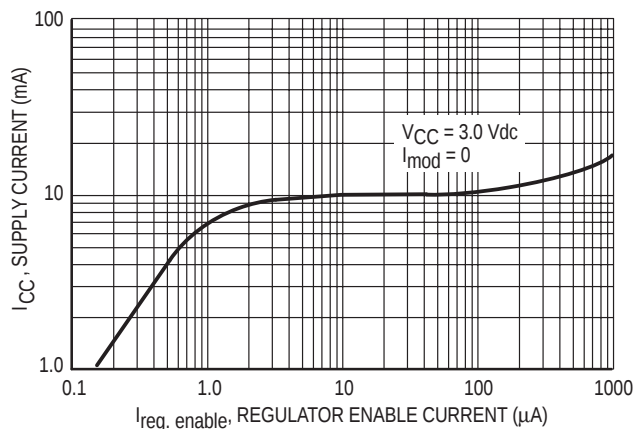


Figure 5. Change Oscillator Frequency versus Oscillator Control Current

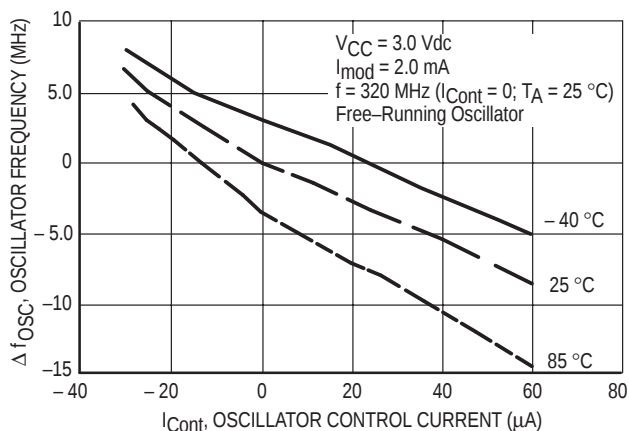


Figure 6. Change in Oscillator Frequency and Output Power versus Ambient Temperature

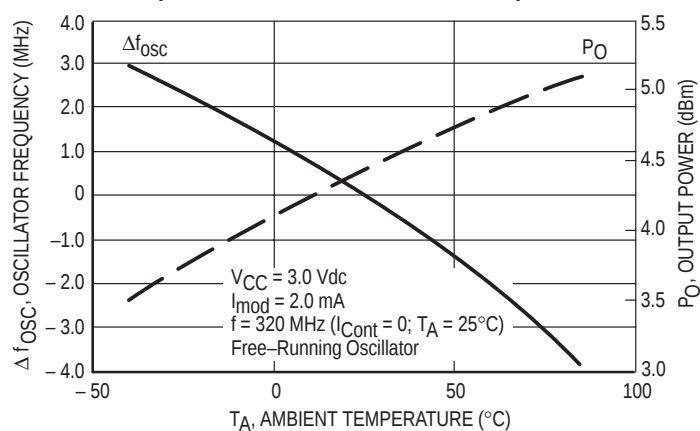


Figure 7. MC13175 Reference Oscillator Frequency versus Phase Detector Current

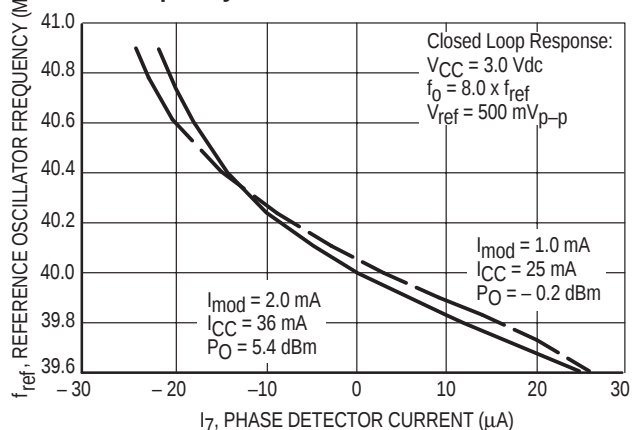


Figure 8. MC13176 Reference Oscillator Frequency versus Phase Detector Current

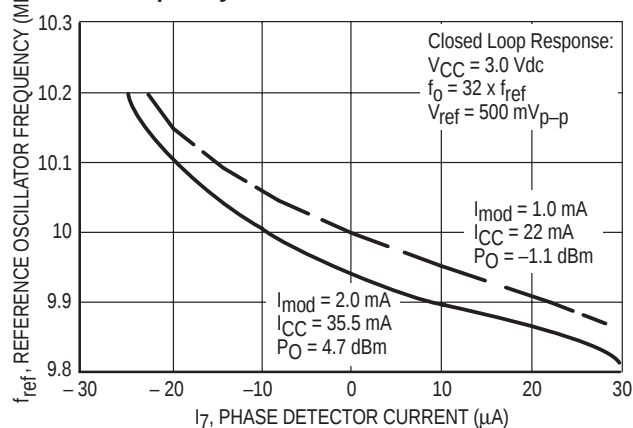


Figure 9. Change in Oscillator Frequency versus Oscillator Control Current

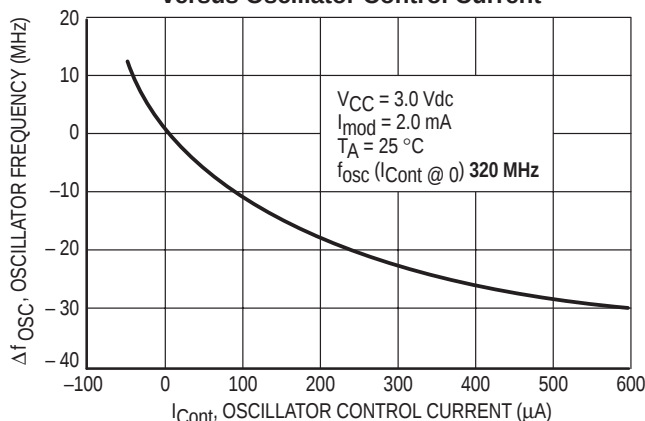
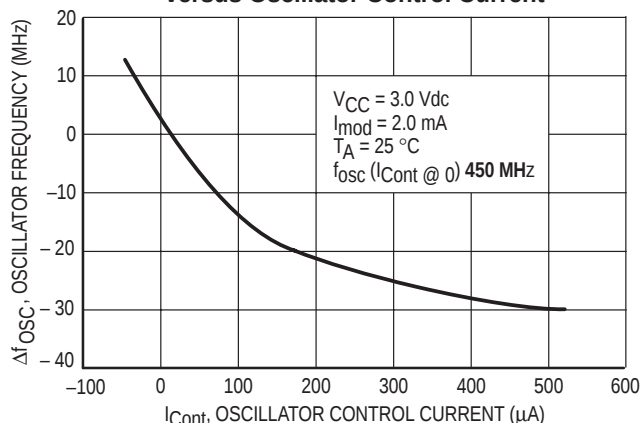


Figure 10. Change in Oscillator Frequency versus Oscillator Control Current



APPLICATIONS INFORMATION

Evaluation PC Board

The evaluation PCB, shown in Figures 26 and 27, is very versatile and is intended to be used across the entire useful frequency range of this device. The center section of the board provides an area for attaching all SMT components to the circuit side and radial leaded components to the component ground side of the PCB (see Figures 28 and 29). Additionally, the peripheral area surrounding the RF core provides pads to add supporting and interface circuitry as a particular application dictates. This evaluation board will be discussed and referenced in this section.

Current Controlled Oscillator (Pins 1 to 4)

It is critical to keep the interconnect leads from the CCO (Pins 1 and 4) to the external inductor symmetrical and equal in length. With a minimum inductor, the maximum free running frequency is greater than 1.0 GHz. Since this inductor will be small, it may be either a microstrip inductor, an air wound inductor or a tuneable RF coil. An air wound inductor may be tuned by spreading the windings, whereas tuneable RF coils are tuned by adjusting the position of an aluminum core in a threaded coilform. As the aluminum core coupling to the windings is increased, the inductance is decreased. The temperature coefficient using an aluminum core is better than a ferrite core. The UniCoil™ inductors made by Coilcraft may be obtained with aluminum cores (Part No. 51-129-169).

Ground (Pins 5, 10 and 15)

Ground Returns: It is best to take the grounds to a backside ground plane via plated through holes or eyelets at the pins. The application PCB layout implements this technique. Note that the grounds are located at or less than 100 mils from the devices pins.

Decoupling: Decoupling each ground pin to V_{CC} isolates each section of the device by reducing interaction between sections and by localizing circulating currents.

Loop Characteristics (Pins 6 and 7)

Figure 11 is the component block diagram of the MC1317XD PLL system where the loop characteristics are described by the gain constants. Access to individual components of this PLL system is limited, inasmuch as the loop is only pinned out at the phase detector output and the

frequency control input for the CCO. However, this allows for characterization of the gain constants of these loop components. The gain constants K_P , K_O and K_N are well defined in the MC13175 and MC13176.

Phase Detector (Pin 7)

With the loop in lock, the difference frequency output of the phase detector is DC voltage that is a function of the phase difference. The sinusoidal type detector used in this IC has the following transfer characteristic:

$$I_e = A \sin \theta_e$$

The gain factor of the phase detector, K_P (with the loop in lock) is specified as the ratio of DC output current, I_e to phase error, θ_e :

$$K_P = I_e / \theta_e \text{ (Amps/radians)}$$

$$K_P = A \sin \theta_e / \theta_e$$

$$\sin \theta_e \sim \theta_e \text{ for } \theta_e \leq 0.2 \text{ radians;}$$

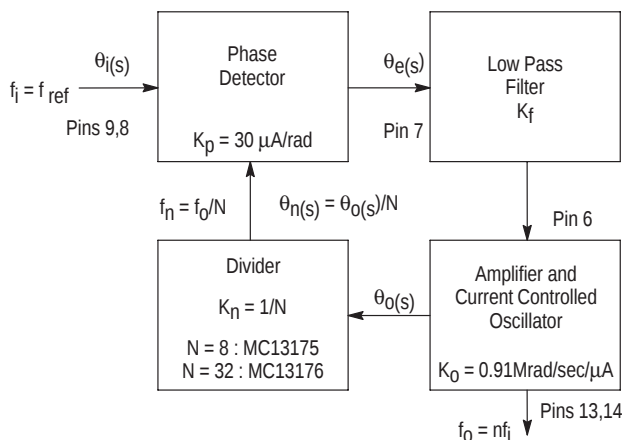
$$\text{thus, } K_P = A \text{ (Amps/radians)}$$

Figures 7 and 8 show that the detector DC current is approximately 30 μA where the loop loses lock at $\theta_e = \pm \pi/2$ radians; therefore, K_P is 30 μA /radians.

Current Controlled Oscillator, CCO (Pin 6)

Figures 9 and 10 show the non-linear change in frequency of the oscillator over an extended range of control current for 320 and 450 MHz applications. K_O ranges from approximately 6.3×10^5 rad/sec/ μA or 100 kHz/ μA (Figure 9) to 8.8×10^5 rad/sec/ μA or 140 kHz/ μA (Figure 10) over a relatively linear response of control current (0 to 100 μA). The oscillator gain factor depends on the operating range of the control current (i.e., the slope is not constant). Included in the CCO gain factor is the internal amplifier which can sink and source at least 30 μA of input current from the phase detector. The internal circuitry at Pin 6 limits the CCO control current to 50 μA of source capability while its sink capability exceeds 200 μA as shown in Figures 9 and 10. Further information to follow shows how to use the full capabilities of the CCO by addition of an external loop amplifier and filter (see Figure 15). This additional circuitry yields at $K_O = 0.145$ MHz/ μA or 9.1×10^5 rad/sec/ μA .

Figure 11. Block Diagram of MC1317XD PLL



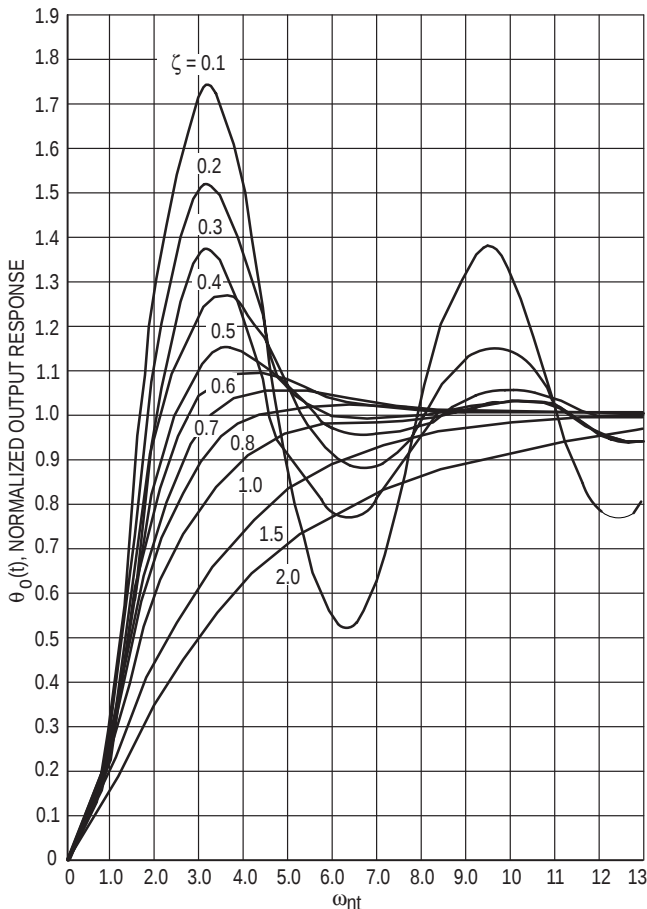
Where: K_p = Phase detector gain constant in $\mu A/rad$; $K_p = 30 \mu A/rad$
 K_f = Filter transfer function
 $K_n = 1/N$; $N = 8$ for the MC13175 and
 $N = 32$ for the MC13176
 K_o = CCO gain constant in $rad/sec/\mu A$
 $K_o = 9.1 \times 10^5 rad/sec/\mu A$

Loop Filtering

The fundamental loop characteristics, such as capture range, loop bandwidth, lock-up time and transient response are controlled externally by loop filtering.

The natural frequency (ω_n) and damping factor (∂) are important in the transient response to a step input of phase or frequency. For a given ∂ and lock time, ω_n can be determined from the plot shown in Figure 12.

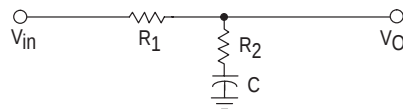
Figure 12. Type 2 Second Order Response



For $\partial = 0.707$ and lock time = 1.0 ms;
 then $\omega_n = 5.0/t = 5.0 krad/sec$.

The loop filter may take the form of a simple low pass filter or a lag-lead filter which creates an additional pole at origin in the loop transfer function. This additional pole along with that of the CCO provides two pure integrators ($1/s^2$). In the lag-lead low pass network shown in Figure 13, the values of the low pass filtering parameters R_1 , R_2 and C determine the loop constants ω_n and ∂ . The equations $t_1 = R_1 C$ and $t_2 = R_2 C$ are related in the loop filter transfer functions $F(s) = 1 + t_2 s / (1 + t_1 + t_2) s$.

Figure 13. Lag-Lead Low Pass Filter



The closed loop transfer function takes the form of a 2nd order low pass filter given by,

$$H(s) = K_v F(s) / s + K_v F(s)$$

From control theory, if the loop filter characteristic has $F(0) = 1$, the DC gain of the closed loop, K_v is defined as,

$$K_v = K_p K_o K_n$$

and the transfer function has a natural frequency,

$$\omega_n = (K_v / t_1 + t_2)^{1/2}$$

and a damping factor,

$$\partial = (\omega_n / 2) (t_2 + 1/K_v)$$

Rewriting the above equations and solving for the MC13176 with $\partial = 0.707$ and $\omega_n = 5.0 k rad/sec$:

$$\begin{aligned} K_v &= K_p K_o K_n = (30) (0.91 \times 10^6) (1/32) = 0.853 \times 10^6 \\ t_1 + t_2 &= K_v / \omega_n^2 = 0.853 \times 10^6 / (25 \times 10^6) = 34.1 \text{ ms} \\ t_2 &= 2\partial / \omega_n = (2) (0.707) / (5 \times 10^3) = 0.283 \text{ ms} \\ t_1 &= (K_v / \omega_n^2) - t_2 = (34.1 - 0.283) = 33.8 \text{ ms} \end{aligned}$$

For $C = 0.47 \mu$;

then, $R_1 = t_1/C = 33.8 \times 10^{-3}/0.47 \times 10^{-6} = 72 \text{ k}$

thus, $R_2 = t_2/C = 0.283 \times 10^{-3}/0.47 \times 10^{-6} = 0.60 \text{ k}$

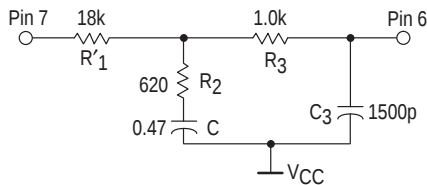
In the above example, the following standard value components are used,

$C = 0.47 \mu$; $R_2 = 620$ and $R'_1 = 72 \text{ k} - 53 \text{ k} \sim 18 \text{ k}$

(R'_1 is defined as $R_1 - 53 \text{ k}$, the output impedance of the phase detector.)

Since the output of the phase detector is high impedance ($\sim 50 \text{ k}$) and serves as a current source, and the input to the frequency control, Pin 6 is low impedance (impedance of the two diode to ground is approximately 500Ω), it is imperative that the second order low pass filter design above be modified. In order to minimize loading of the R_2C shunt network, a higher impedance must be established to Pin 6. A simple solution is achieved by adding a low pass network between the passive second order network and the input to Pin 6. This helps to minimize the loading effects on the second order low pass while further suppressing the sideband spurs of the crystal oscillator. A low pass filter with $R_3 = 1.0 \text{ k}$ and $C_2 = 1500 \text{ p}$ has a corner frequency (f_c) of 106 kHz ; the reference sideband spurs are down greater than -60 dBc .

Figure 14. Modified Low Pass Loop Filter



Hold-In Range

The hold-in range, also called the lock range, tracking range and synchronization range, is the ability of the CCO frequency, f_0 to track the input reference signal, $f_{\text{ref}} \cdot N$ as it gradually shifted away from the free running frequency, f_f . Assuming that the CCO is capable of sufficient frequency deviation and that the internal loop amplifier and filter are not overdriven, the CCO will track until the phase error, θ_e approaches $\pm\pi/2$ radians. Figures 5 through 8 are a direct

measurement of the hold-in range (i.e. $\Delta f_{\text{ref}} \times N = \pm \Delta f_H \times 2\pi$). Since $\sin \theta_e$ cannot exceed ± 1.0 , as θ_e approaches $\pm\pi/2$ the hold-in range is equal to the DC loop gain, $K_V \times N$.

$$\pm \Delta \omega_H = \pm K_V \times N$$

where, $K_V = K_P K_O K_N$.

In the above example,

$$\pm \Delta \omega_H = \pm 27.3 \text{ Mrad/sec}$$

$$\pm \Delta f_H = \pm 4.35 \text{ MHz}$$

Extended Hold-in Range

The hold-in range of about 3.4% could cause problems over temperature in cases where the free-running oscillator drifts more than 2 to 3% because of relatively high temperature coefficients of the ferrite tuned CCO inductor. This problem might worsen for lower frequency applications where the external tuning coil is large compared to internal capacitance at Pins 1 and 4. To improve hold-in range performance, it is apparent that the gain factors involved must be carefully considered.

K_N = is either 1/8 in the MC13175 or 1/32 in the MC13176.

K_P = is fixed internally and cannot be altered.

K_O = Figures 9 and 10 suggest that there is capability of greater control range with more current swing. However, this swing must be symmetrical about the center of the dynamic response. The suggested zero current operating point for $\pm 100 \mu\text{A}$ swing of the CCO is at about $+70 \mu\text{A}$ offset point.

K_a = External loop amplification will be necessary since the phase detector only supplies $\pm 30 \mu\text{A}$.

In the design example in Figure 15, an external resistor (R_5) of 15 k to V_{CC} (3.0 Vdc) provides approximately $100 \mu\text{A}$ of current boost to supplement the existing $50 \mu\text{A}$ internal source current. R_4 (1.0 k) is selected for approximately 0.1 Vdc across it with $100 \mu\text{A}$. R_1 , R_2 and R_3 are selected to set the potential at Pin 7 and the base of 2N4402 at approximately 0.9 Vdc and the emitter at 1.55 Vdc when error current to Pin 6 is approximately zero μA . C_1 is chosen to reduce the level of the crystal sidebands.

Figure 15. External Loop Amplifier

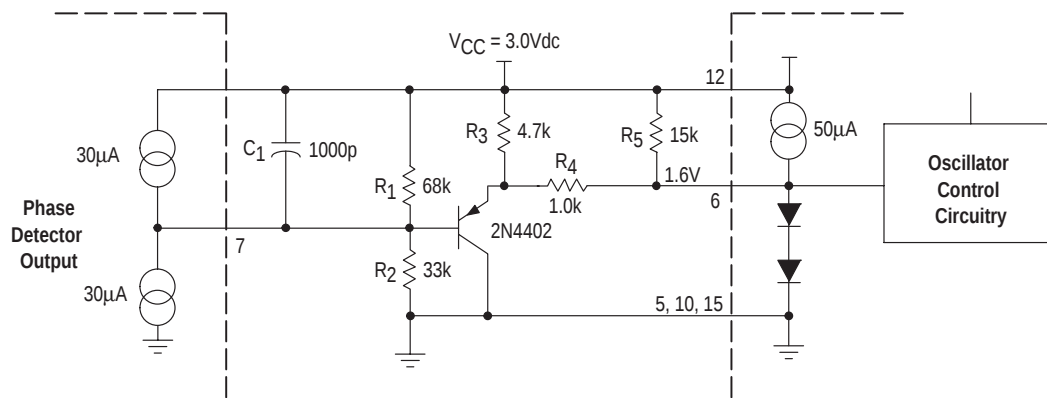
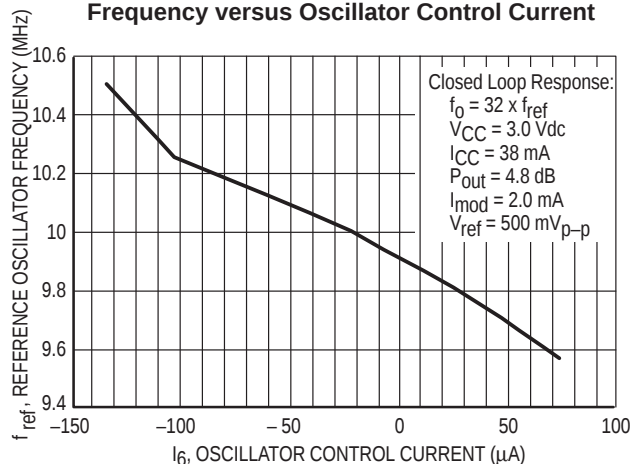


Figure 16 shows the improved hold-in range of the loop. The Δf_{ref} is moved 950 kHz with over 200 μA swing of control current for an improved hold-in range of ± 15.2 MHz or ± 95.46 Mrad/sec.

Figure 16. MC13176 Reference Oscillator Frequency versus Oscillator Control Current



Lock-in Range/Capture Range

If a signal is applied to the loop not equal to free running frequency, f_f , then the loop will capture or lock-in the signal by making $f_s = f_0$ (i.e. if the initial frequency difference is not too great). The lock-in range can be expressed as $\Delta\omega_L \sim \pm 2\omega_n$

FM Modulation

Noise external to the loop (phase detector input) is minimized by narrowing the bandwidth. This noise is minimal in a PLL system since the reference frequency is usually derived from a crystal oscillator. FM can be achieved by applying a modulation current superimposed on the control current of the CCO. The loop bandwidth must be narrow enough to prevent the loop from responding to the modulation frequency components, thus, allowing the CCO to deviate in frequency. The loop bandwidth is related to the natural frequency ω_n . In the lag-lead design example where the natural frequency, $\omega_n = 5.0$ krad/sec and a damping factor, $\partial = 0.707$, the loop bandwidth = 1.64 kHz. Characterization data of the closed loop responses for both the MC13175 and MC13176 at 320 MHz (Figures 7 and 8, respectively) show satisfactory performance using only a simple low-pass loop filter network. The loop filter response is strongly influenced by the high output impedance of the phase detector.

$$f_c = 0.159/RC;$$

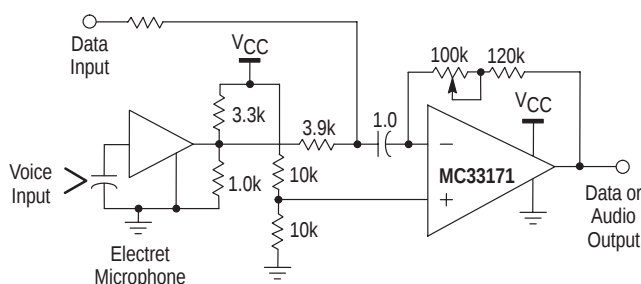
For $R = 1.0 \text{ k} + R_7$ ($R_7 = 53 \text{ k}$) and $C = 390 \text{ pF}$

$$f_c = 7.55 \text{ kHz or } \omega_c = 47 \text{ krad/sec}$$

The application example in Figure 17a of a 320 MHz FM transmitter demonstrates the FM capabilities of the IC. A high value series resistor (100 k) to Pin 6 sets up the current source to drive the modulation section of the chip. Its value is dependent on the peak to peak level of the encoding data and the maximum desired frequency deviation. The data input is AC coupled with a large coupling capacitor which is selected for the modulating frequency. The component placements on the circuit side and ground side of the PC board are shown in Figures 28 and 29, respectively. Figure 18a illustrates the input data of a 10 kHz modulating signal at 1.6 Vp-p. Figures 18b and 18c depict the deviation and resulting modulation spectrum showing the carrier null at -40 dBc. Figure 18d shows the unmodulated carrier power output at 3.5 dBm for $V_{CC} = 3.0$ Vdc.

For voice applications using a dynamic or an electret microphone, an op amp is used to amplify the microphone's low level output. The microphone amplifier circuit is shown in Figure 19. Figure 17b shows an application example for NBFM audio or direct FSK in which the reference crystal oscillator is modulated.

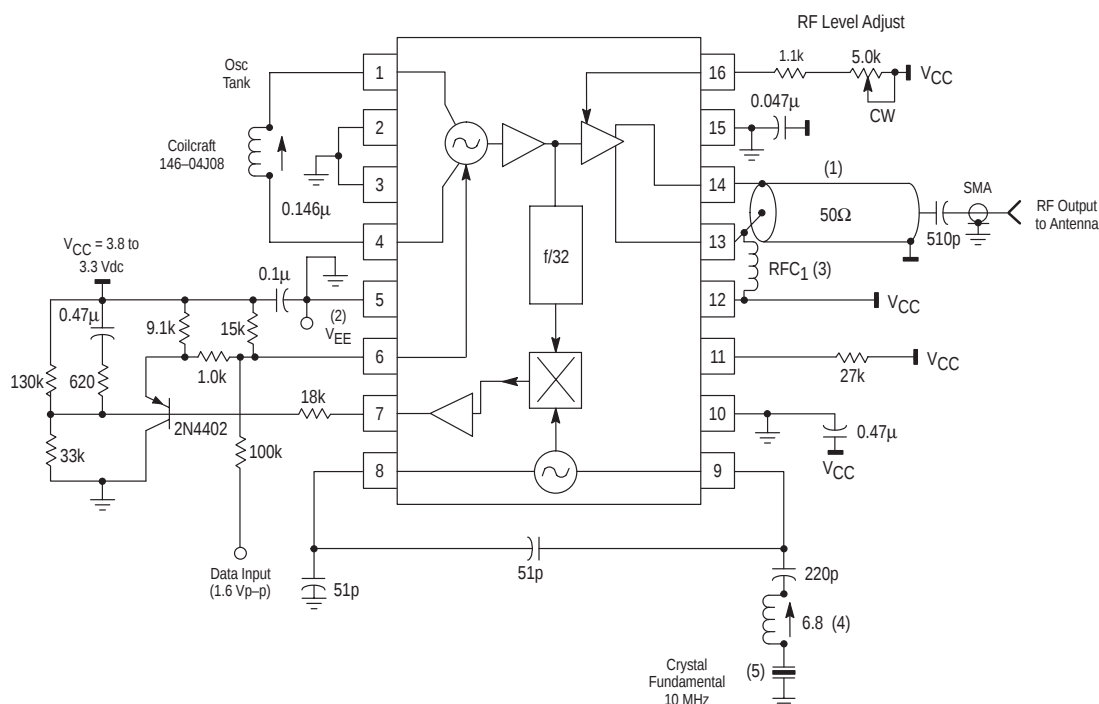
Figure 19. Microphone Amplifier



Local Oscillator Application

To reduce internal loop noise, a relatively wide loop bandwidth is needed so that the loop tracks out or cancels the noise. This is emphasized to reduce inherent CCO and divider noise or noise produced by mechanical shock and environmental vibrations. In a local oscillator application the CCO and divider noise should be reduced by proper selection of the natural frequency of the loop. Additional low pass filtering of the output will likely be necessary to reduce the crystal sideband spurs to a minimal level.

Figure 17a. 320 MHz MC13176D FM Transmitter



NOTES: 1. 50 Ω coaxial balun, 2 inches long.

2. Pins 5, 10 and 15 are grounds and connected to V_{EE} which is the component's side ground plane.

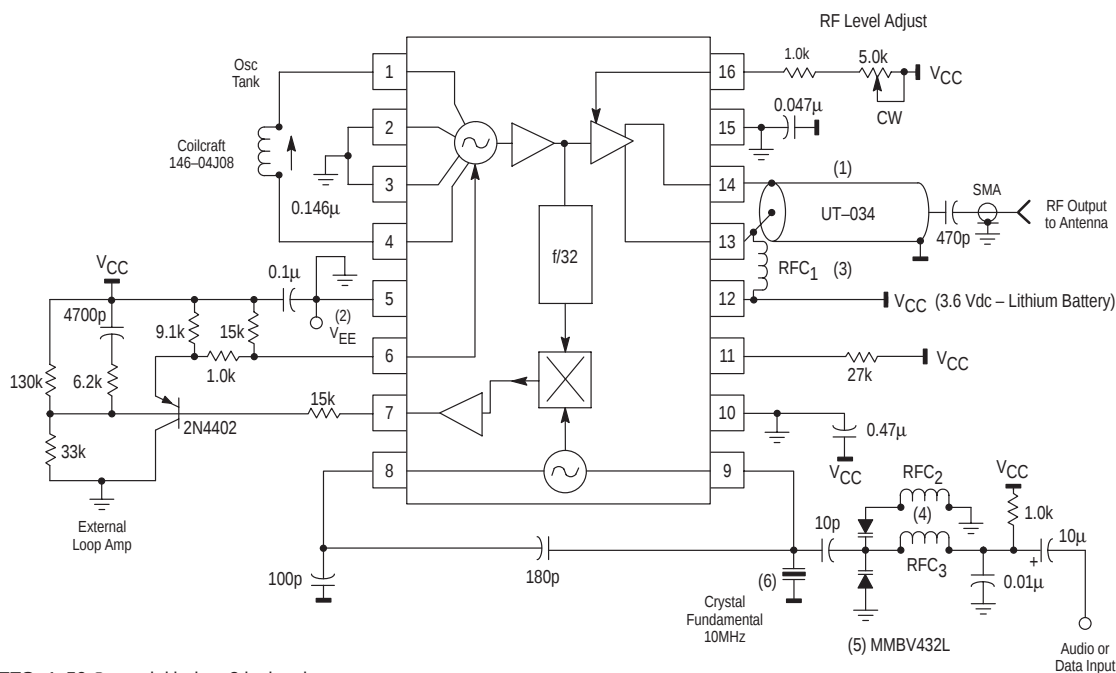
These pins must be decoupled to V_{CC} ; decoupling capacitors should be placed as close as possible to the pins.

3. RFC₁ is 180 nH Coilcraft surface mount inductor or 190 nH Coilcraft 146-05J08.

4. Recommended source is a Coilcraft "slot seven" 7.0 mm tuneable inductor, part #7M3-682.

5. The crystal is a parallel resonant, fundamental mode calibrated with 32 pF load capacitance.

Figure 17b. 320 MHz NBFM Transmitter



NOTES: 1. 50 Ω coaxial balun, 2 inches long.

2. Pins 5, 10 and 15 are grounds and connected to V_{EE} which is the component's side ground plane. These pins must be decoupled to V_{CC} ; decoupling capacitors should be placed as close as possible to the pins.

3. RFC₁ is 180 nH Coilcraft surface mount inductor.

4. RFC₂ and RFC₃ are high impedance crystal frequency of 10 MHz; 8.2 μ H molded inductor gives $X_L > 1000 \Omega$.

5. A single varactor like the MV2105 may be used whereby RFC₂ is not needed.

6. The crystal is a parallel resonant, fundamental mode calibrated with 32 pF load capacitance.

Figure 18a. Input Data Waveform

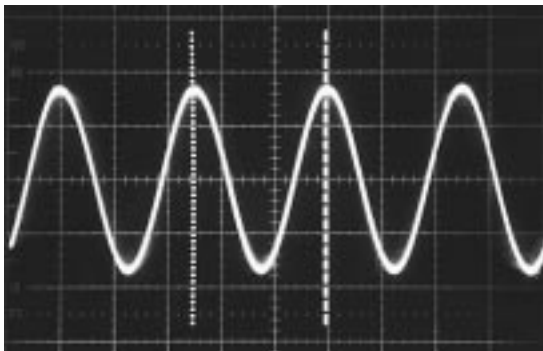


Figure 18b. Frequency Deviation



Figure 18c. Modulation Spectrum

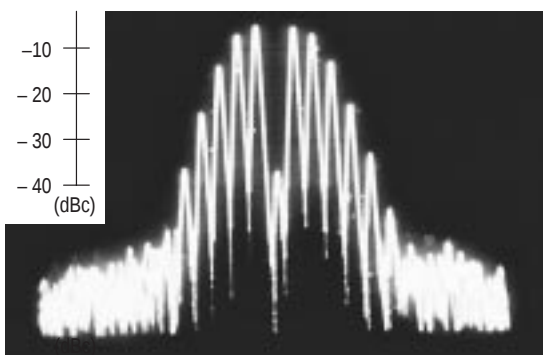


Figure 18d. Unmodulated Carrier



Reference Crystal Oscillator (Pins 8 and 9)

Selection of Proper Crystal: A crystal can operate in a number of mechanical modes. The lowest resonant frequency mode is its fundamental while higher order modes are called overtones. At each mechanical resonance, a crystal behaves like a RLC series-tuned circuit having a large inductor and a high Q. The inductor L_S is series resonance with a dynamic capacitor, C_S determined by the elasticity of the crystal lattice and a series resistance R_S , which accounts for the power dissipated in heating the crystal. This series RLC circuit is in parallel with a static capacitance, C_P which is created by the crystal block and by the metal plates and leads that make contact with it.

Figure 20 is the equivalent circuit for a crystal in a single resonant mode. It is assumed that other modes of resonance are so far off frequency that their effects are negligible.

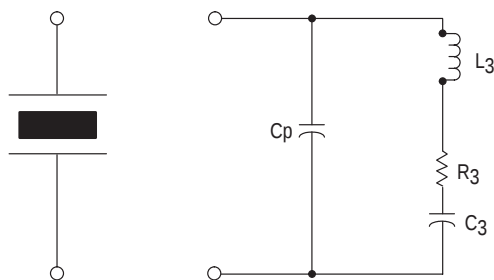
Series resonant frequency, f_S is given by;

$$f_S = 1/2\pi(L_S C_S)^{1/2}$$

and parallel resonant frequency, f_P is given by;

$$f_P = f_S(1 + C_S/C_P)^{1/2}$$

Figure 20. Crystal Equivalent Circuit



the frequency separation at resonance is given by;

$$\Delta f = f_P - f_S = f_S[1 - (1 + C_S/C_P)^{-1/2}]$$

Usually f_P is less than 1% higher than f_S , and a crystal exhibits an extremely wide variation of the reactance with frequency between f_P and f_S . A crystal oscillator circuit is very stable with frequency. This high rate of change of impedance with frequency stabilizes the oscillator, because any significant change in oscillator frequency will cause a large phase shift in the feedback loop keeping the oscillator on frequency.

Manufacturers specify crystal for either series or parallel resonant operation. The frequency for the parallel mode is calibrated with a specified shunt capacitance called a “load capacitance.” The most common value is 30 to 32 pF. If the load capacitance is placed in series with the crystal, the equivalent circuit will be series resonance at the specified parallel-resonant frequency. Frequencies up to 20 MHz use parallel resonant crystal operating in the fundamental mode, while above 20 MHz to about 60 MHz, a series resonant crystal specified and calibrated for operation in the overtone mode is used.

Application Examples

Two types of crystal oscillator circuits are used in the applications circuits: 1) fundamental mode common emitter Colpitts (Figures 1, 17a, 17b, and 21), and 2) third overtone impedance inversion Colpitts (also Figures 1 and 21).

The fundamental mode common emitter Colpitts uses a parallel resonant crystal calibrated with a 32 pF load capacitance. The capacitance values are chosen to provide excellent frequency stability and output power of > 500 mVp-p at Pin 9. In Figures 1 and 21, the fundamental mode reference oscillator is fixed tuned relying on the repeatability of the crystal and passive network to maintain the frequency, while in the circuit shown in Figure 17, the oscillator frequency can be adjusted with the variable inductor for the precise operating frequency.

The third overtone impedance inversion Colpitts uses a series resonance crystal with a 25 ppm tolerance. In the application examples (Figures 1 and 21), the reference oscillator operates with the third overtone crystal at 40.0000 MHz. Thus, the MC13175 is operated at 320 MHz ($f_0/8 = \text{crystal}$; $320/8 = 40.0000$ MHz). The resistor across the crystal ensures that the crystal will operate in the series resonant mode. A tuneable inductor is used to adjust the oscillation frequency; it forms a parallel resonant circuit with the series and parallel combination of the external capacitors forming the divider and feedback network and the base-emitter capacitance of the device. If the crystal is shorted, the reference oscillator should free-run at the frequency dictated by the parallel resonant LC network.

The reference oscillator can be operated as high as 60 MHz with a third overtone crystal. Therefore, it is possible to use the MC13175 up to at least 480 MHz and the MC13176 up to 950 MHz (based on the maximum capability of the divider network).

Enable (Pin 11)

The enabling resistor at Pin 11 is calculated by:

$$R_{\text{Reg. enable}} = V_{\text{CC}} - 1.0 \text{ Vdc} / I_{\text{reg. enable}}$$

From Figure 4, $I_{\text{reg. enable}}$ is chosen to be 75 μA . So, for a $V_{\text{CC}} = 3.0 \text{ Vdc}$ $R_{\text{Reg. enable}} = 26.6 \text{ k}\Omega$, a standard value 27 k Ω resistor is adequate.

Layout Considerations

Supply (Pin 12): In the PCB layout, the V_{CC} trace must be kept as wide as possible to minimize inductive reactance along the trace; it is best that V_{CC} (RF ground) completely fills around the surface mounted components and interconnect traces on the circuit side of the board. This technique is demonstrated in the evaluation PC board.

Battery/Selection/Lithium Types

The device may be operated from a 3.0 V lithium battery. Selection of a suitable battery is important. Because one of the major problems for long life battery powered equipment is oxidation of the battery terminals, a battery mounted in a clip-in socket is not advised. The battery leads or contact post should be isolated from the air to eliminate oxide build-up. The battery should have PC board mounting tabs which can be soldered to the PCB. Consideration should be given for the peak current capability of the battery. Lithium batteries have current handling capabilities based on the composition of the lithium compound, construction and the battery size. A 1300 mA/hr rating can be achieved in the cylindrical cell battery. The Rayovac CR2/3A lithium-manganese dioxide battery is a crimp sealed, spiral wound 3.0 Vdc, 1300 mA/hr cylindrical cell with PC board mounting tabs. It is an excellent choice based on capacity and size (1.358" long by 0.665" in diameter).

Differential Output (Pins 13, 14)

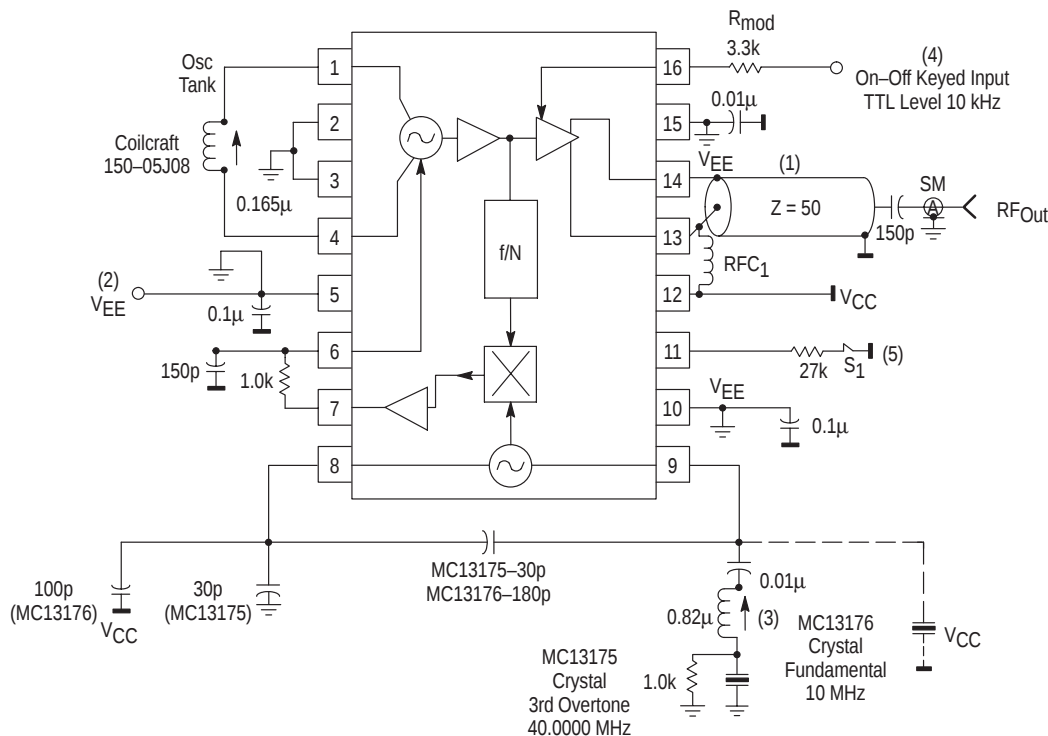
The availability of micro-coaxial cable and small baluns in surface mount and radial-leaded components allows for simple interface to the output ports. A loop antenna may be directly connected with bias via RFC or 50 Ω resistors. Antenna configuration will vary depending on the space available and the frequency of operation.

AM Modulation (Pin 16)

Amplitude Shift Key: The MC13175 and MC13176 are designed to accommodate Amplitude Shift Keying (ASK). ASK modulation is a form of digital modulation corresponding to AM. The amplitude of the carrier is switched between two or more values in response to the PCM code. For the binary case, the usual choice is On-Off Keying (often abbreviated OOK). The resultant amplitude modulated waveform consists of RF pulses called marks, representing binary 1 and spaces representing binary 0.

MC13175 MC13176

Figure 21. ASK 320 MHz Application Circuit



NOTES: 1. 50 Ω coaxial balun, 1/10 wavelength line (1.5") provides the best match to a 50 Ω load.

2. Pins 5, 10 and 15 are ground and connected to V_{EE} which is the component/DC ground plane side of PCB. These pins must be decoupled to V_{CC} ; decoupling capacitors should be placed as close as possible to the pins.

3. The crystal oscillator circuit may be adjusted for frequency with the variable inductor (MC13175); 1.0 k resistor shunting the crystal prevents it from oscillating in the fundamental mode. Recommended source is Coilcraft “slot seven” 7.0 mm tuneable inductor, part #7M3–821.

4. The On–Off keyed signal turns the output of the transmitter off and on with TTL level pulses through R_{mod} at Pin 16. The “On” power and I_{CC} is set by the resistor which sets $I_{mod} = V_{TTL} - 0.8 / R_{mod}$. (see Figure 23).

5. S1 simulates an enable gate pulse from a microprocessor which will enable the transmitter. (see Figure 4 to determine precise value of the enabling resistor based on the potential of the gate pulse and the desired enable.)

Figure 21 shows a typical application in which the output power has been reduced for linearity and current drain. The current draw on the device is 16 mA I_{CC} (average) and -22.5 dBm (average power output) using a 10 kHz modulating rate for the on-off keying. This equates to 20 mA and -2.3 dBm "On", 13 mA and -41 dBm "Off". In Figure 22a, the device's modulating waveform and encoded carrier

are displayed. The crystal oscillator enable time is needed to set the acquisition timing. It takes typically 4.0 msec to reach full magnitude of the oscillator waveform (see Figure 22b, Oscillator Waveform, at Pin 8). A square waveform of 3.0 V peak with a period that is greater than the oscillator enable time is applied to the Enable (Pin 11).

Figure 22a. ASK Input Waveform and Modulated Carrier

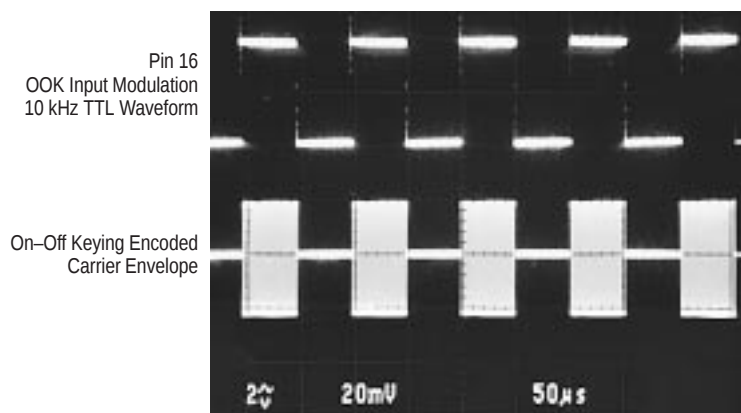
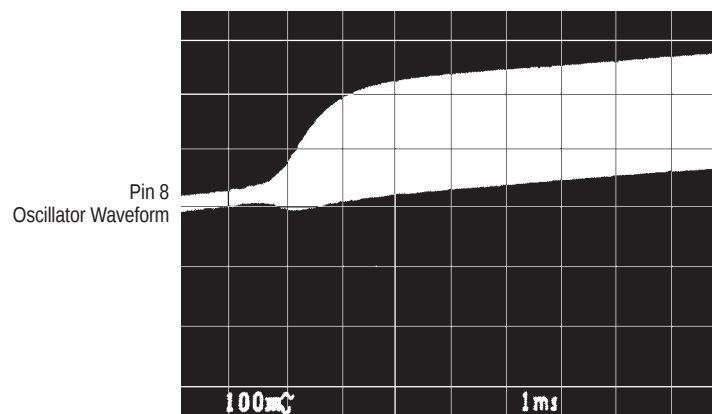
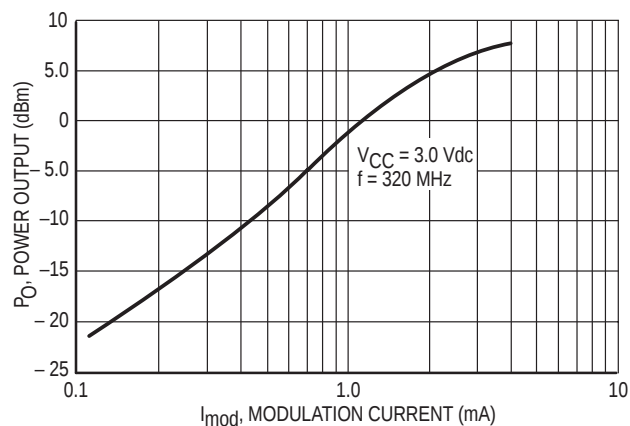
Figure 22b. Oscillator Enable Time, T_{enable} 

Figure 23. Power Output versus Modulation Current



Analog AM

In analog AM applications, the output amplifier's linearity must be carefully considered. Figure 23 is a plot of Power Output versus Modulation Current at 320 MHz, 3.0 Vdc. In order to achieve a linear encoding of the modulating sinusoidal waveform on the carrier, the modulating signal must amplitude modulate the carrier in the linear portion of its power output response. When using a sinewave modulating signal, the signal rides on a positive DC offset called V_{mod} which sets a static (modulation off) modulation current, I_{mod} . I_{mod} controls the power output of the IC. As the modulating signal moves around this static bias point the modulating current varies causing power output to vary or to be AM modulated. When the IC is operated at modulation current levels greater than 2.0 mA_{dc} the differential output stage starts to saturate.

In the design example, shown in Figure 24, the operating point is selected as a tradeoff between average power output and quality of the AM.

For $V_{CC} = 3.0\text{ Vdc}$; $I_{CC} = 18.5\text{ mA}$ and $I_{mod} = 0.5\text{ mA}$ and a static DC offset of 1.04 Vdc , the circuit shown in Figure 24 completes the design. Figures 25a, 25b and 25c show the results of -6.9 dBm output power and 100% modulation by the 10 kHz and 1.0 MHz modulating sinewave signals. The amplitude of the input signals is approximately 800 mVp-p .

Where $R_{mod} = (V_{CC} - 1.04\text{ Vdc})/0.5\text{ mA} = 3.92\text{ k}$, use a standard value resistor of 3.9 k .

Figure 24. Analog AM Transmitter

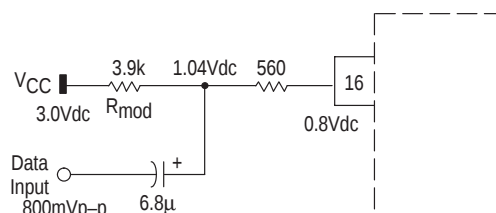


Figure 25a. Power Output of Unmodulated Carrier



Figure 25b. Input Signal and AM Modulated Carrier for $f_{mod} = 10\text{ kHz}$

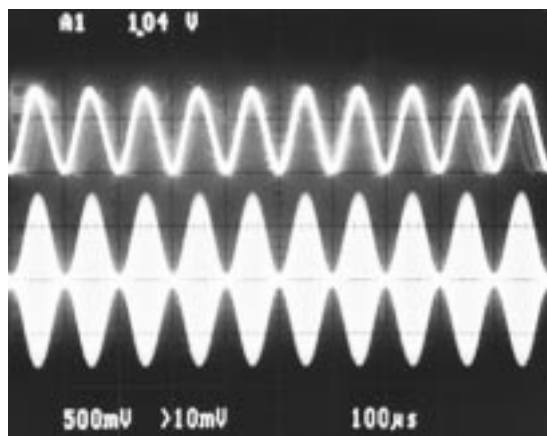
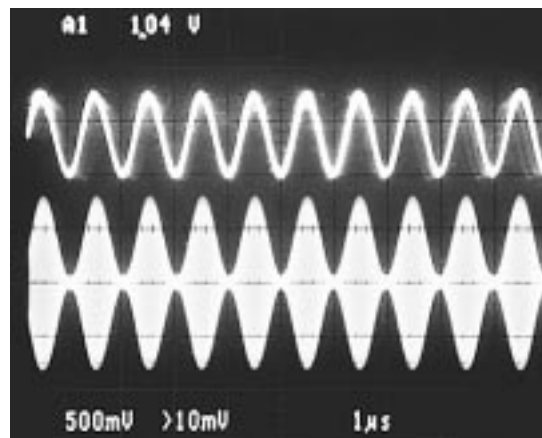


Figure 25c. Input Signal and AM Modulated Carrier for $f_{mod} = 1.0\text{ MHz}$



MC13175 MC13176

Figure 26. Circuit Side View of MC1317XD

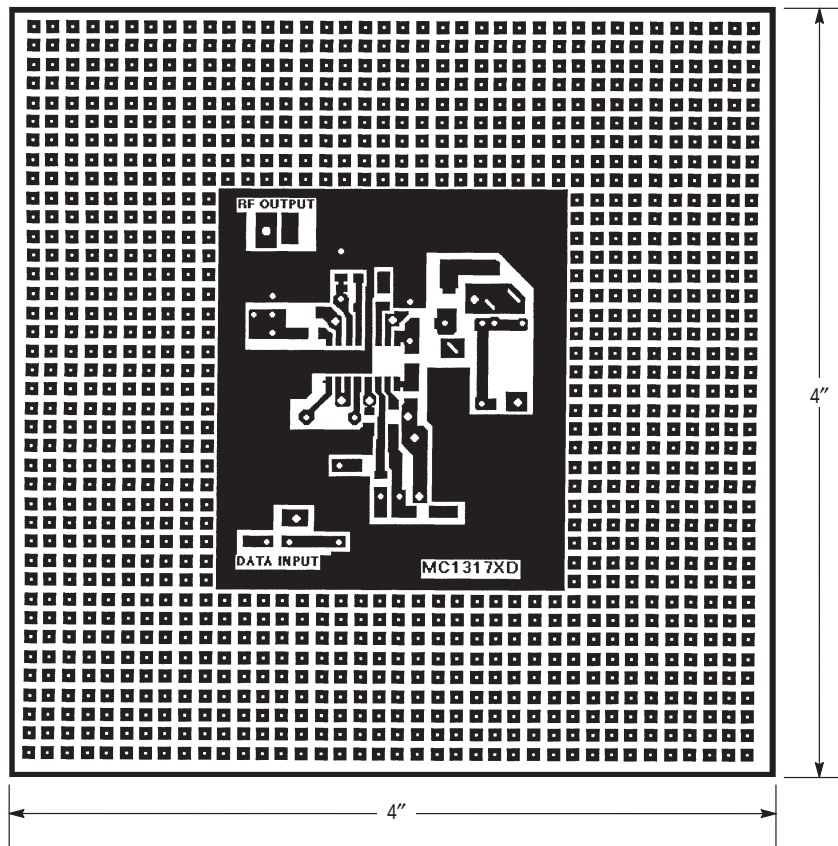
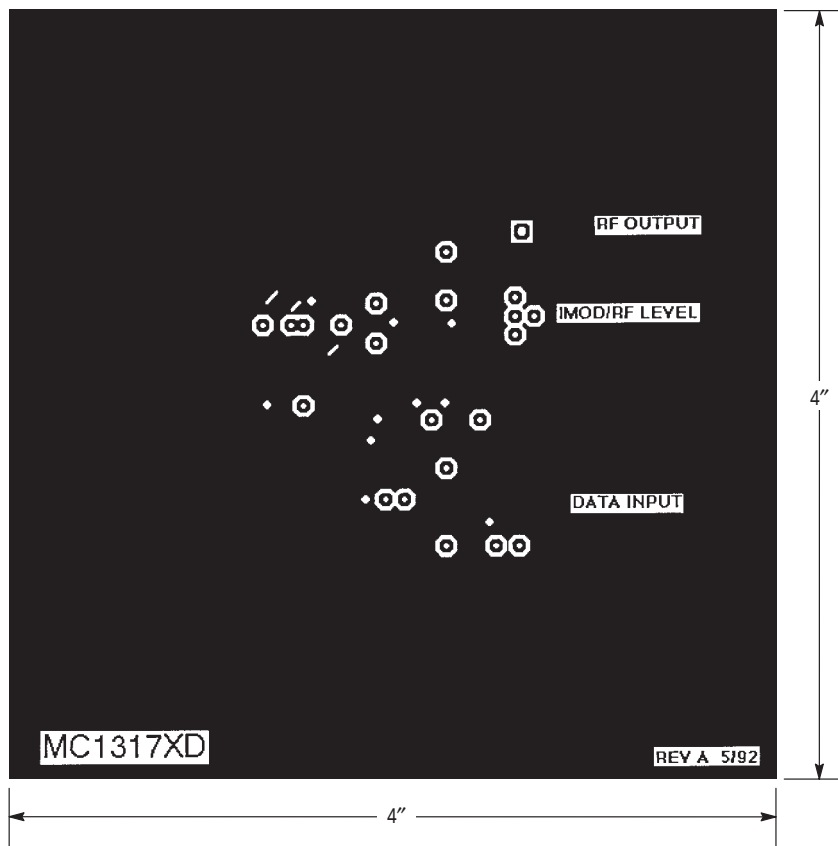


Figure 27. Ground Side View



MC13175 MC13176

Figure 28. Surface Mounted Components Placement
(on Circuit Side)

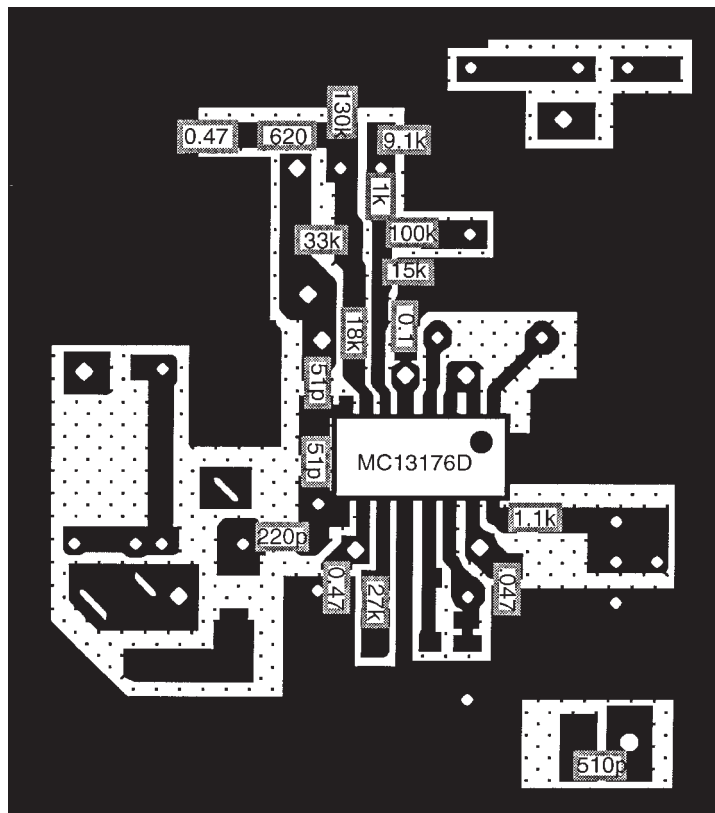
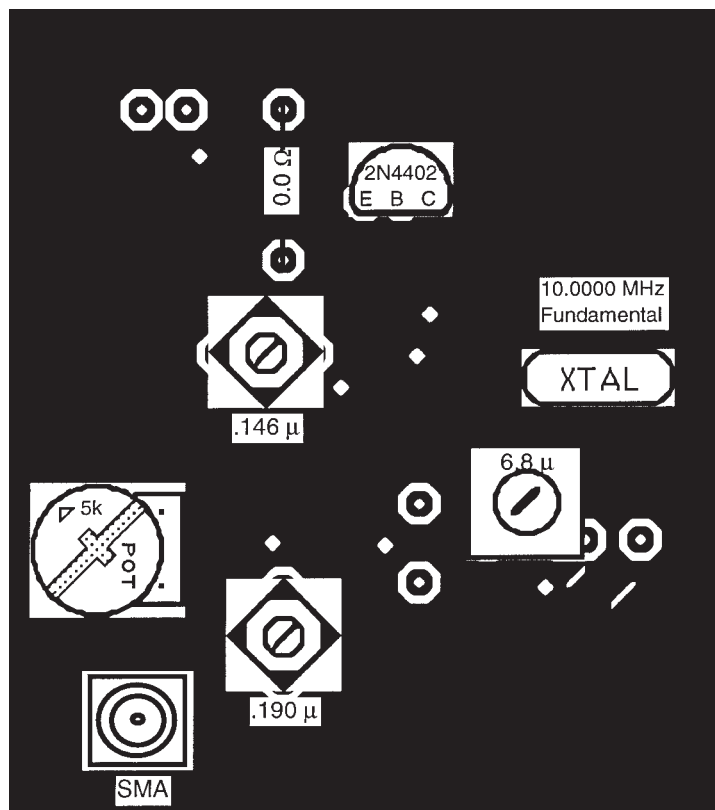


Figure 29. Radial Leaded Components Placement
(on Ground Side)

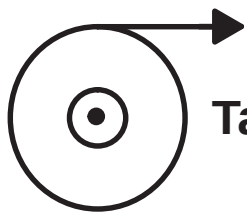


Tape and Reel Options

In Brief . . .

Motorola offers the convenience of Tape and Reel packaging for our growing family of standard integrated circuit products. Reels are available to support the requirements of both first and second generation pick-and-place equipment. The packaging fully conforms to the latest EIA-481A specification. The antistatic embossed tape provides a secure cavity, sealed with a peel-back cover tape.

	Page
Tape and Reel Configurations	12-2
Tape and Reel Information Table	12-4
Analog MPQ Table	12-5

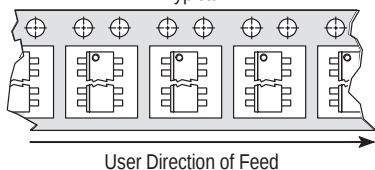


Tape and Reel Configurations

Mechanical Polarization

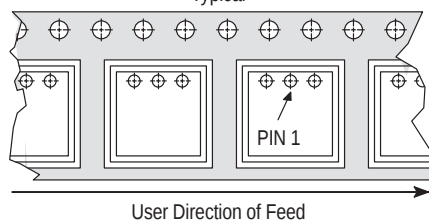
SOIC and Micro-8 DEVICES

Typical



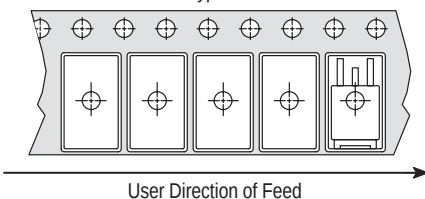
PLCC DEVICES

Typical



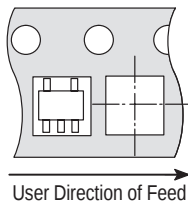
DPAK and D²PAK DEVICES

Typical



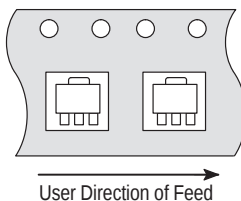
SOT-23 (5 Pin) DEVICES

Typical



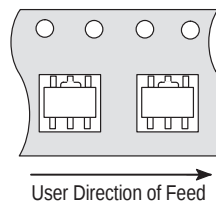
SOT-89 (3 Pin) DEVICES

Typical



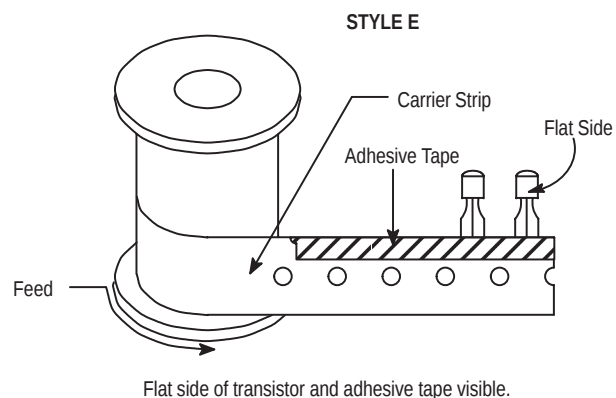
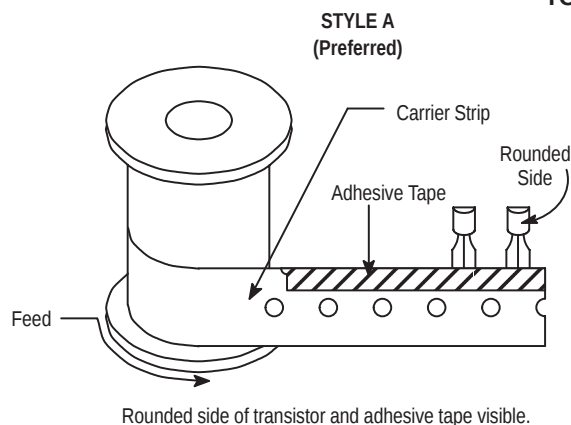
SOT-89 (5 Pin) DEVICES

Typical

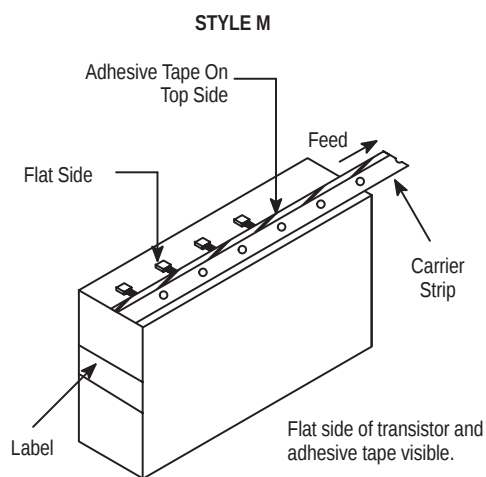
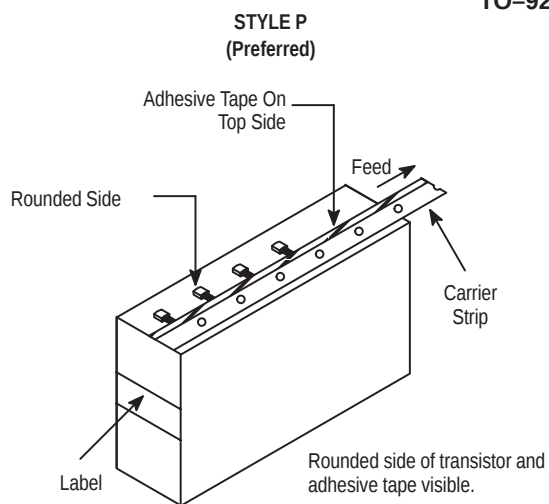


Tape and Reel Configurations (continued)

TO-92 Reel Styles



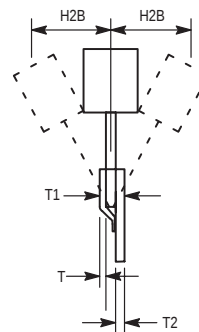
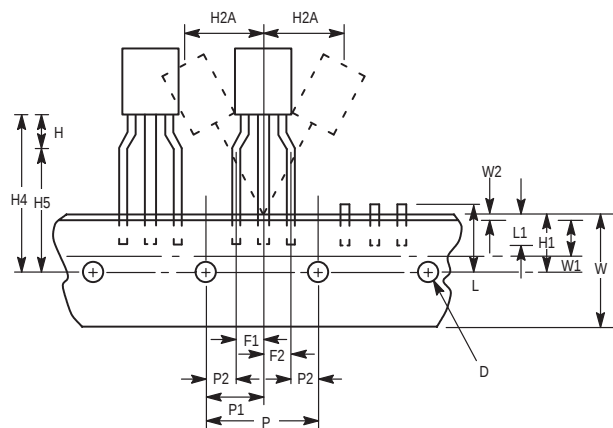
TO-92 Ammo Pack Styles



Style P ammo pack is equivalent to Styles A and B of reel pack dependent on feed orientation from box.

Style M ammo pack is equivalent to Style E of reel pack dependent on feed orientation from box.

TO-92 EIA Radial Tape in Fan Fold Box or On Reel



Tape and Reel Information Table

Package	Tape Width (mm)	Devices ⁽¹⁾ per Reel	Reel Size (inch)	Device Suffix
SO-8, SOP-8	12	2,500	13	R2
SO-14	16	2,500	13	R2
SO-16	16	2,500	13	R2
SO-16L, SO-8+8L WIDE	16	1,000	13	R2
SO-20L WIDE	24	1,000	13	R2
SO-24L WIDE	24	1,000	13	R2
SO-28L WIDE	24	1,000	13	R2
SO-28L WIDE	32	1,000	13	R3
Micro-8	12	2,500	13	R2
PLCC-20	16	1,000	13	R2
PLCC-28	24	500	13	R2
PLCC-44	32	500	13	R2
PLCC-52	32	500	13	R2
PLCC-68	44	250	13	R2
PLCC-84	44	250	13	R2
TO-226AA (TO-92) ⁽²⁾	18	2,000	13	RA, RE, RP, or RM (Ammo Pack) only
DPAK	16	2,500	13	RK
D ² PAK	24	800	13	R4
SOT-23 (5 Pin)	8	3,000	7	TR
SOT-89 (3/5 Pin)	12	1,000	7	T1

⁽¹⁾ Minimum order quantity is 1 reel. Distributors/OEM customers may break lots or reels at their option, however broken reels may not be returned.

⁽²⁾ Integrated circuits in TO-226AA packages are available in Styles A and E only, with optional "Ammo Pack" (Suffix RP or RM). The RA and RP configurations are preferred. For ordering information please contact your local Motorola Semiconductor Sales Office.

Analog MPQ Table

Tape/Reel and Ammo Pack

Package Type	Package Code	MPQ
PLCC		
Case 775	0802	1000/reel
Case 776	0804	500/reel
Case 777	0801	500/reel
SOIC		
Case 751	0095	2500/reel
Case 751A	0096	2500/reel
Case 751B	0097	2500/reel
Case 751G	2003	1000/reel
Case 751D	2005	1000/reel
Case 751E	2008	1000/reel
Case 751F	2009	1000/reel
Micro-8		
Case 846A	—	2500/reel
TO-92		
Case 29	0031	2000/reel
Case 29	0031	2000/Ammo Pack
DPAK		
Case 369A	—	2500/reel
D²PAK		
Case 936	—	800/reel
SOT-23 (5 Pin)		
Case 1212	—	3000/reel
SOT-89 (3 Pin)		
Case 1213	—	1000/reel
SOT-89 (5 Pin)		
Case 1214	—	1000/reel

Packaging Information

In Brief . . .

The packaging availability for each device type is indicated on the individual data sheets and the Selector Guide. All of the outline dimensions for the packages are given in this section.

The maximum power consumption an integrated circuit can tolerate at a given operating ambient temperature can be found from the equation:

$$P_{D(TA)} = \frac{T_{J(max)} - T_A}{R_{\theta JA(Typ)}}$$

where:

$P_{D(TA)}$ = Power Dissipation allowable at a given operating ambient temperature. This must be greater than the sum of the products of the supply voltages and supply currents at the worst case operating condition.

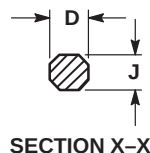
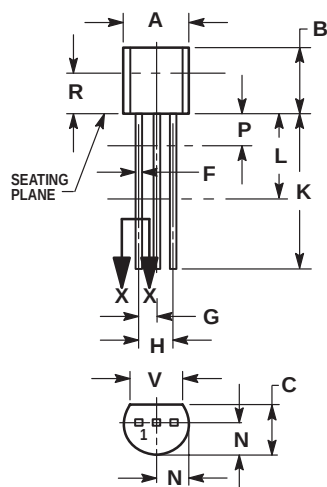
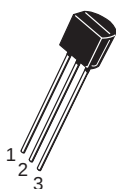
$T_{J(max)}$ = Maximum operating Junction Temperature as listed in the Maximum Ratings Section. See individual data sheets for $T_{J(max)}$ information.

T_A = Maximum desired operating Ambient Temperature

$R_{\theta JA(Typ)}$ = Typical Thermal Resistance Junction-to-Ambient

Case Outline Dimensions

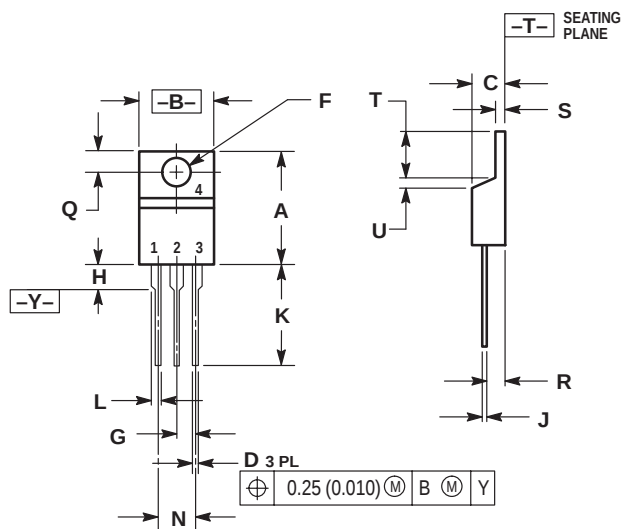
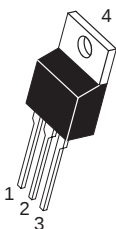
LP, P, Z SUFFIX
CASE 29-04
 Plastic Package
 (TO-226AA/TO-92)
 ISSUE AD



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
 4. DIMENSION F APPLIES BETWEEN P AND L. DIMENSION D AND J APPLY BETWEEN L AND K MINIMUM. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.022	0.41	0.55
F	0.016	0.019	0.41	0.48
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	—	12.70	—
L	0.250	—	6.35	—
N	0.080	0.105	2.04	2.66
P	—	0.100	—	2.54
R	0.115	—	2.93	—
V	0.135	—	3.43	—

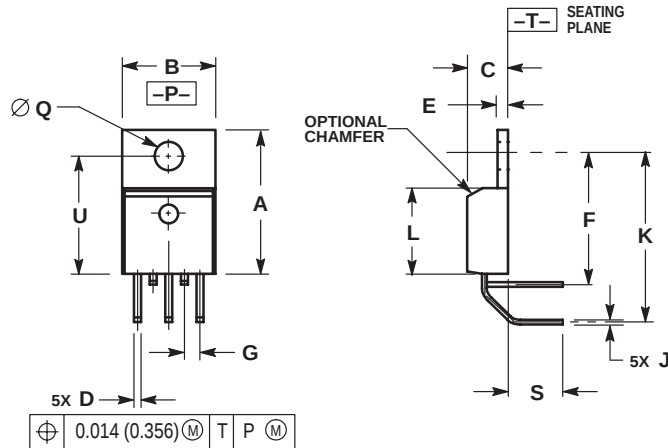
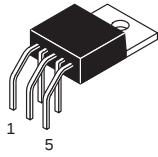
KC, T SUFFIX
CASE 221A-06
 Plastic Package
 ISSUE Y



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.560	0.625	14.23	15.87
B	0.380	0.420	9.66	10.66
C	0.140	0.190	3.56	4.82
D	0.020	0.045	0.51	1.14
E	0.139	0.155	3.53	3.93
G	0.100 BSC	—	2.54 BSC	—
H	—	0.280	—	7.11
J	0.012	0.045	0.31	1.14
K	0.500	0.580	12.70	14.73
L	0.045	0.070	1.15	1.77
N	0.200 BSC	—	5.08 BSC	—
Q	0.100	0.135	2.54	3.42
R	0.080	0.115	2.04	2.92
S	0.020	0.055	0.51	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27

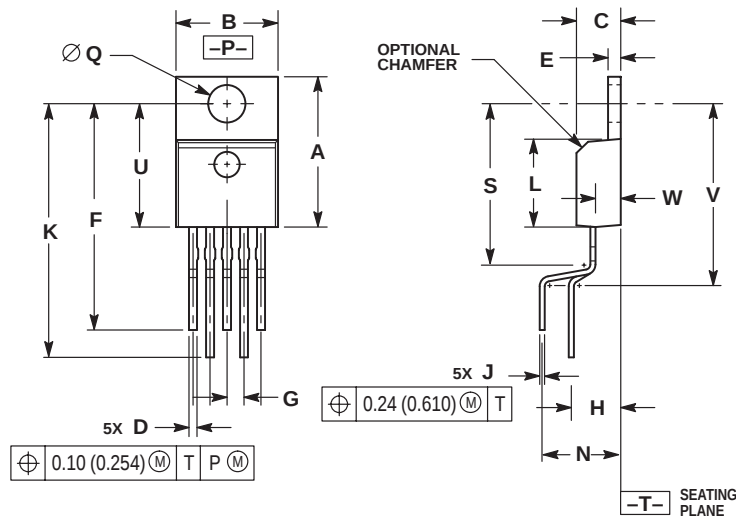
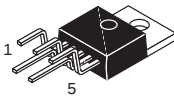
TH SUFFIX
CASE 314A-03
 Plastic Package
 ISSUE D



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 0.043 (1.092) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.572	0.613	14.529	15.570
B	0.390	0.415	9.906	10.541
C	0.170	0.180	4.318	4.572
D	0.025	0.038	0.635	0.965
E	0.048	0.055	1.219	1.397
F	0.570	0.585	14.478	14.859
G	0.067 BSC		1.702 BSC	
J	0.015	0.025	0.381	0.635
K	0.730	0.745	18.542	18.923
L	0.320	0.365	8.128	9.271
Q	0.140	0.153	3.556	3.886
S	0.210	0.260	5.334	6.604
U	0.468	0.505	11.888	12.827

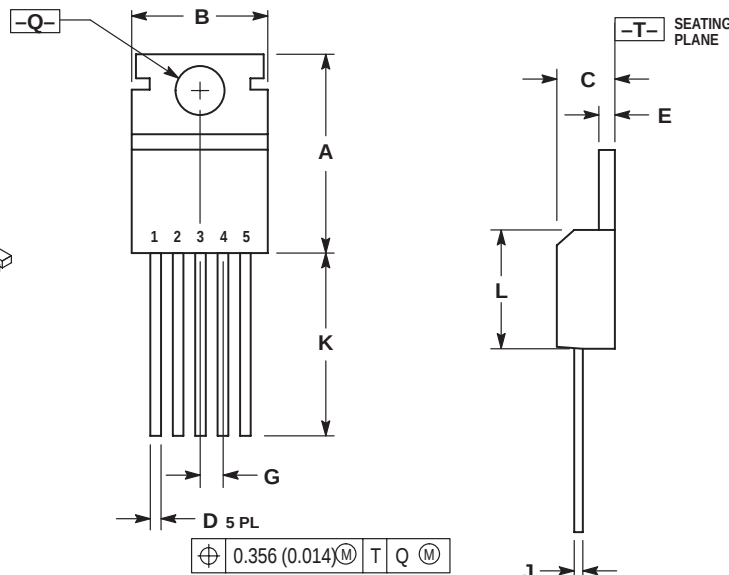
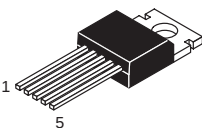
T, TV SUFFIX
CASE 314B-05
 Plastic Package
 ISSUE J



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 0.043 (1.092) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.572	0.613	14.529	15.570
B	0.390	0.415	9.906	10.541
C	0.170	0.180	4.318	4.572
D	0.025	0.038	0.635	0.965
E	0.048	0.055	1.219	1.397
F	0.850	0.935	21.590	23.749
G	0.067 BSC		1.702 BSC	
H	0.166 BSC		4.216 BSC	
J	0.015	0.025	0.381	0.635
K	0.900	1.100	22.860	27.940
L	0.320	0.365	8.128	9.271
N	0.320 BSC		8.128 BSC	
Q	0.140	0.153	3.556	3.886
S	—	0.620	—	15.748
U	0.468	0.505	11.888	12.827
V	—	0.735	—	18.669
W	0.090	0.110	2.286	2.794

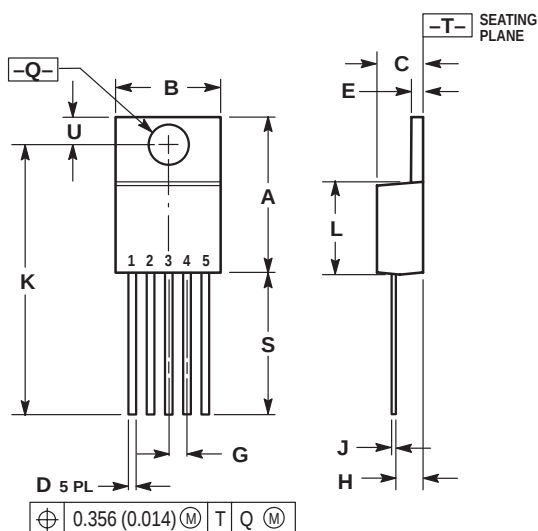
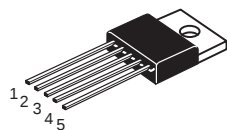
T SUFFIX
CASE 314C-01
 Plastic Package
 ISSUE A



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 10.92 (0.043) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.610	0.625	15.59	15.88
B	0.380	0.420	9.65	10.67
C	0.160	0.190	4.06	4.83
D	0.020	0.040	0.51	1.02
E	0.035	0.055	0.89	1.40
G	0.067 BSC		1.702 BSC	
J	0.015	0.025	0.38	0.64
K	0.500	—	12.70	—
L	0.355	0.370	9.02	9.40
Q	0.139	0.147	3.53	3.73

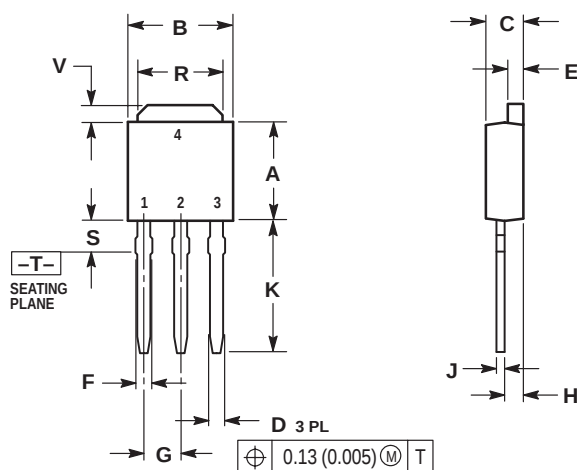
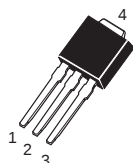
T, T1 SUFFIX
CASE 314D-03
 Plastic Package
 ISSUE D



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 10.92 (0.043) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.572	0.613	14.529	15.570
B	0.390	0.415	9.906	10.541
C	0.170	0.180	4.318	4.572
D	0.025	0.038	0.635	0.965
E	0.048	0.055	1.219	1.397
G	0.067 BSC		1.702 BSC	
H	0.087	0.112	2.210	2.845
J	0.015	0.025	0.381	0.635
K	1.020	1.065	25.908	27.051
L	0.320	0.365	8.128	9.271
Q	0.140	0.153	3.556	3.886
U	0.105	0.117	2.667	2.972
S	0.543	0.582	13.792	14.783

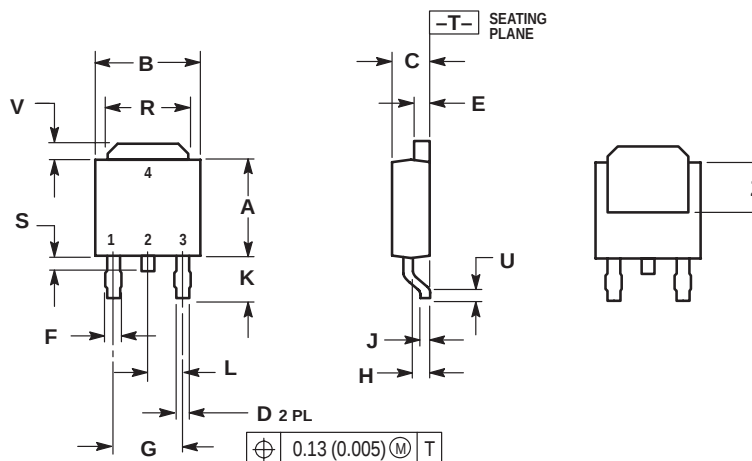
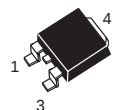
DT-1 SUFFIX
CASE 369-07
 Plastic Package (DPAK)
 ISSUE K



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.250	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.033	0.040	0.84	1.01
F	0.037	0.047	0.94	1.19
G	0.090 BSC		2.29 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.350	0.380	8.89	9.65
R	0.175	0.215	4.45	5.46
S	0.050	0.090	1.27	2.28
V	0.030	0.050	0.77	1.27

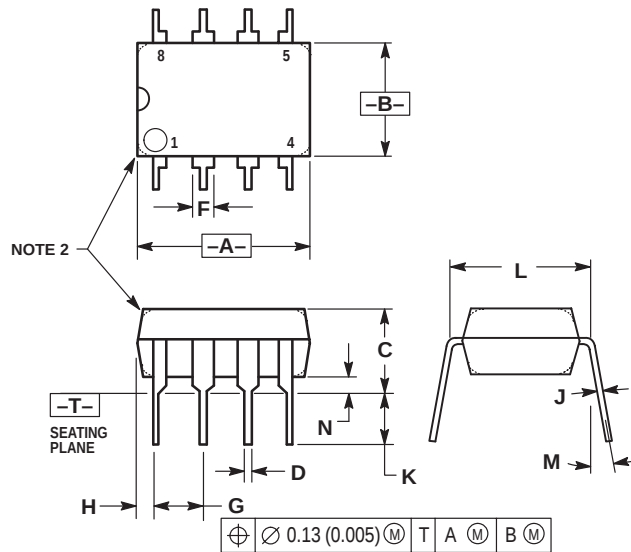
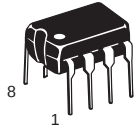
DT SUFFIX
CASE 369A-13
 Plastic Package (DPAK)
 ISSUE Y



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.250	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.033	0.040	0.84	1.01
F	0.037	0.047	0.94	1.19
G	0.180 BSC		4.58 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.102	0.114	2.60	2.89
L	0.090 BSC		2.29 BSC	
R	0.175	0.215	4.45	5.46
S	0.020	0.050	0.51	1.27
U	0.020	—	0.51	—
V	0.030	0.050	0.77	1.27
Z	0.138	—	3.51	—

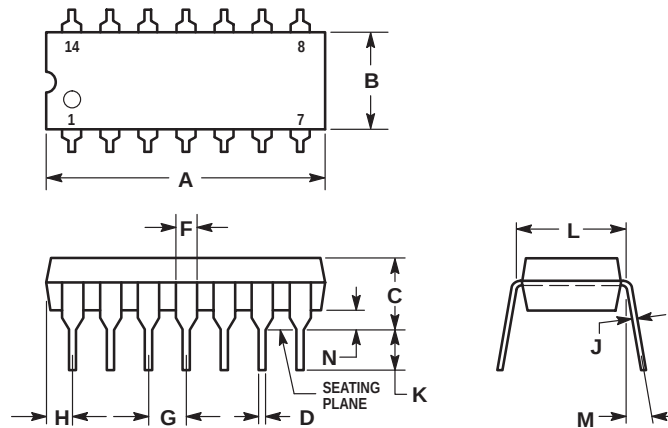
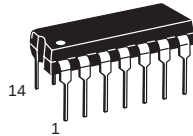
DP1, N, P, P1 SUFFIX
CASE 626-05
 Plastic Package
 ISSUE K



- NOTES:
1. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 2. PACKAGE CONTOUR OPTIONAL (ROUND OR SQUARE CORNERS).
 3. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.40	10.16	0.370	0.400
B	6.10	6.60	0.240	0.260
C	3.94	4.45	0.155	0.175
D	0.38	0.51	0.015	0.020
F	1.02	1.78	0.040	0.070
G	2.54 BSC		0.100 BSC	
H	0.76	1.27	0.030	0.050
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	—	10°	—	10°
N	0.76	1.01	0.030	0.040

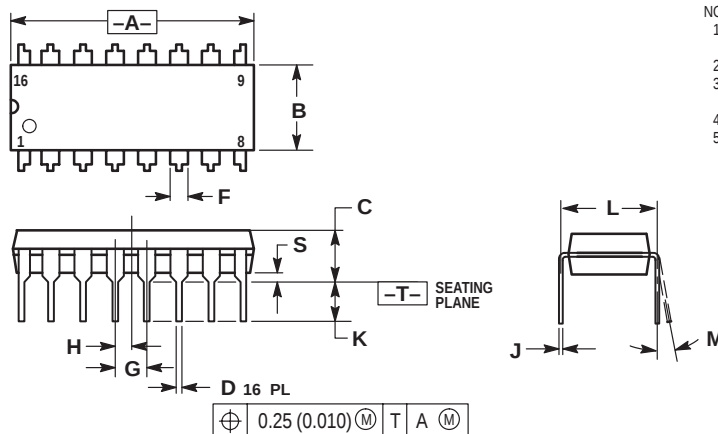
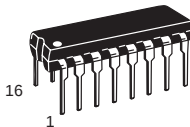
N, P, N-14, P2 SUFFIX
CASE 646-06
 Plastic Package
 ISSUE L



- NOTES:
1. LEADS WITHIN 0.13 (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
 2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 4. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.715	0.770	18.16	19.56
B	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100 BSC		2.54 BSC	
H	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.300 BSC		7.62 BSC	
M	0°	10°	0°	10°
N	0.015	0.039	0.39	1.01

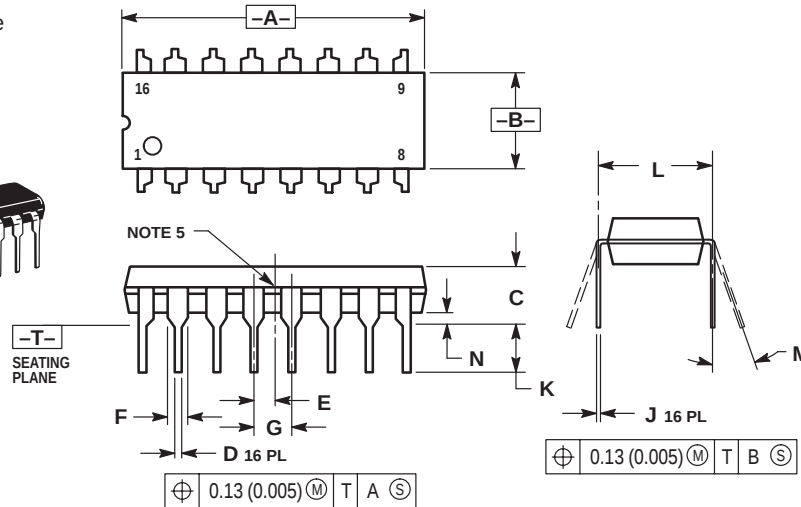
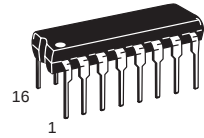
DP2, N, P, PC SUFFIX
CASE 648-08
 Plastic Package
 ISSUE R



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

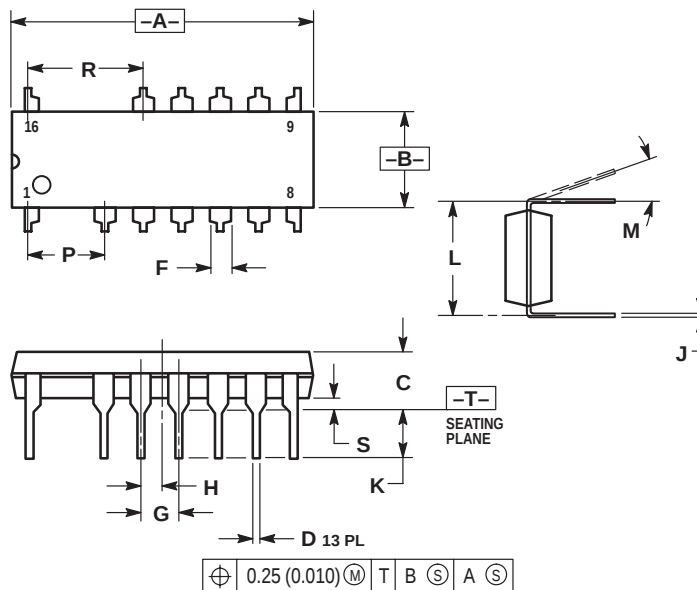
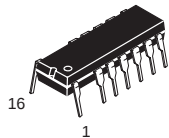
B, P, P2, V SUFFIX
CASE 648C-03
 Plastic Package
 (DIP-16)
 ISSUE C



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. INTERNAL LEAD CONNECTION BETWEEN 4 AND 5, 12 AND 13.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.840	18.80	21.34
B	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
E	0.050 BSC		1.27 BSC	
F	0.040	0.70	1.02	1.78
G	0.100 BSC		2.54 BSC	
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.300 BSC		7.62 BSC	
M	0°	10°	0°	10°
N	0.015	0.040	0.39	1.01

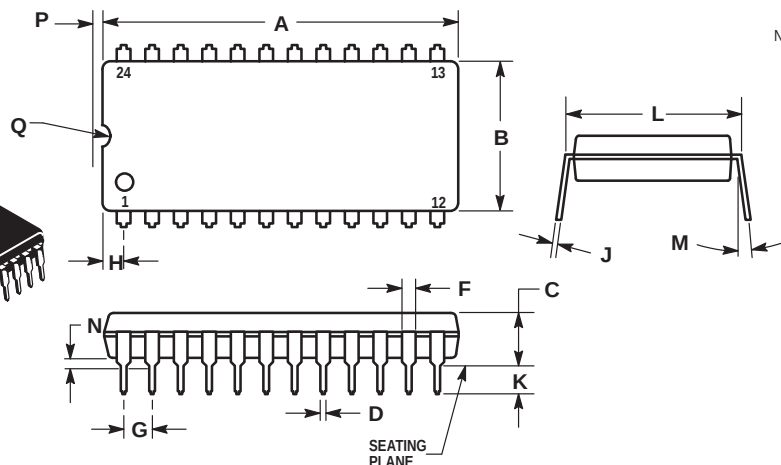
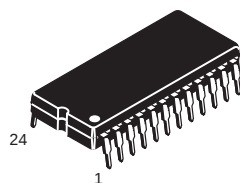
P SUFFIX
CASE 648E-01
 Plastic Package
 (DIP-16)
 ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION A AND B DOES NOT INCLUDE MOLD PROTRUSION.
 5. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.25 (0.010).
 6. ROUNDED CORNER OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.760	18.80	19.30
B	0.245	0.260	6.23	6.60
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.050	0.070	1.27	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.120	0.140	3.05	3.55
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
P	0.200 BSC		5.08 BSC	
R	0.300 BSC		7.62 BSC	
S	0.015	0.035	0.39	0.88

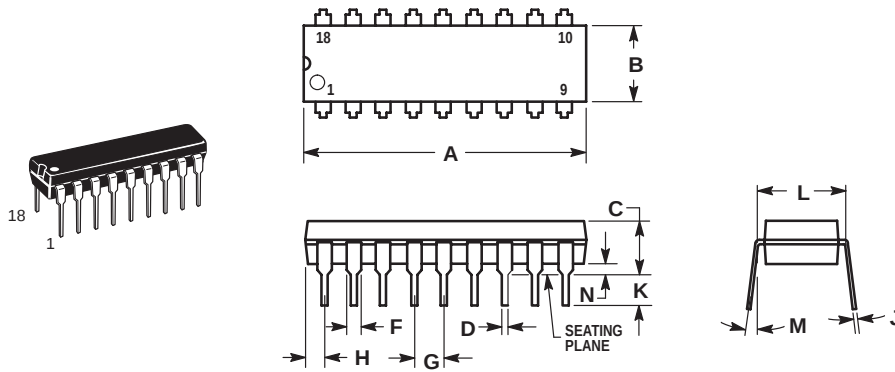
P SUFFIX
CASE 649-03
 Plastic Package
 ISSUE D



- NOTES:
1. LEADS WITHIN 0.13 (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
 2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	31.50	32.13	1.240	1.265
B	13.21	13.72	0.520	0.540
C	4.70	5.21	0.185	0.205
D	0.38	0.51	0.015	0.020
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	1.65	2.16	0.065	0.085
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	14.99	15.49	0.590	0.610
M	—	10°	—	10°
N	0.51	1.02	0.020	0.040
P	0.13	0.38	0.005	0.015
Q	0.51	0.76	0.020	0.030

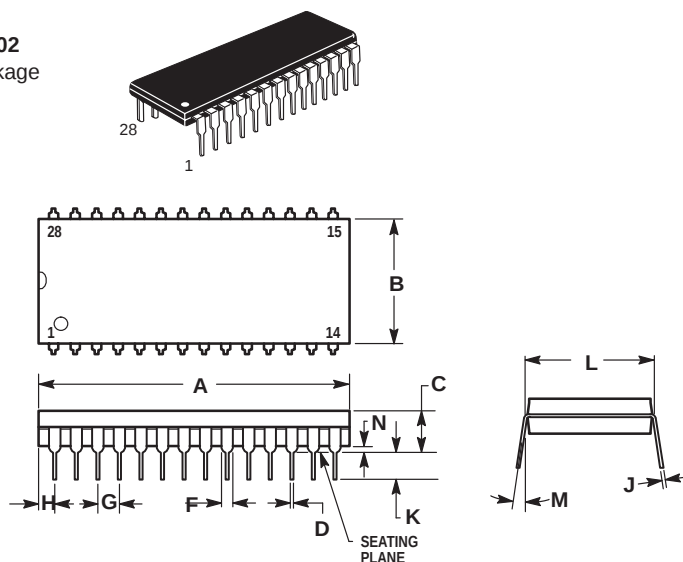
A, B, N, P SUFFIX
CASE 707-02
 Plastic Package
 ISSUE C



- NOTES:
1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25 (0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
 2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	22.22	23.24	0.875	0.915
B	6.10	6.60	0.240	0.260
C	3.56	4.57	0.140	0.180
D	0.36	0.56	0.014	0.022
F	1.27	1.78	0.050	0.070
G	2.54 BSC		0.100 BSC	
H	1.02	1.52	0.040	0.060
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

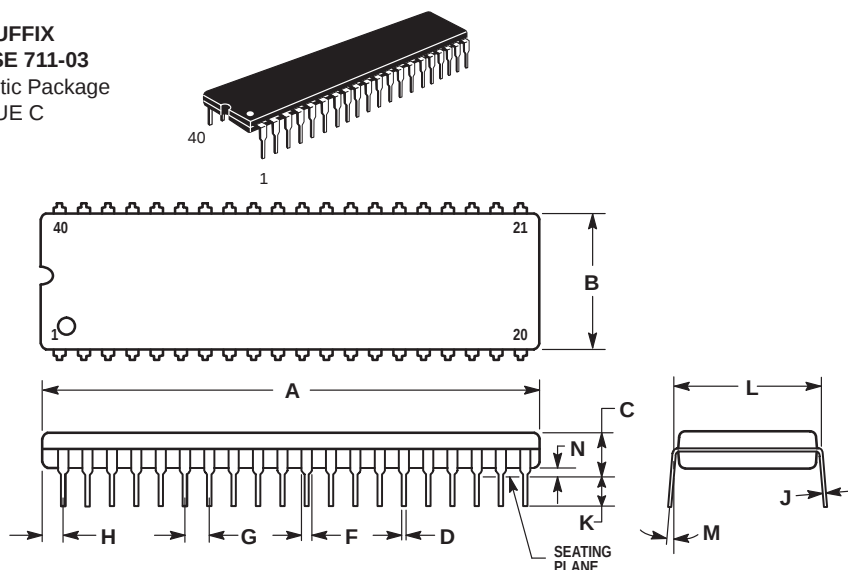
P SUFFIX
CASE 710-02
 Plastic Package
 ISSUE B



- NOTES:
1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25 (0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
 2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	36.45	37.21	1.435	1.465
B	13.72	14.22	0.540	0.560
C	3.94	5.08	0.155	0.200
D	0.36	0.56	0.014	0.022
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	1.65	2.16	0.065	0.085
J	0.20	0.38	0.008	0.015
K	2.92	3.43	0.115	0.135
L	15.24 BSC		0.600 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

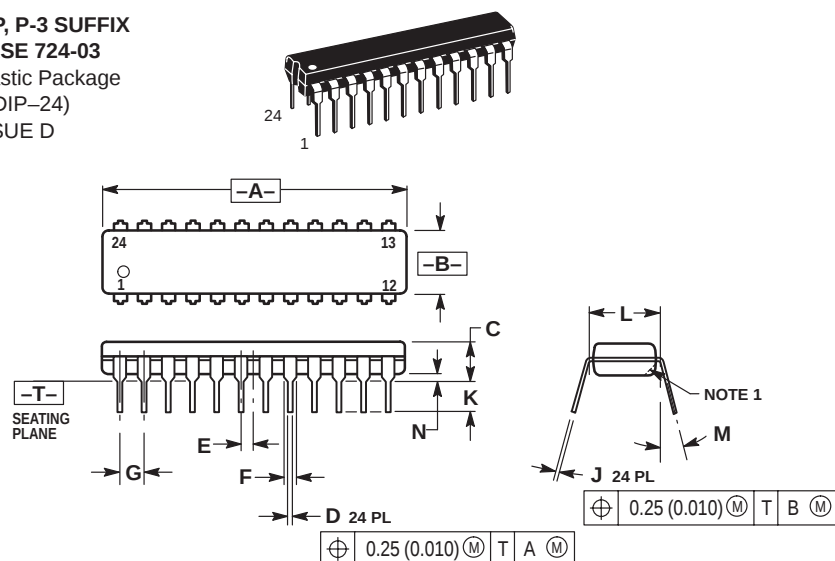
P SUFFIX
CASE 711-03
 Plastic Package
 ISSUE C



- NOTES:
1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25 (0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
 2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	51.69	52.45	2.035	2.065
B	13.72	14.22	0.540	0.560
C	3.94	5.08	0.155	0.200
D	0.36	0.56	0.014	0.022
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	1.65	2.16	0.065	0.085
J	0.20	0.38	0.008	0.015
K	2.92	3.43	0.115	0.135
L	15.24 BSC		0.600 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

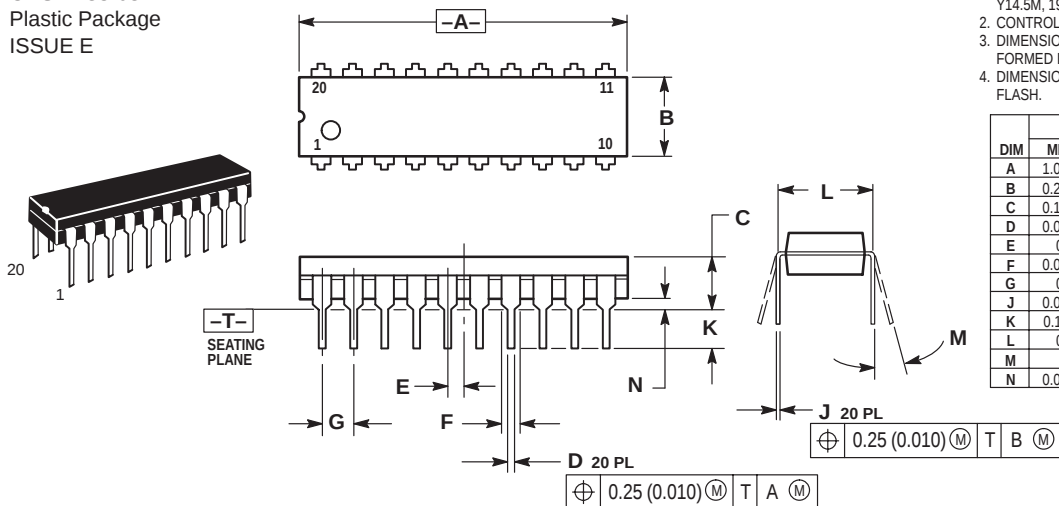
F, P, P-3 SUFFIX
CASE 724-03
 Plastic Package
 (NDIP-24)
 ISSUE D



- NOTES:
1. CHAMFERED CONTOUR OPTIONAL.
 2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 3. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 4. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.230	1.265	31.25	32.13
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.020	0.38	0.51
E	0.050 BSC		1.27 BSC	
F	0.040	0.060	1.02	1.52
G	0.100 BSC		2.54 BSC	
J	0.007	0.012	0.18	0.30
K	0.110	0.140	2.80	3.55
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

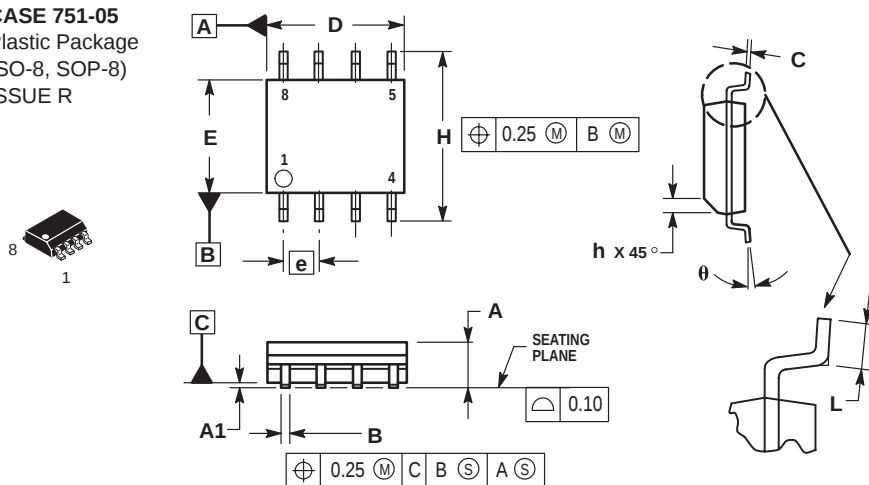
H, P, DP SUFFIX
CASE 738-03
 Plastic Package
 ISSUE E



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.010	1.070	25.66	27.17
B	0.240	0.260	6.10	6.60
C	0.150	0.180	3.81	4.57
D	0.015	0.022	0.39	0.55
E	0.050 BSC		1.27 BSC	
F	0.050	0.070	1.27	1.77
G	0.100 BSC		2.54 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.140	2.80	3.55
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

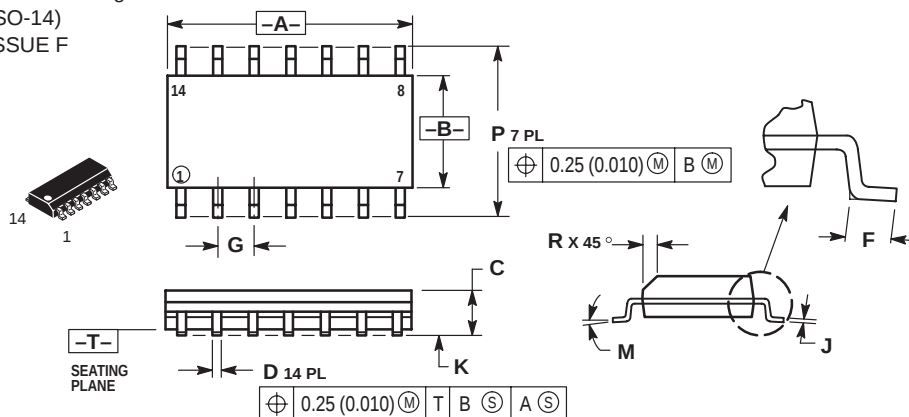
D, D1, D2 SUFFIX
CASE 751-05
 Plastic Package
 (SO-8, SOP-8)
 ISSUE R



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. DIMENSIONS ARE IN MILLIMETERS.
 3. DIMENSION D AND E DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
 5. DIMENSION B DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS	
	MIN	MAX
A	1.35	1.75
A1	0.10	0.25
B	0.35	0.49
C	0.18	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27 BSC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.25
θ	0°	7°

D SUFFIX
CASE 751A-03
 Plastic Package
 (SO-14)
 ISSUE F

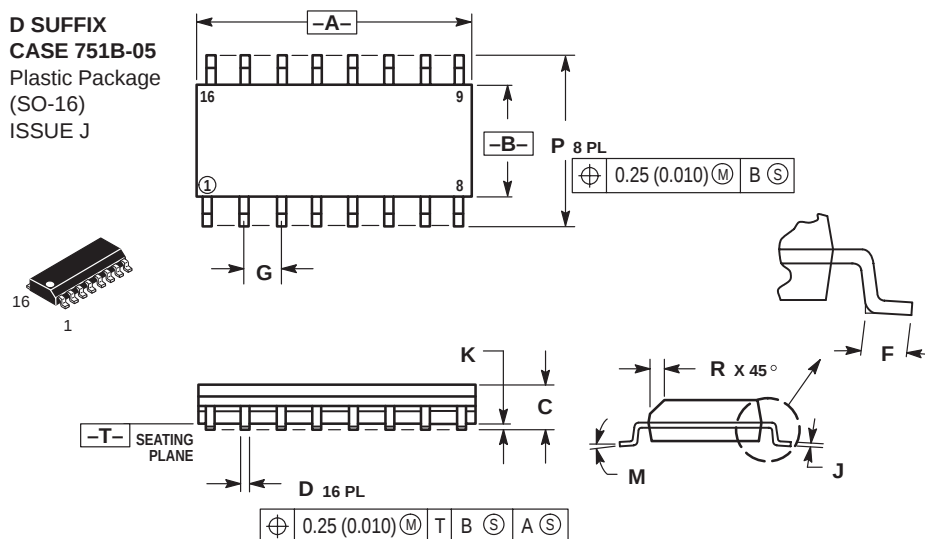


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

D SUFFIX
CASE 751B-05
 Plastic Package
 (SO-16)
 ISSUE J

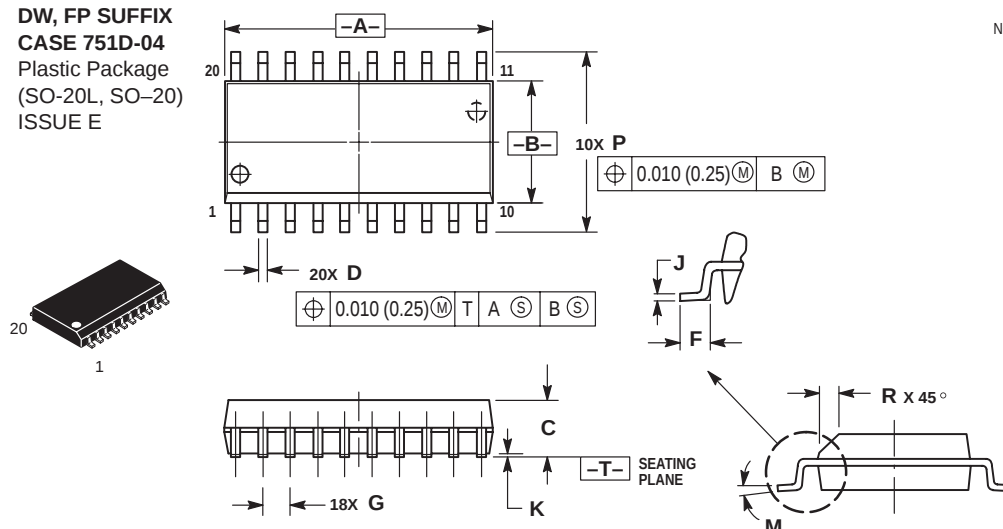


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

DW, FP SUFFIX
CASE 751D-04
 Plastic Package
 (SO-20L, SO-20)
 ISSUE E

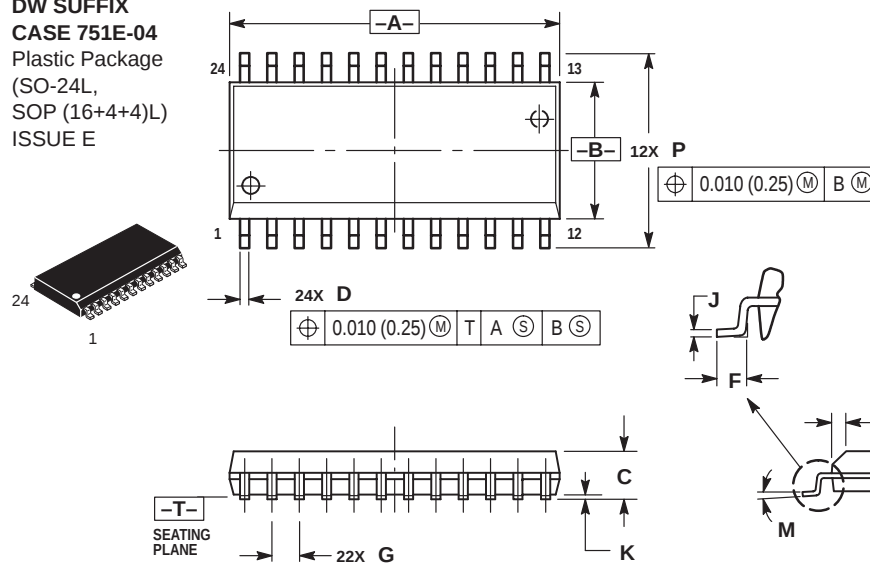


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.150 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	12.65	12.95	0.499	0.510
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27	BSC	0.050	BSC
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

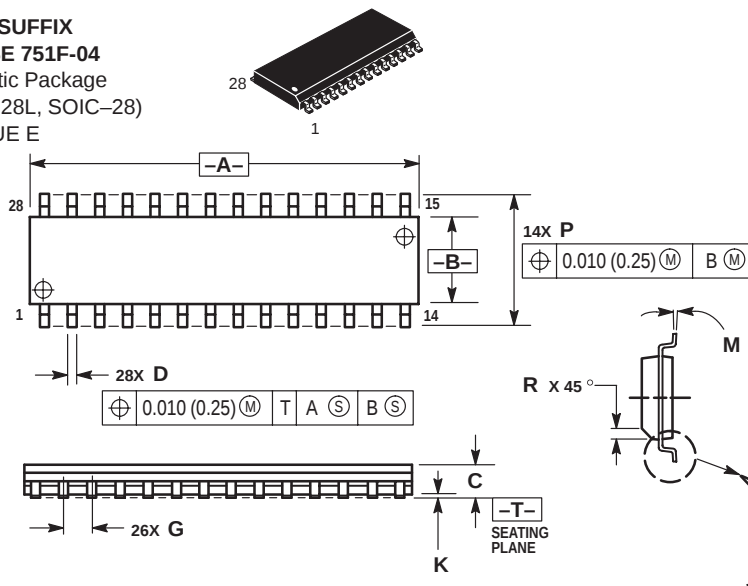
DW SUFFIX
CASE 751E-04
 Plastic Package
 (SO-24L,
 SOP (16+4+4)L)
 ISSUE E



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	15.25	15.54	0.601	0.612
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.41	0.90	0.016	0.035
G	1.27 BSC		0.050 BSC	
J	0.23	0.32	0.009	0.013
K	0.13	0.29	0.005	0.011
M	0°	8°	0°	8°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

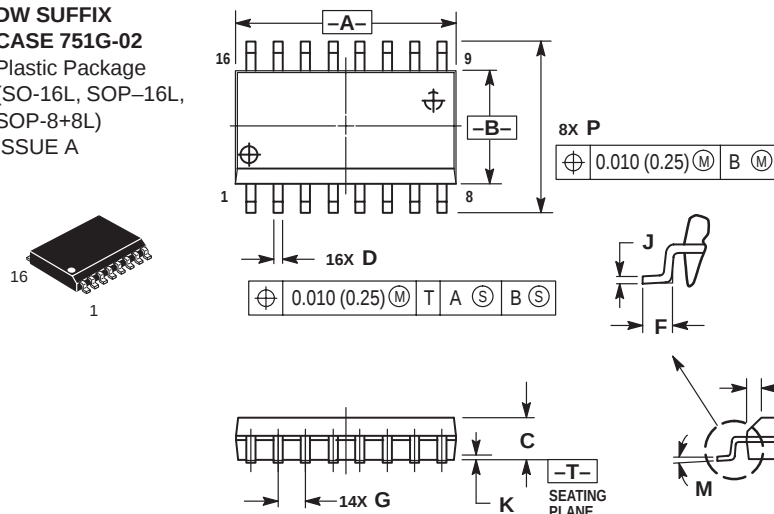
DW SUFFIX
CASE 751F-04
 Plastic Package
 (SO-28L, SOIC-28)
 ISSUE E



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	17.80	18.05	0.701	0.711
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.41	0.90	0.016	0.035
G	1.27 BSC		0.050 BSC	
J	0.23	0.32	0.009	0.013
K	0.13	0.29	0.005	0.011
M	0°	8°	0°	8°
P	10.01	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

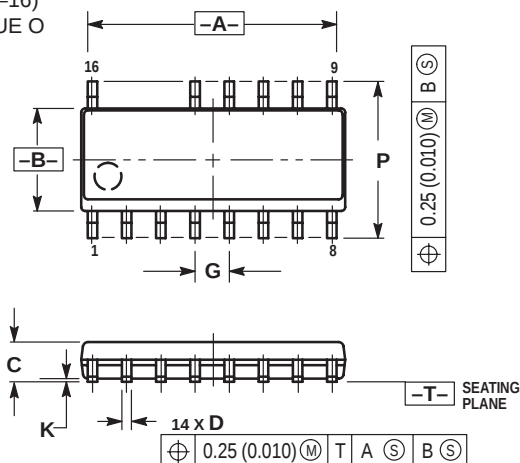
DW SUFFIX
CASE 751G-02
 Plastic Package
 (SO-16L, SOP-16L,
 SOP-8+8L)
 ISSUE A



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.15	10.45	0.400	0.411
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

D SUFFIX
CASE 751K-01
 Plastic Package
 (SO-16)
 ISSUE O

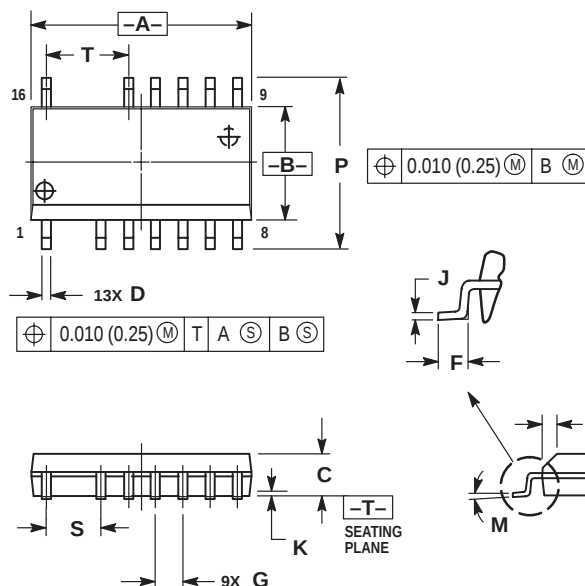
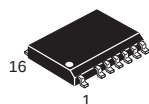


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.368	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

DW SUFFIX
CASE 751N-01
 Plastic Package
 (SOP-16L)
 ISSUE O



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

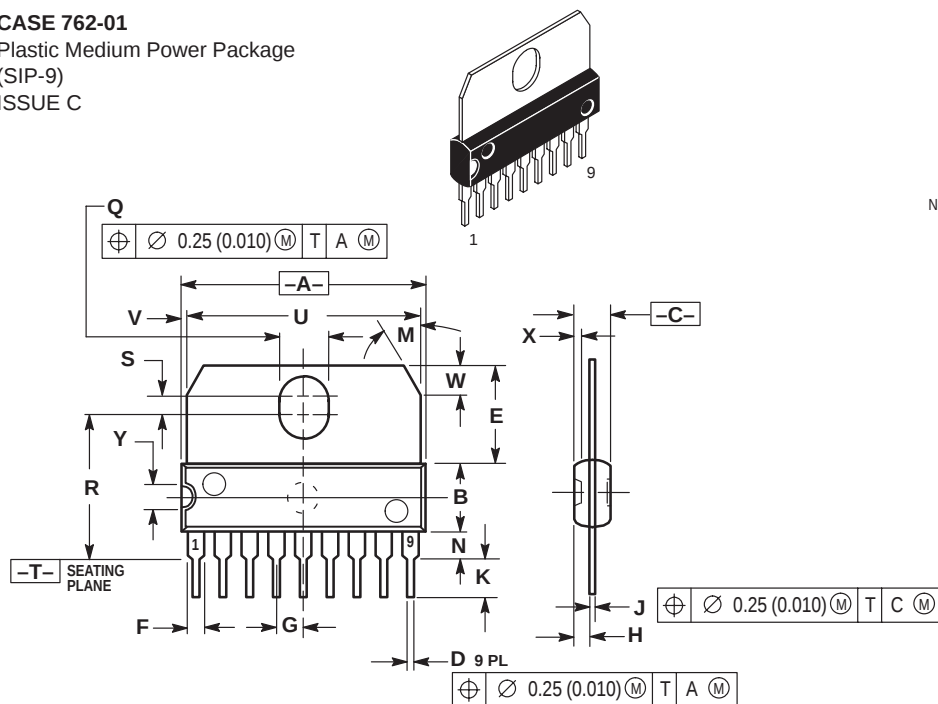
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.15	10.45	0.400	0.411
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029
S	2.54 BSC		0.100 BSC	
T	3.81 BSC		0.150 BSC	

CASE 762-01

Plastic Medium Power Package

(SIP-9)

ISSUE C

**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.

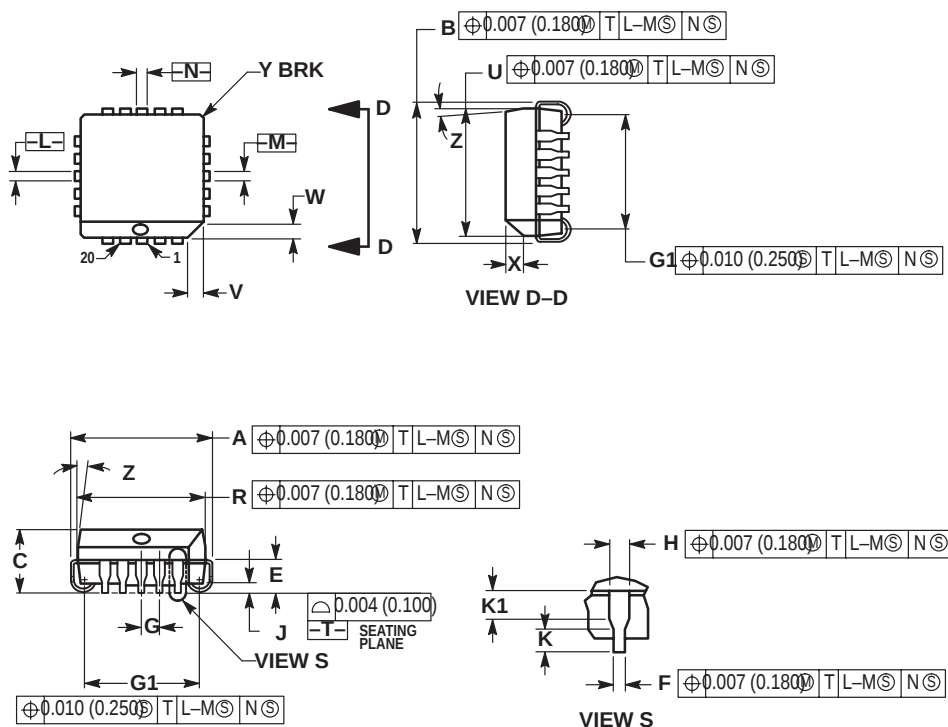
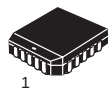
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	22.40	23.00	0.873	0.897
B	6.40	6.60	0.252	0.260
C	3.45	3.65	0.135	0.143
D	0.40	0.55	0.015	0.021
E	9.35	9.60	0.368	0.377
F	1.40	1.60	0.055	0.062
G	2.54 BSC		0.100 BSC	
H	1.51	1.71	0.059	0.067
J	0.360	0.400	0.014	0.015
K	3.95	4.20	0.155	0.165
M	30° BSC		30° BSC	
N	2.50	2.70	0.099	0.106
Q	3.15	3.45	0.124	0.135
R	13.60	13.90	0.535	0.547
S	1.65	1.95	0.064	0.076
U	22.00	22.20	0.866	0.874
V	0.55	0.75	0.021	0.029
W	2.89 BSC		0.113 BSC	
X	0.65	0.75	0.025	0.029
Y	2.70	2.80	0.106	0.110

FN SUFFIX**CASE 775-02**

Plastic Package

(PLCC-20)

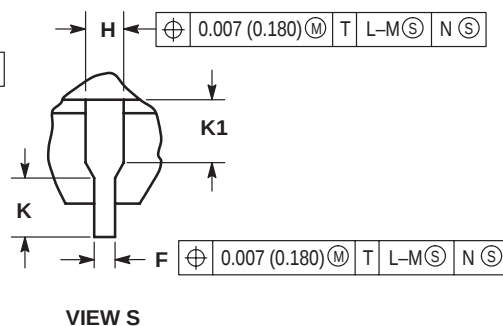
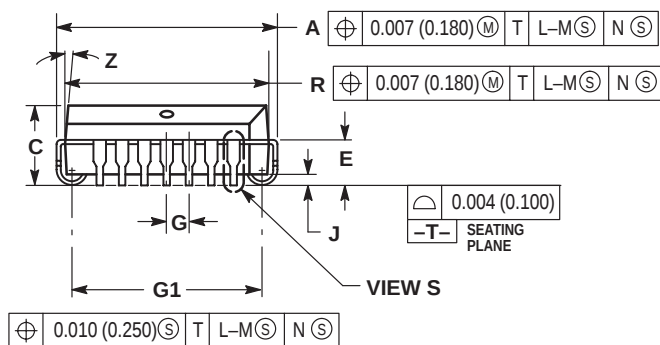
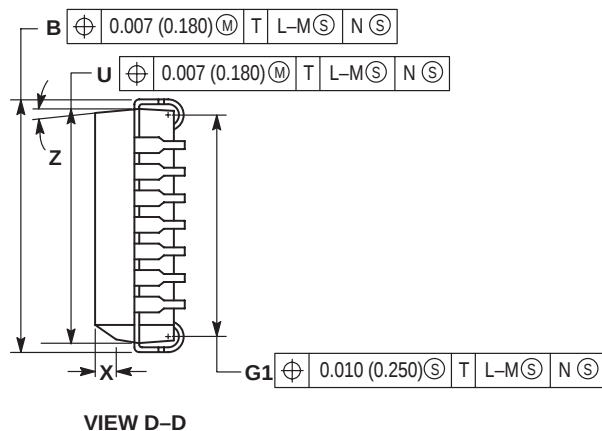
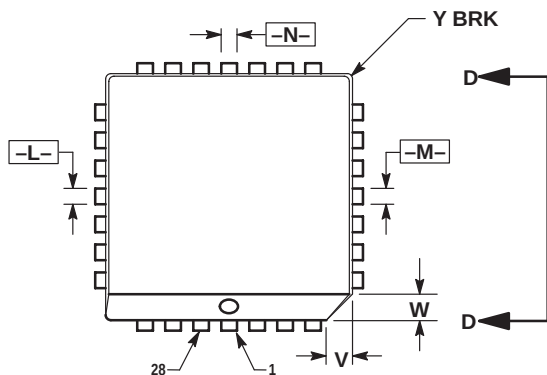
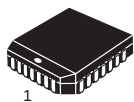
ISSUE C

**NOTES:**

1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: INCH.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
B	0.385	0.395	9.78	10.03
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	—	0.51	—
K	0.025	—	0.64	—
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	—	0.020	—	0.50
Z	2°	10°	2°	10°
G1	0.310	0.330	7.88	8.38
K1	0.040	—	1.02	—

FN SUFFIX
CASE 776-02
 Plastic Package
 (PLCC-28)
 ISSUE D

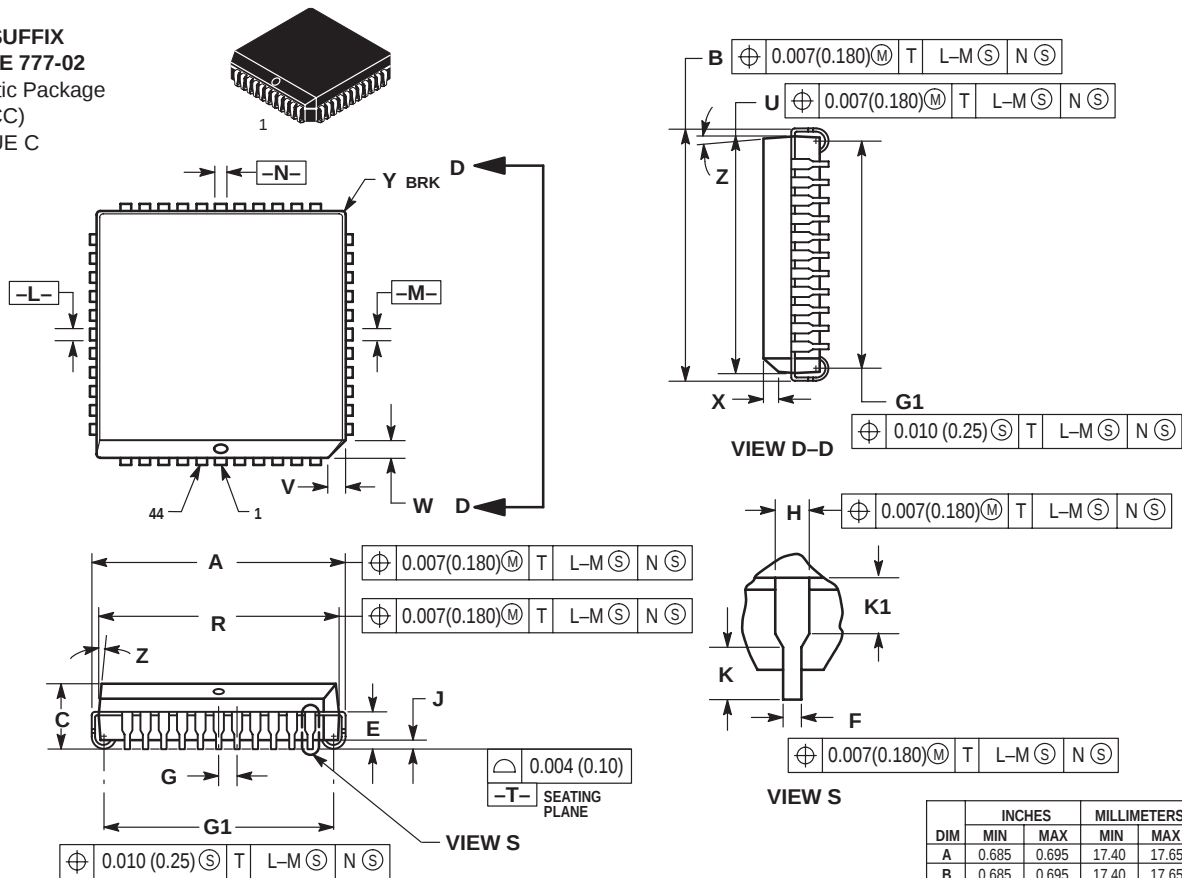


NOTES:

1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: INCH.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.485	0.495	12.32	12.57
B	0.485	0.495	12.32	12.57
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	—	0.51	—
K	0.025	—	0.64	—
R	0.450	0.456	11.43	11.58
U	0.450	0.456	11.43	11.58
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	—	0.020	—	0.50
Z	2°	10°	2°	10°
G1	0.410	0.430	10.42	10.92
K1	0.040	—	1.02	—

FN SUFFIX
CASE 777-02
 Plastic Package
 (PLCC)
 ISSUE C



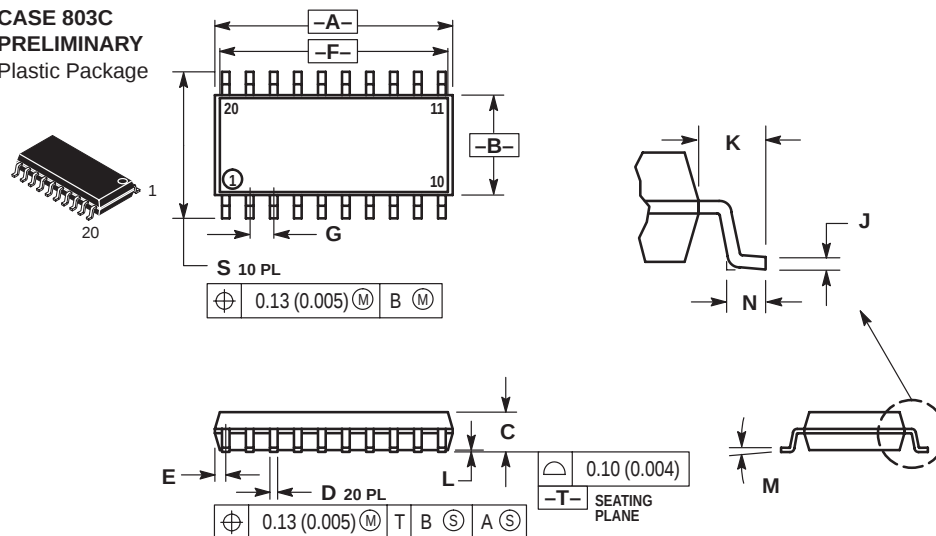
NOTES:

1. DATUMS -L-, -M-, AND -N- ARE DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.25) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: INCH.

6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.685	0.695	17.40	17.65
B	0.685	0.695	17.40	17.65
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	—	0.51	—
K	0.025	—	0.64	—
R	0.650	0.656	16.51	16.66
U	0.650	0.656	16.51	16.66
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	—	0.020	—	0.50
Z	2°	10°	2°	10°
G1	0.610	0.630	15.50	16.00
K1	0.040	—	1.02	—

M SUFFIX
CASE 803C
PRELIMINARY
 Plastic Package



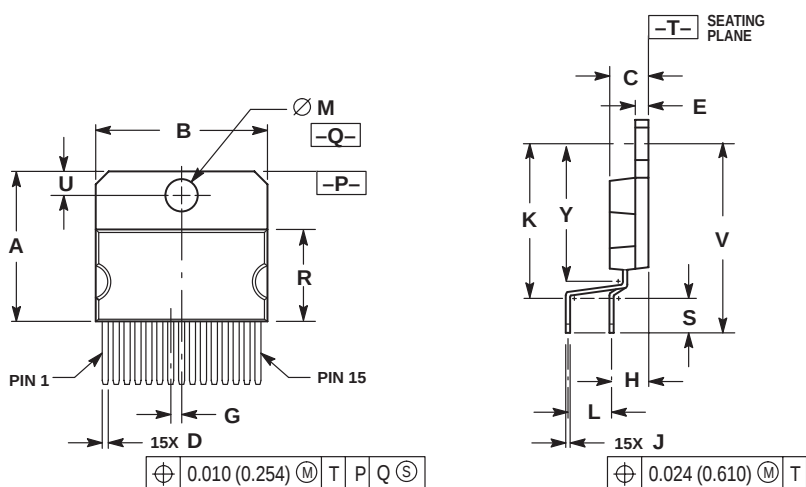
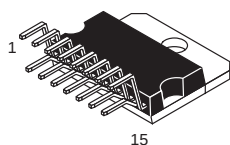
NOTES:

6. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
7. CONTROLLING DIMENSION: MILLIMETER.
8. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
9. MAXIMUM MOLD PROTRUSION 0.15 (0.008) PER SIDE.
10. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.006) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	12.35	12.80	0.486	0.504
B	5.10	5.45	0.201	0.215
C	1.95	2.05	0.077	0.081
D	0.35	0.50	0.014	0.020
E	—	0.81	—	0.032
F	12.40*		0.488*	
G	1.15	1.39	0.045	0.055
H	0.59	0.81	0.023	0.032
J	0.18	0.27	0.007	0.011
K	1.10	1.50	0.043	0.059
L	0.05	0.20	0.001	0.008
M	0°	10°	0°	10°
N	0.50	0.85	0.020	0.033
S	7.40	8.20	0.291	0.323

*APPROXIMATE

TV SUFFIX
CASE 821C-04
 Plastic Package
 (15-Pin ZIP)
 ISSUE D

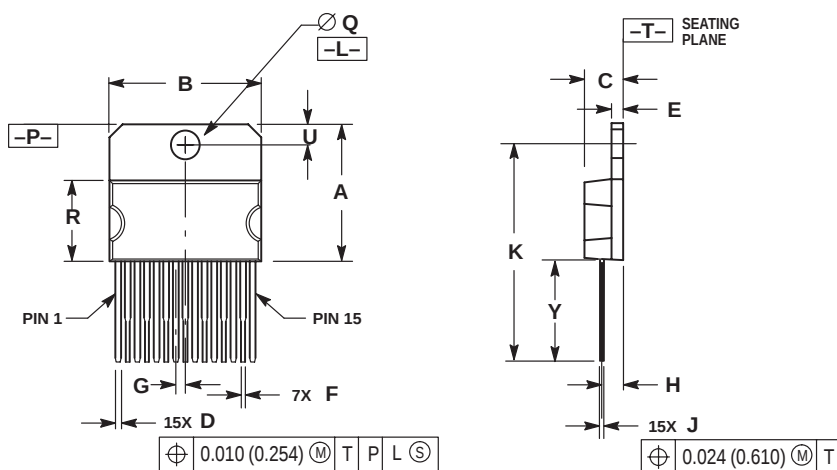
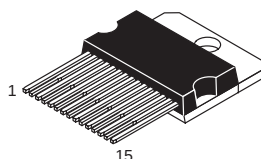


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION R DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
5. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.010 (0.250).
6. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.003 (0.076) TOTAL IN EXCESS OF THE D DIMENSION, AT MAXIMUM MATERIAL CONDITION.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.684	0.694	17.374	17.627
B	0.784	0.792	19.914	20.116
C	0.173	0.181	4.395	4.597
D	0.024	0.031	0.610	0.787
E	0.058	0.062	1.473	1.574
G	0.050 BSC		1.270 BSC	
H	0.169 BSC		4.293 BSC	
J	0.018	0.024	0.458	0.609
K	0.700	0.710	17.780	18.034
L	0.200 BSC		5.080 BSC	
M	0.148	0.151	3.760	3.835
R	0.416	0.426	10.567	10.820
S	0.157	0.167	3.988	4.242
U	0.105	0.115	2.667	2.921
V	0.868 REF		22.047 REF	
Y	0.625	0.639	15.875	16.231

T SUFFIX
CASE 821D-03
 Plastic Package
 ISSUE C

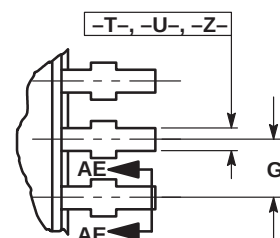
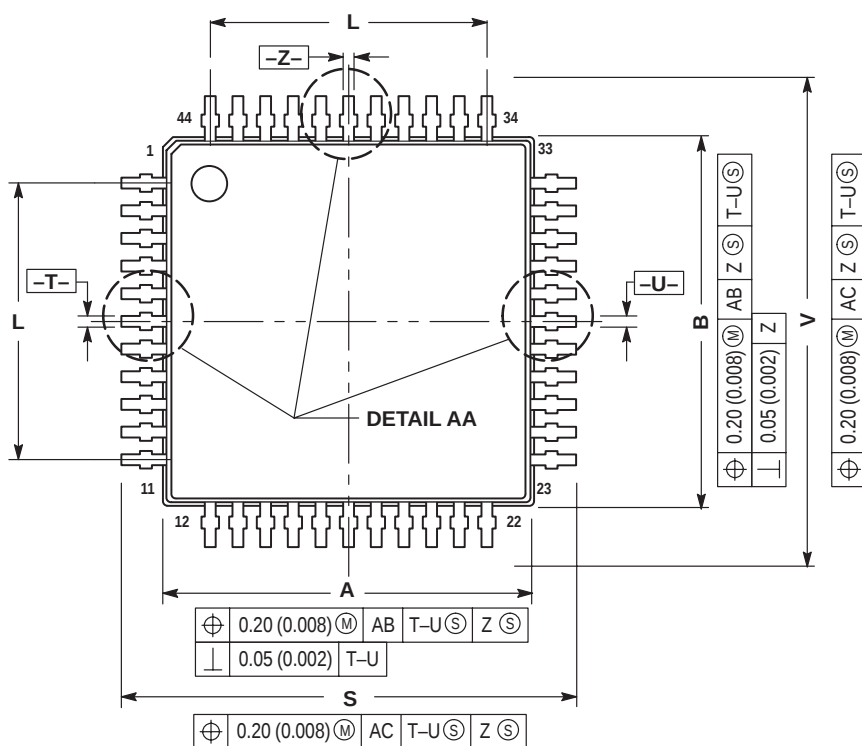
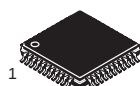


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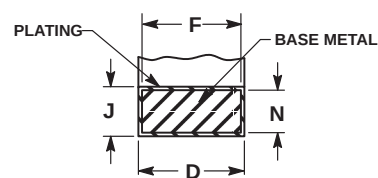
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION R DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
5. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.010 (0.250).
6. DELETED
7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.003 (0.076) TOTAL IN EXCESS OF THE D DIMENSION, AT MAXIMUM MATERIAL CONDITION.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.681	0.694	17.298	17.627
B	0.784	0.792	19.914	20.116
C	0.173	0.181	4.395	4.597
D	0.024	0.031	0.610	0.787
E	0.058	0.062	1.473	1.574
F	0.016	0.023	0.407	0.584
G	0.050 BSC		1.270 BSC	
H	0.110 BSC		2.794 BSC	
J	0.018	0.024	0.458	0.609
K	1.078	1.086	27.382	27.584
Q	0.148	0.151	3.760	3.835
R	0.416	0.426	10.567	10.820
U	0.110 BSC		2.794 BSC	
Y	0.503 REF		12.776 REF	

FTB SUFFIX
CASE 824D-01
 Plastic Package
 (TQFP-44)
 ISSUE O

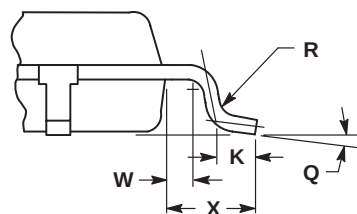
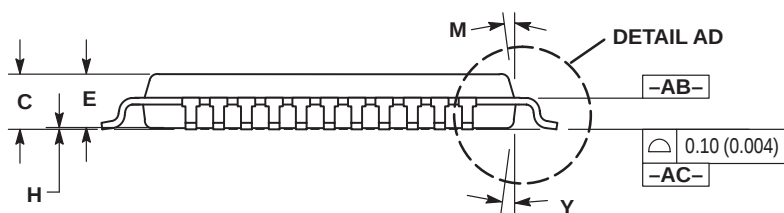


DETAIL AA



SECTION AE-AE

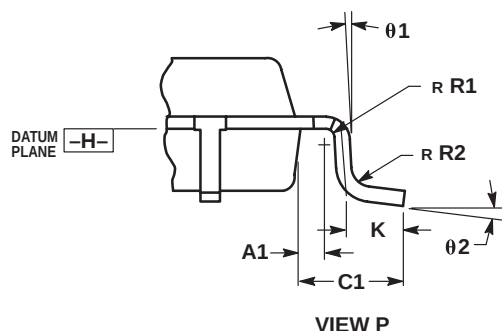
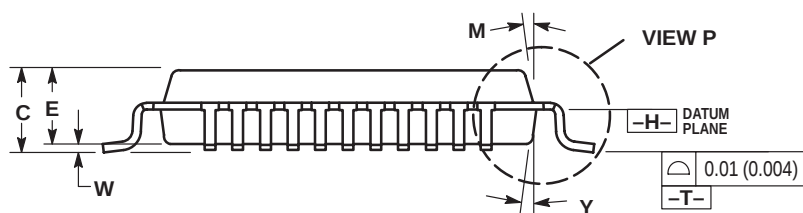
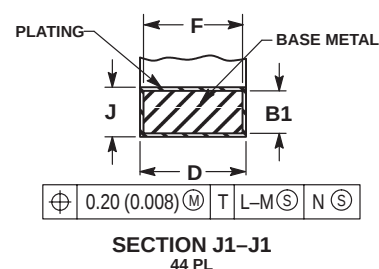
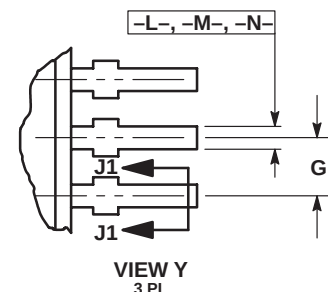
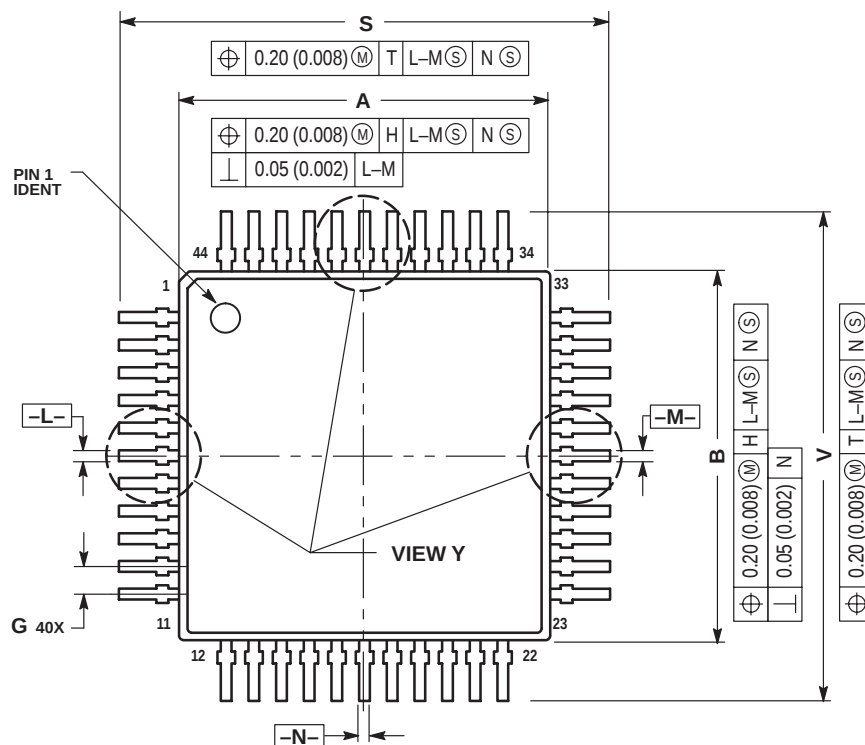
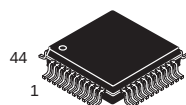
- NOTES:**
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
 4. DATUMS -T-, -U- AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.
 5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -AC-.
 6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
 7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.530 (0.021).



VIEW AD

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.950	10.050	0.392	0.396
B	9.950	10.050	0.392	0.396
C	1.400	1.600	0.055	0.063
D	0.300	0.450	0.012	0.018
E	1.350	1.450	0.053	0.057
F	0.300	0.400	0.012	0.016
G	0.800 BSC		0.031 BSC	
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.450	0.550	0.018	0.022
L	8.000 BSC		0.315 BSC	
M	12° REF		12° REF	
N	0.090	0.160	0.004	0.006
Q	1°	5°	1°	5°
R	0.100	0.200	0.004	0.008
S	11.900	12.100	0.469	0.476
V	11.900	12.100	0.469	0.476
W	0.200 REF		0.008 REF	
X	1.000 REF		0.039 REF	
Y	12° REF		12° REF	

FB SUFFIX
CASE 824E-02
 Plastic Package
 (QFP)
 ISSUE A

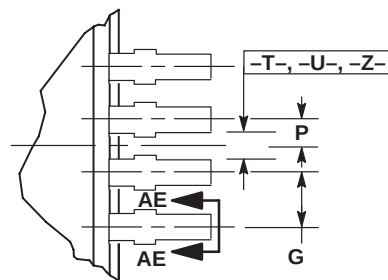
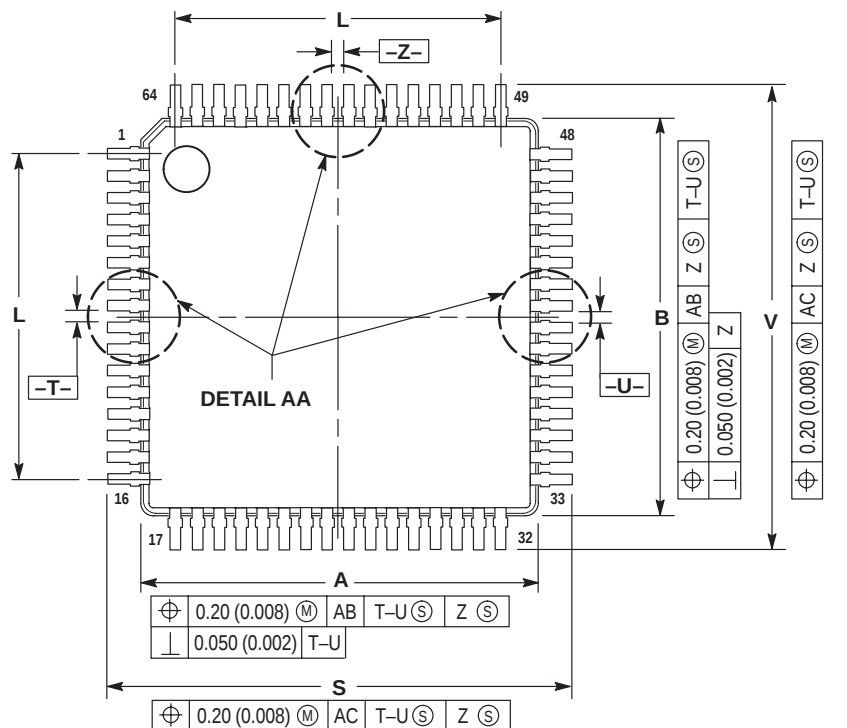
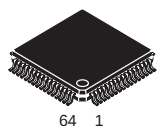


NOTES:

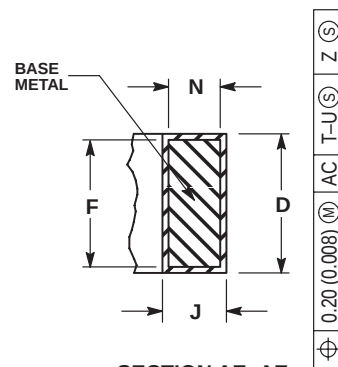
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS -L-, -M- AND -N- TO BE DETERMINED AT DATUM PLANE -H-.
5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -T-.
6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.530 (0.021).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.90	10.10	0.390	0.398
B	9.90	10.10	0.390	0.398
C	2.00	2.21	0.079	0.087
D	0.30	0.45	0.0118	0.0177
E	2.00	2.10	0.079	0.083
F	0.30	0.40	0.012	0.016
G	0.80 BSC		0.031 BSC	
J	0.13	0.23	0.005	0.009
K	0.65	0.95	0.026	0.037
M	5°	10°	5°	10°
S	12.95	13.45	0.510	0.530
V	12.95	13.45	0.510	0.530
W	0.000	0.210	0.000	0.008
Y	5°	10°	5°	10°
A1	0.450 REF		0.018 REF	
B1	0.130	0.170	0.005	0.007
C1	1.600 REF		0.063 REF	
R1	0.130	0.300	0.005	0.012
R2	0.130	0.300	0.005	0.012
θ1	5°	10°	5°	10°
θ2	0°	7°	0°	7°

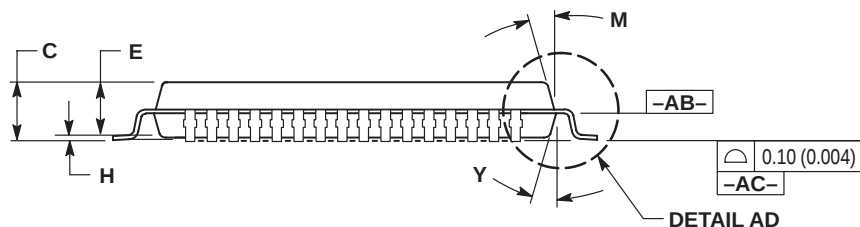
FB SUFFIX
CASE 840F-01
 Plastic Package
 ISSUE O



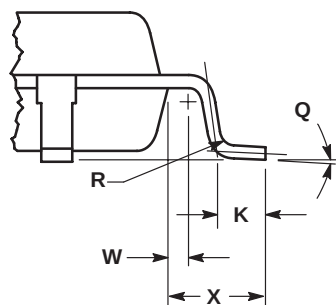
DETAIL AA



SECTION AE-AE



DETAIL AD



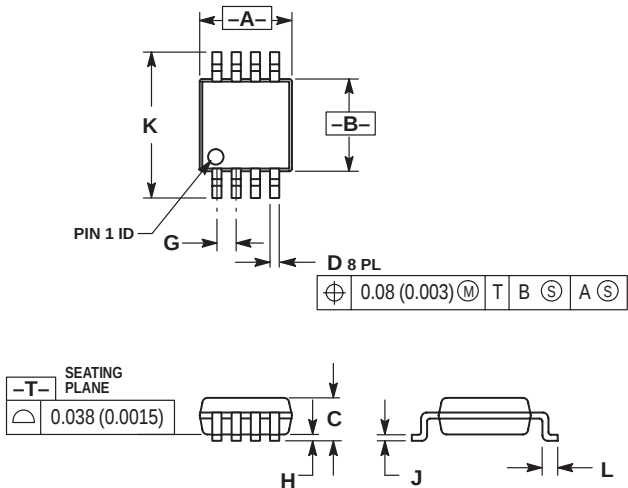
DETAIL AD

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS -T-, -U- AND -Z- TO BE DETERMINED AT DATUM PLANE -AC-.
5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -AC-.
6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.350 (0.014).

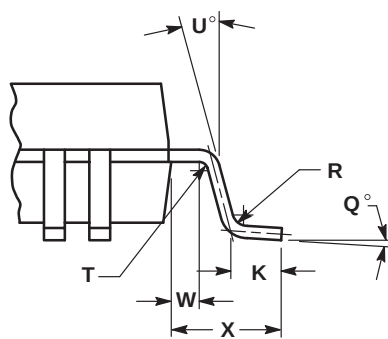
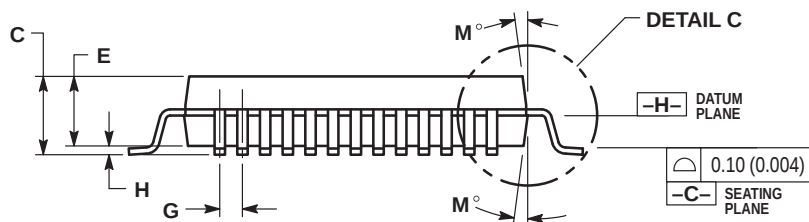
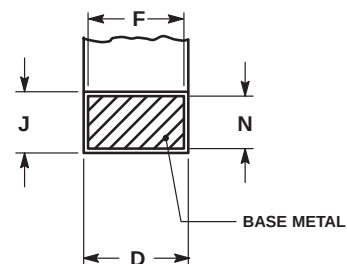
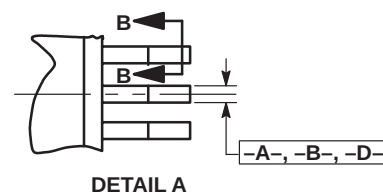
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.950	10.050	0.392	0.396
B	9.950	10.050	0.392	0.396
C	1.400	1.600	0.055	0.063
D	0.170	0.270	0.007	0.011
E	1.350	1.450	0.053	0.057
F	0.170	0.230	0.007	0.009
G	0.500 BSC		0.020 BSC	
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.450	0.550	0.018	0.022
L	7.500 BSC		0.295 BSC	
M	12° REF		12° REF	
N	0.090	0.160	0.004	0.006
P	0.250 BSC		0.010 BSC	
Q	1°	5°	1°	5°
R	0.100	0.200	0.004	0.008
S	11.900	12.100	0.469	0.476
V	11.900	12.100	0.469	0.476
W	0.200 REF		0.008 REF	
X	1.000 REF		0.039 REF	
Y	12° REF		12° REF	

DM SUFFIX
CASE 846A-02
 Plastic Package
 (Micro-8)
 ISSUE C



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	—	1.10	—	0.043
D	0.25	0.40	0.010	0.016
G	0.65 BSC		0.026 BSC	
H	0.05	0.15	0.002	0.006
J	0.13	0.23	0.005	0.009
K	4.75	5.05	0.187	0.199
L	0.40	0.70	0.016	0.028

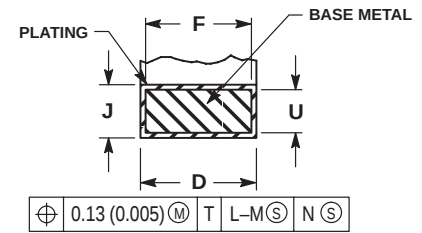
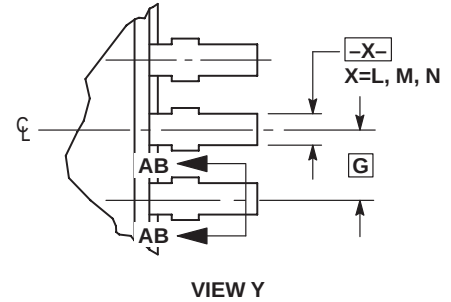
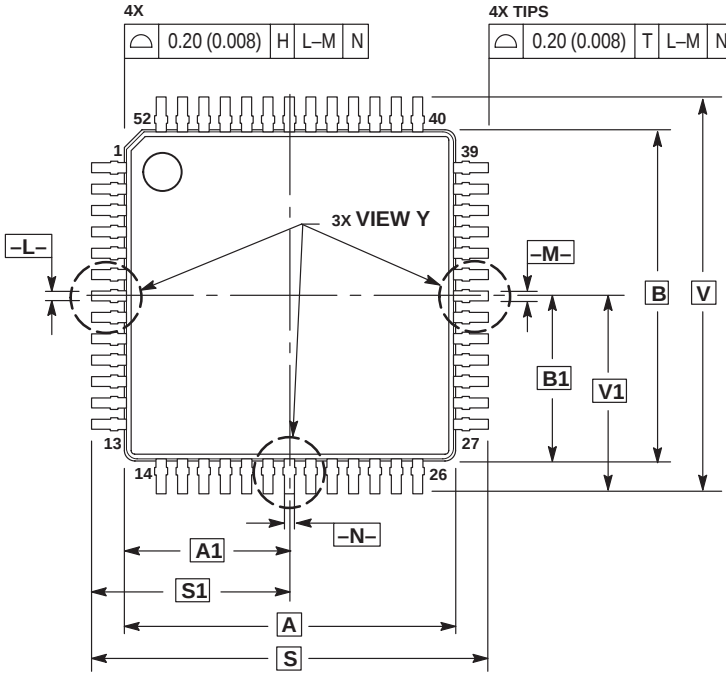
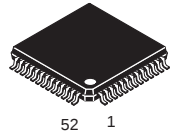


NOTES:

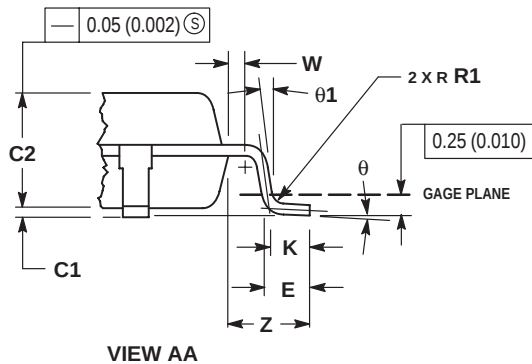
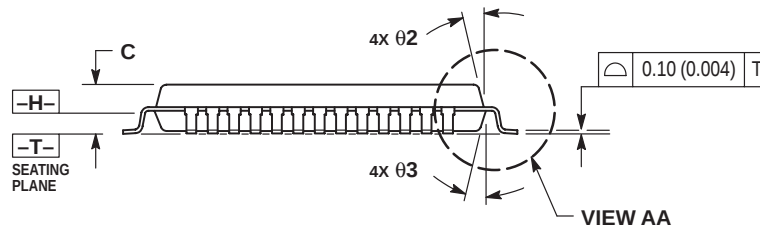
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE --H-- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS --A--, --B-- AND --D-- TO BE DETERMINED AT DATUM PLANE --H--.
5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE --C--.
6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE --H--.
7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.90	10.10	0.390	0.398
B	9.90	10.10	0.390	0.398
C	2.10	2.45	0.083	0.096
D	0.22	0.38	0.009	0.015
E	2.00	2.10	0.079	0.083
F	0.22	0.33	0.009	0.013
G	0.65 BSC		0.026 BSC	
H	—	0.25	—	0.010
J	0.13	0.23	0.005	0.009
K	0.65	0.95	0.026	0.037
L	7.80 REF		0.307 REF	
M	5°	10°	5°	10°
N	0.13	0.17	0.005	0.007
Q	0°	7°	0°	7°
R	0.13	0.30	0.005	0.012
S	12.95	13.45	0.510	0.530
T	0.13	—	0.005	—
U	0°	—	0°	—
V	12.95	13.45	0.510	0.530
W	0.35	0.45	0.014	0.018
X	1.6 REF		0.063 REF	

FB SUFFIX
CASE 848D-03
 Plastic Package
 ISSUE C



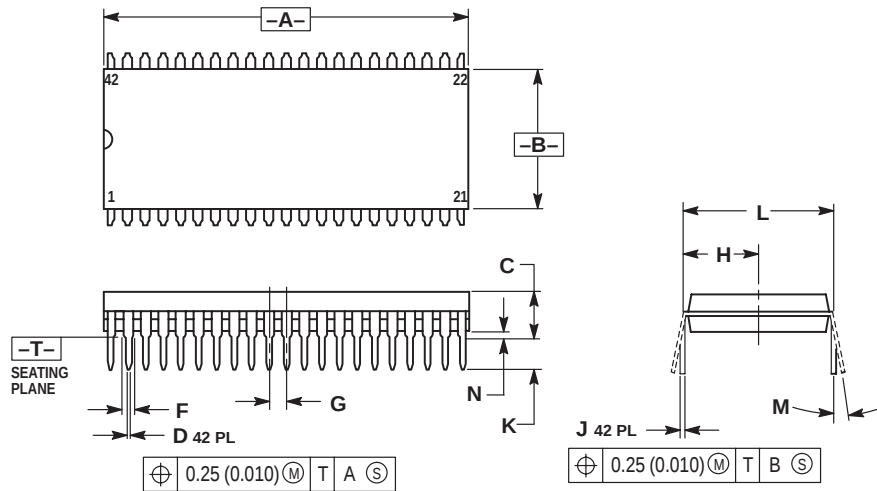
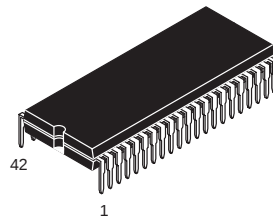
SECTION AB-AB
 ROTATED 90° CLOCKWISE



- NOTES:**
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
 4. DATUMS -L-, -M- AND -N- TO BE DETERMINED AT DATUM PLANE -H-.
 5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -T-.
 6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
 7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.46 (0.018). MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07 (0.003).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.00 BSC		0.394 BSC	
A1	5.00 BSC		0.197 BSC	
B	10.00 BSC		0.394 BSC	
B1	5.00 BSC		0.197 BSC	
C	—	1.70	—	0.067
C1	0.05	0.20	0.002	0.008
C2	1.30	1.50	0.051	0.059
D	0.20	0.40	0.008	0.016
E	0.45	0.75	0.018	0.030
F	0.22	0.35	0.009	0.014
G	0.65 BSC		0.026 BSC	
J	0.07	0.20	0.003	0.008
K	0.50 REF		0.020 REF	
R1	0.08	0.20	0.003	0.008
S	12.00 BSC		0.472 BSC	
S1	6.00 BSC		0.236 BSC	
U	0.09	0.16	0.004	0.006
V	12.00 BSC		0.472 BSC	
V1	6.00 BSC		0.236 BSC	
W	0.20 REF		0.008 REF	
Z	1.00 REF		0.039 REF	
θ	0°	7°	0°	7°
θ1	0°	—	0°	—
θ2	12° REF		12° REF	
θ3	5°	13°	5°	13°

B SUFFIX
CASE 858-01
 Plastic Package
 ISSUE O

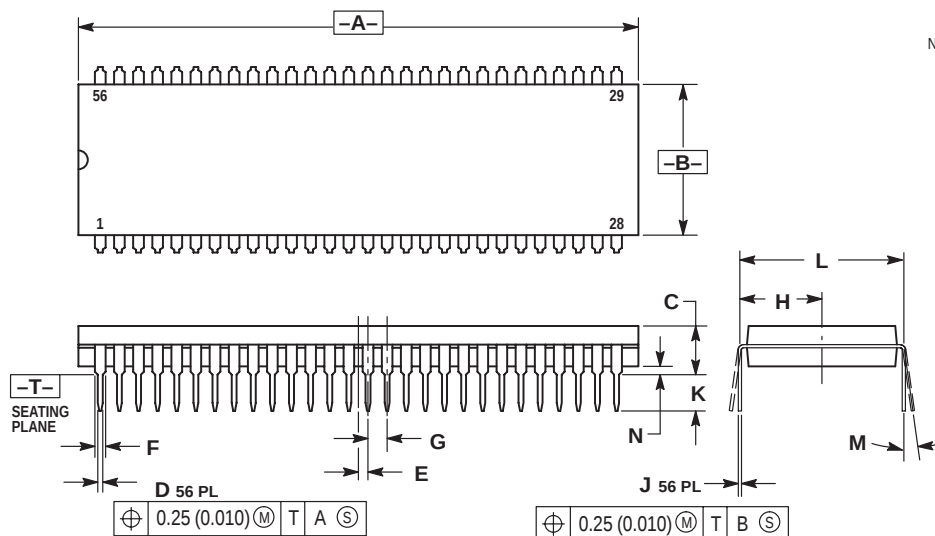
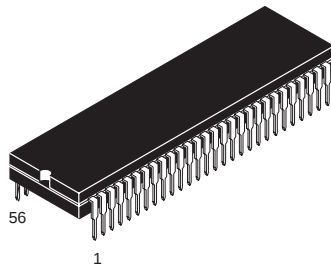


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH. MAXIMUM MOLD FLASH 0.25 (0.010).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.435	1.465	36.45	37.21
B	0.540	0.560	13.72	14.22
C	0.155	0.200	3.94	5.08
D	0.014	0.022	0.36	0.56
F	0.032	0.046	0.81	1.17
G	0.070 BSC		1.778 BSC	
H	0.300 BSC		7.62 BSC	
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.600 BSC		15.24 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.02

B SUFFIX
CASE 859-01
 Plastic Package
 (SDIP)
 ISSUE O

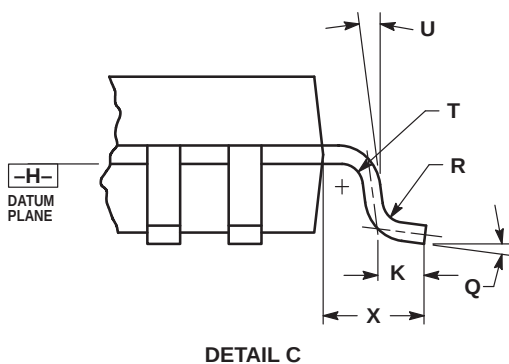
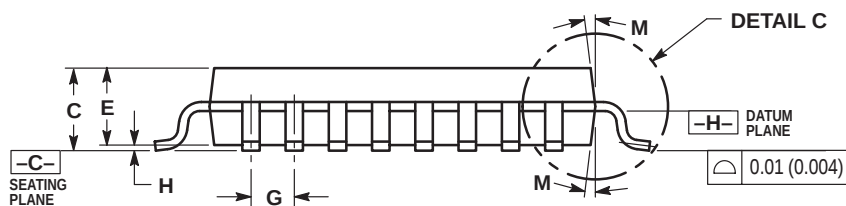
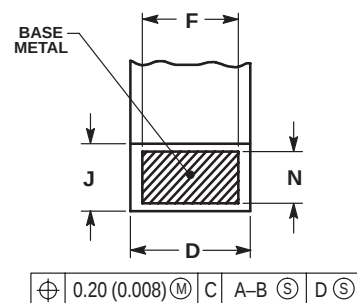
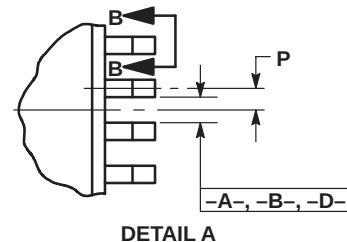
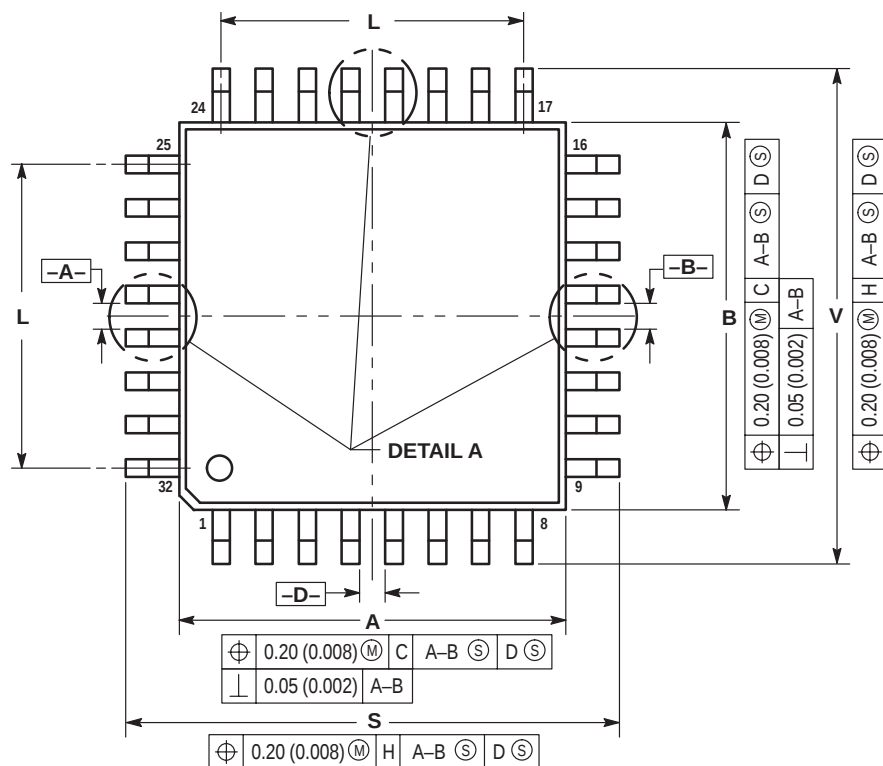
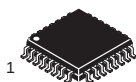


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH. MAXIMUM MOLD FLASH 0.25 (0.010)

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	2.035	2.065	51.69	52.45
B	0.540	0.560	13.72	14.22
C	0.155	0.200	3.94	5.08
D	0.014	0.022	0.36	0.56
E	0.035 BSC		0.89 BSC	
F	0.032	0.046	0.81	1.17
G	0.070 BSC		1.778 BSC	
H	0.300 BSC		7.62 BSC	
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.600 BSC		15.24 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.02

FB, FTB SUFFIX
CASE 873-01
Plastic Package
(TQFP-32)
ISSUE A

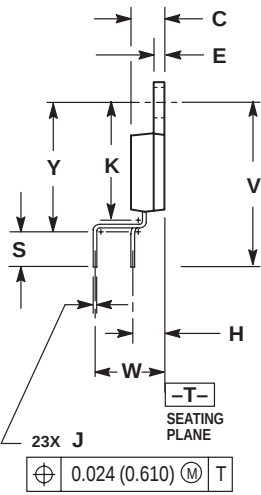
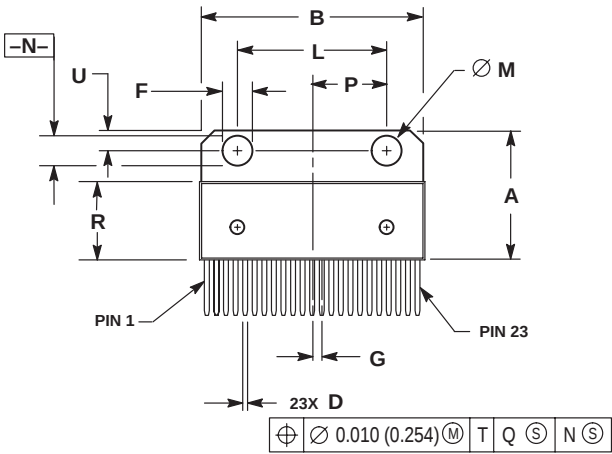
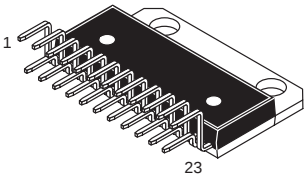


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS -A-, -B- AND -D- TO BE DETERMINED AT DATUM PLANE -H-.
5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -C-.
6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.95	7.10	0.274	0.280
B	6.95	7.10	0.274	0.280
C	1.40	1.60	0.055	0.063
D	0.273	0.373	0.010	0.015
E	1.30	1.50	0.051	0.059
F	0.273	—	0.010	—
G	0.80	BSC	0.031	BSC
H	—	0.20	—	0.008
J	0.119	0.197	0.005	0.008
K	0.33	0.57	0.013	0.022
L	5.6	REF	0.220	REF
M	6°	8°	6°	8°
N	0.119	0.135	0.005	0.005
P	0.40	BSC	0.016	BSC
Q	5°	10°	5°	10°
R	0.15	0.25	0.006	0.010
S	8.85	9.15	0.348	0.360
T	0.15	0.25	0.006	0.010
U	5°	11°	5°	11°
V	8.85	9.15	0.348	0.360
X	1.00	REF	0.039	REF

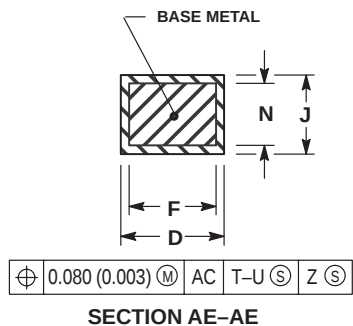
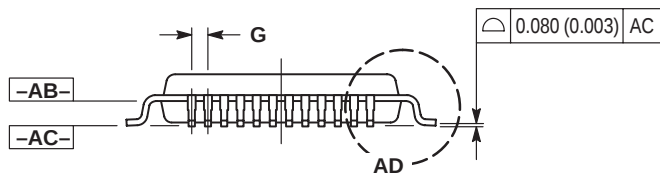
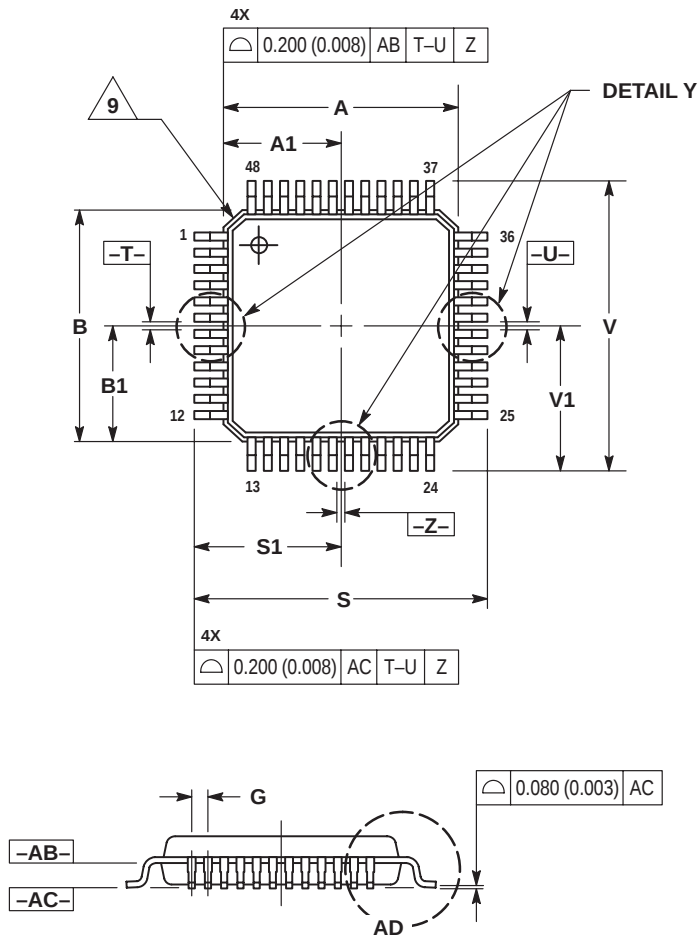
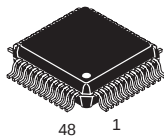
T SUFFIX
CASE 894-03
 Plastic Package
 (23-Pin SZIP)
 ISSUE B



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION R DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
 5. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.010 (0.250).
 6. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.003 (0.076) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.684	0.694	17.374	17.627
B	1.183	1.193	30.048	30.302
C	0.175	0.179	4.445	4.547
D	0.026	0.031	0.660	0.787
E	0.058	0.062	1.473	1.574
F	0.165	0.175	4.191	4.445
G	0.050 BSC		1.270 BSC	
H	0.169 BSC		4.293 BSC	
J	0.014	0.020	0.356	0.508
K	0.625	0.639	15.875	16.231
L	0.770	0.790	19.558	20.066
M	0.148	0.152	3.760	3.861
N	0.148	0.152	3.760	3.861
P	0.390 BSC		9.906 BSC	
R	0.416	0.424	10.566	10.770
S	0.157	0.167	3.988	4.242
U	0.105	0.115	2.667	2.921
V	0.868 REF		22.047 REF	
W	0.200 BSC		5.080 BSC	
Y	0.700	0.710	17.780	18.034

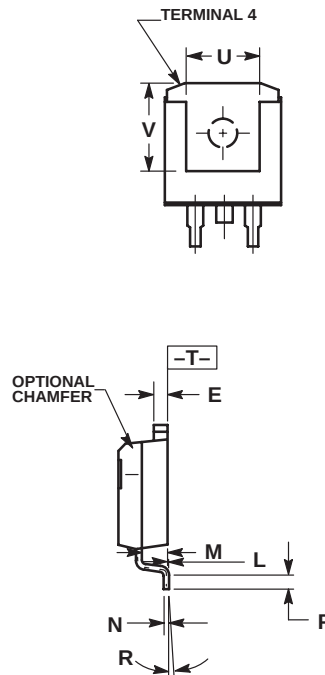
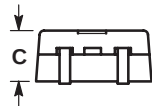
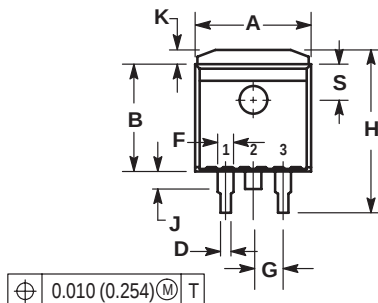
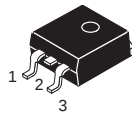
FTA SUFFIX
CASE 932-02
Plastic Package
(TQFP-48)
ISSUE D



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
 4. DATUMS -T-, -U-, AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.
 5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -AC-.
 6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
 7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.350 (0.014).
 8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.0003).
 9. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	7.000 BSC		0.276 BSC	
A1	3.500 BSC		0.138 BSC	
B	7.000 BSC		0.276 BSC	
B1	3.500 BSC		0.138 BSC	
C	1.400	1.600	0.055	0.063
D	0.170	0.270	0.007	0.011
E	1.350	1.450	0.053	0.057
F	0.170	0.230	0.007	0.009
G	0.500 BASIC		0.020 BASIC	
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.500	0.700	0.020	0.028
M	12° REF		12° REF	
N	0.090	0.160	0.004	0.006
P	0.250 BASIC		0.010 BASIC	
Q	1°	5°	1°	5°
R	0.150	0.250	0.006	0.010
S	9.000 BSC		0.354 BSC	
S1	4.500 BSC		0.177 BSC	
V	9.000 BSC		0.354 BSC	
V1	4.500 BSC		0.177 BSC	
W	0.200 REF		0.008 REF	
X	1.000 REF		0.039 REF	

D2T SUFFIX
CASE 936-03
 Plastic Package
 ISSUE B

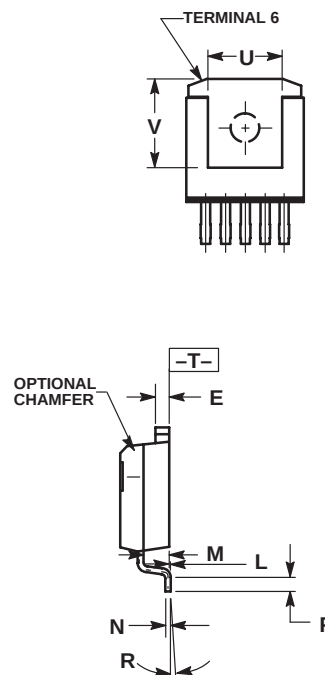
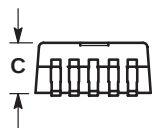
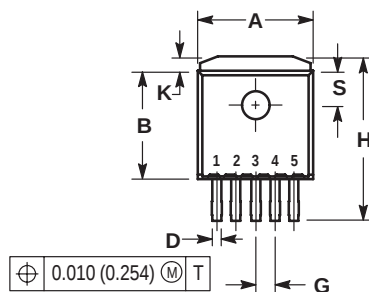
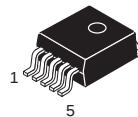


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. TAB CONTOUR OPTIONAL WITHIN DIMENSIONS A AND K.
4. DIMENSIONS U AND V ESTABLISH A MINIMUM MOUNTING SURFACE FOR TERMINAL 4.
5. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.025 (0.635) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.386	0.403	9.804	10.236
B	0.356	0.368	9.042	9.347
C	0.170	0.180	4.318	4.572
D	0.026	0.036	0.660	0.914
E	0.045	0.055	1.143	1.397
F	0.051 REF		1.295 REF	
G	0.100 BSC		2.540 BSC	
H	0.539	0.579	13.691	14.707
J	0.125 MAX		3.175 MAX	
K	0.050 REF		1.270 REF	
L	0.000	0.010	0.000	0.254
M	0.088	0.102	2.235	2.591
N	0.018	0.026	0.457	0.660
P	0.058	0.078	1.473	1.981
R	5° REF		5° REF	
S	0.116 REF		2.946 REF	
U	0.200 MIN		5.080 MIN	
V	0.250 MIN		6.350 MIN	

D2T SUFFIX
CASE 936A-02
 Plastic Package
 (D²PAK)
 ISSUE A

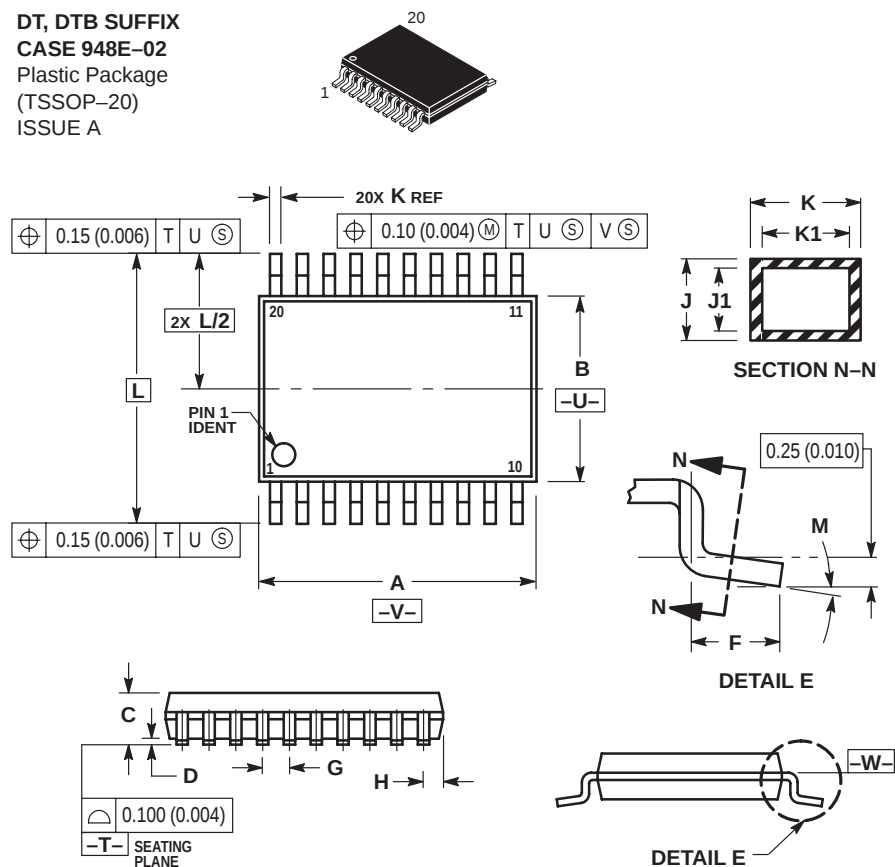


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. TAB CONTOUR OPTIONAL WITHIN DIMENSIONS A AND K.
4. DIMENSIONS U AND V ESTABLISH A MINIMUM MOUNTING SURFACE FOR TERMINAL 6.
5. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.025 (0.635) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.386	0.403	9.804	10.236
B	0.356	0.368	9.042	9.347
C	0.170	0.180	4.318	4.572
D	0.026	0.036	0.660	0.914
E	0.045	0.055	1.143	1.397
G	0.067 BSC		1.702 BSC	
H	0.539	0.579	13.691	14.707
K	0.050 REF		1.270 REF	
L	0.000	0.010	0.000	0.254
M	0.088	0.102	2.235	2.591
N	0.018	0.026	0.457	0.660
P	0.058	0.078	1.473	1.981
R	5° REF		5° REF	
S	0.116 REF		2.946 REF	
U	0.200 MIN		5.080 MIN	
V	0.250 MIN		6.350 MIN	

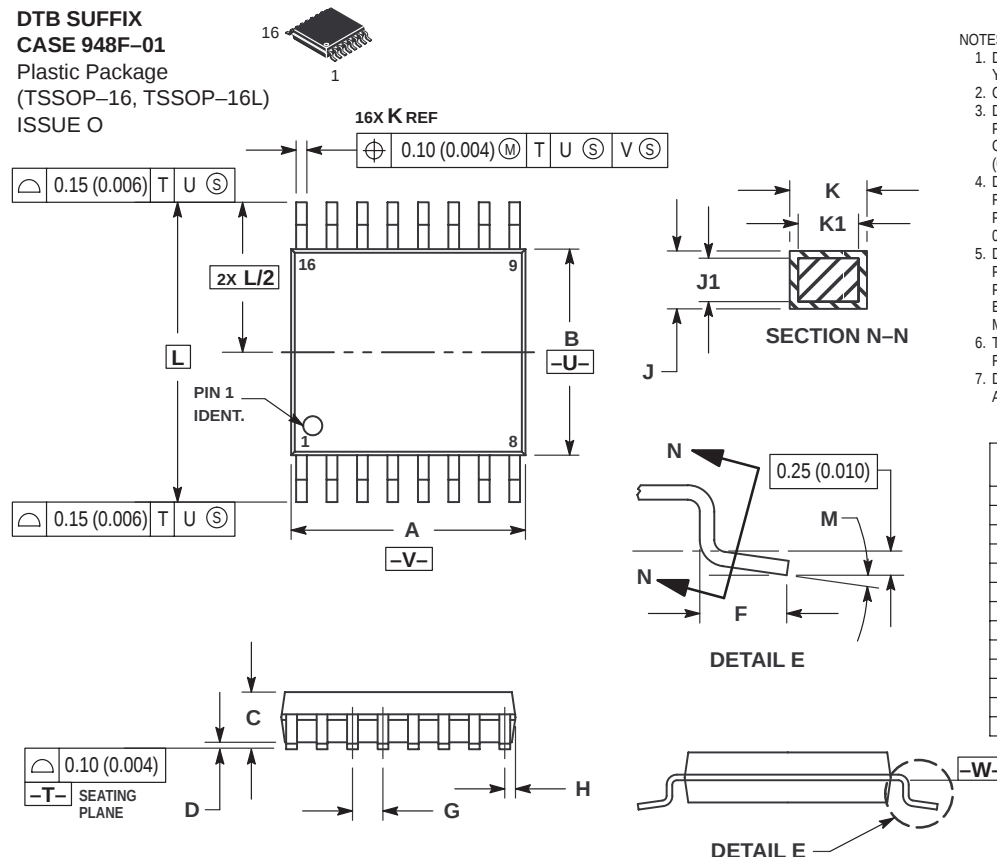
DT, DTB SUFFIX
CASE 948E-02
 Plastic Package
 (TSSOP-20)
 ISSUE A



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.40	6.60	0.252	0.260
B	4.30	4.50	0.169	0.177
C	—	1.20	—	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

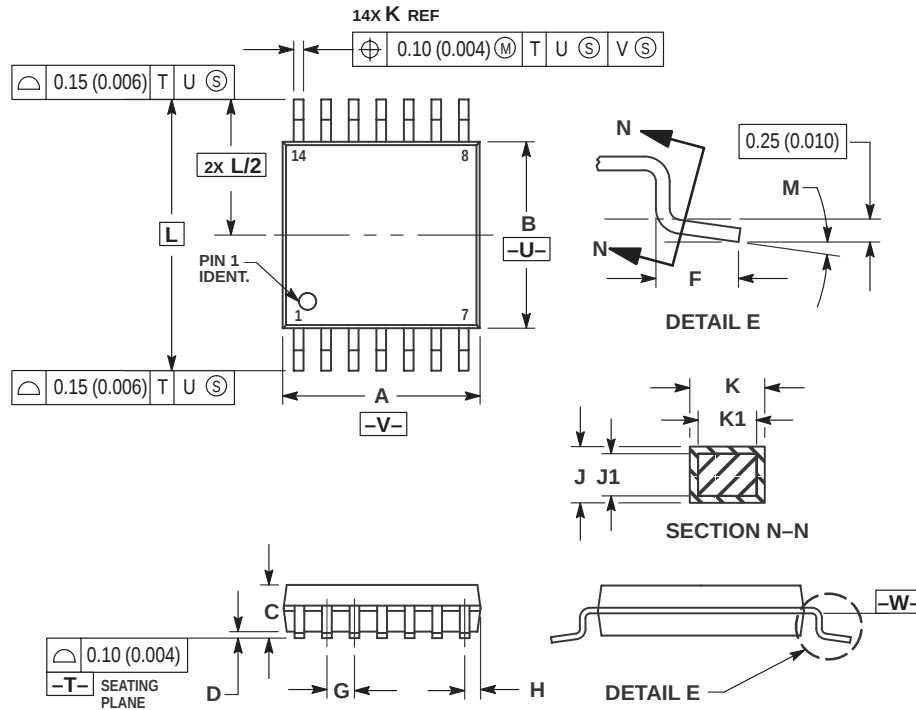
DTB SUFFIX
CASE 948F-01
 Plastic Package
 (TSSOP-16, TSSOP-16L)
 ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	—	1.20	—	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

DTB SUFFIX
CASE 948G-01
 Plastic Package
 (TSSOP-14)
 ISSUE O

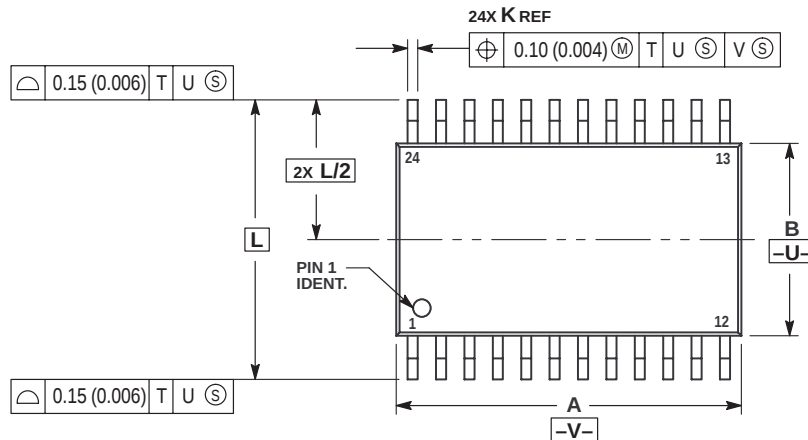
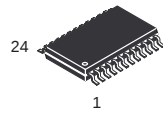


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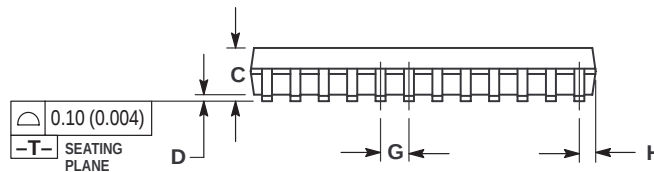
- 1 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2 CONTROLLING DIMENSION: MILLIMETER.
- 3 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- 4 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- 5 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 6 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- 7 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	—	1.20	—	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

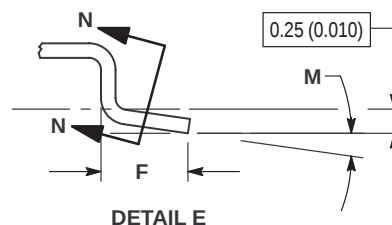
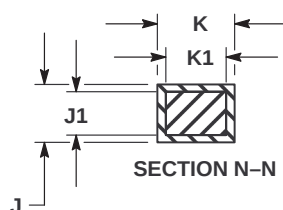
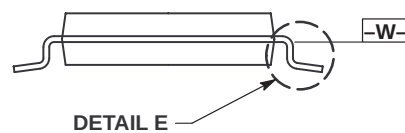
DTB SUFFIX
CASE 948H-01
 Plastic Package
 ISSUE O



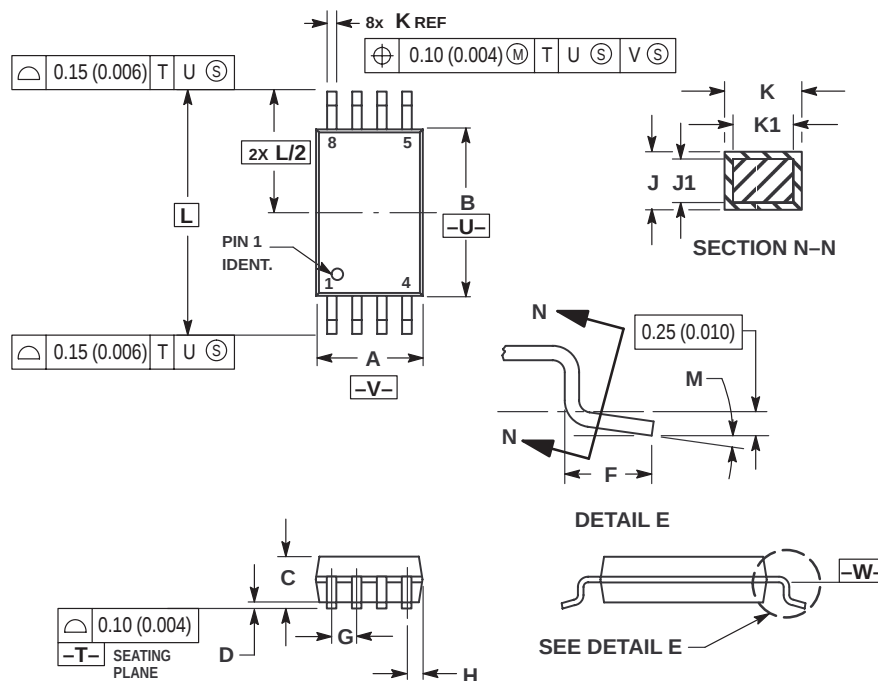
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	7.70	7.90	0.303	0.311
B	4.30	4.50	0.169	0.177
C	—	1.20	—	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°



DTB SUFFIX
CASE 948J-01
 Plastic Package
 (TSSOP-8)
 ISSUE O

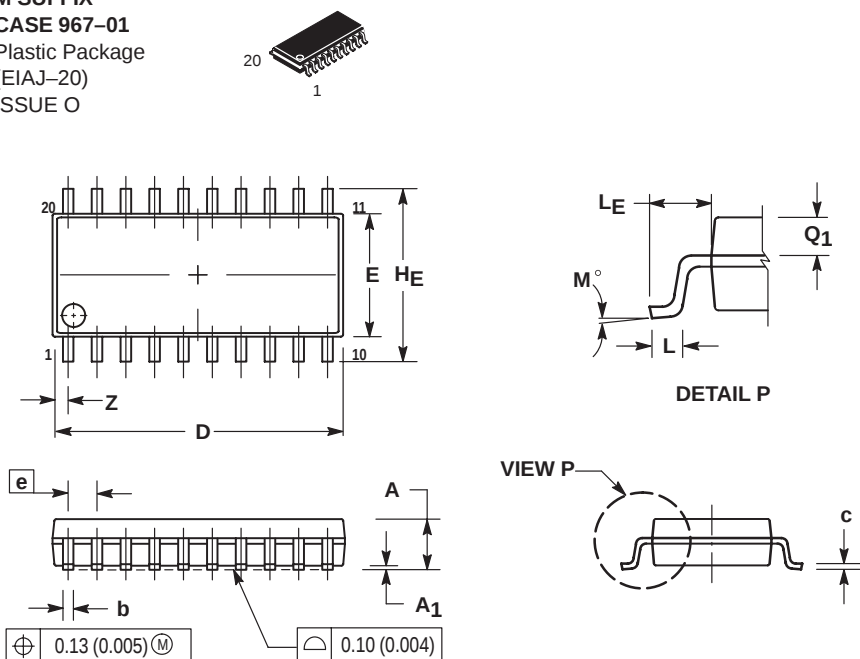


NOTES:

- 1 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2 CONTROLLING DIMENSION: MILLIMETER.
- 3 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- 4 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- 5 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 6 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- 7 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	4.30	4.50	0.169	0.177
C	—	1.20	—	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

M SUFFIX
CASE 967-01
 Plastic Package
 (EIAJ-20)
 ISSUE O

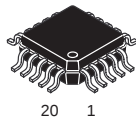


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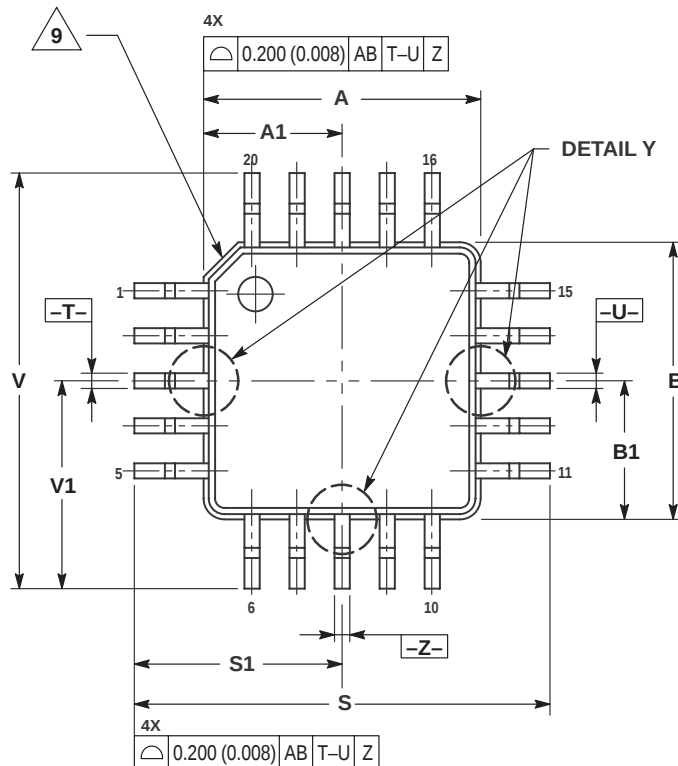
- 1 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2 CONTROLLING DIMENSION: MILLIMETER.
- 3 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- 4 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- 5 THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	—	2.05	—	0.081
A1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	12.35	12.80	0.486	0.504
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q1	0.70	0.90	0.028	0.035
Z	—	0.81	—	0.032

FTB SUFFIX
CASE 976-01
 Plastic Package
 (TQFP-20)
 ISSUE O



20 1



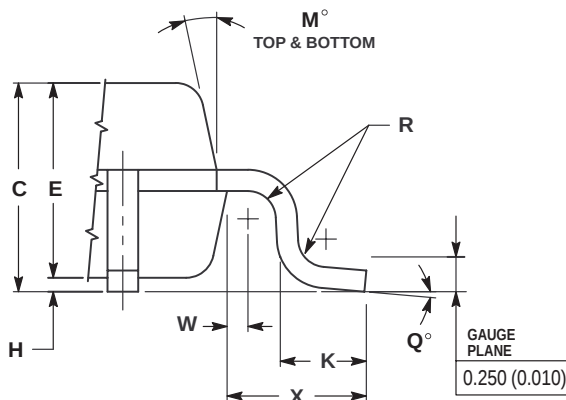
DETAIL Y

DETAIL AD

-AB-

-AC-

0.080 (0.003) AC

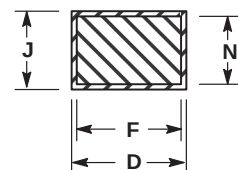


DETAIL AD

DETAIL Y

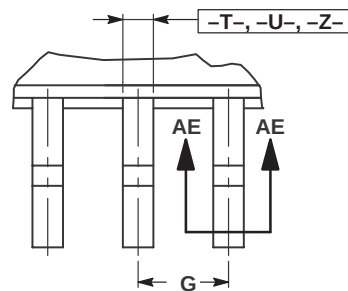
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
 4. DATUMS -T-, -U-, AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.
 5. DIMENSIONS S AND V TO BE DETERMINED AT DATUM PLANE -AC-.
 6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
 7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.350 (0.014).
 8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.0003).
 9. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.000 BSC		0.157 BSC	
A1	2.000 BSC		0.079 BSC	
B	4.000 BSC		0.157 BSC	
B1	2.000 BSC		0.079 BSC	
C	1.400	1.600	0.055	0.063
D	0.170	0.270	0.007	0.011
E	1.350	1.450	0.053	0.057
F	0.170	0.230	0.007	0.009
G	0.650 BSC		0.026 BSC	
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.500	0.700	0.020	0.028
M	12° REF		12° REF	
N	0.090	0.160	0.004	0.006
P	0.250 BSC		0.010 BSC	
Q	1°	5°	1°	5°
R	0.150	0.250	0.006	0.010
S	6.000 BSC		0.236 BSC	
S1	3.000 BSC		0.118 BSC	
V	6.000 BSC		0.236 BSC	
V1	3.000 BSC		0.118 BSC	
W	0.200 REF		0.008 REF	
X	1.000 REF		0.039 REF	

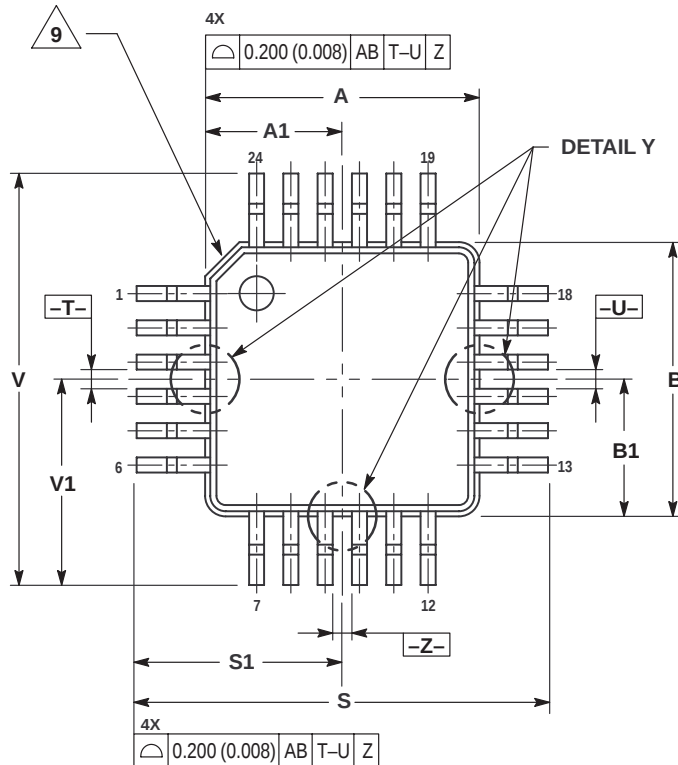
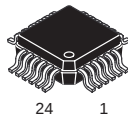


0.080 (0.003) S AC T-U S Z S

SECTION AE-AE

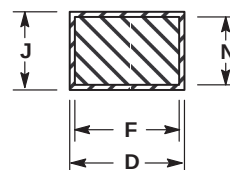
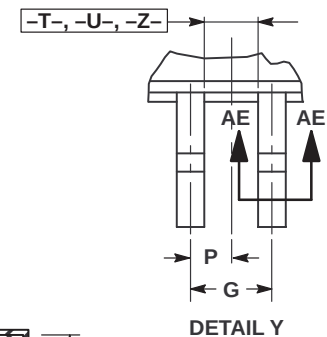
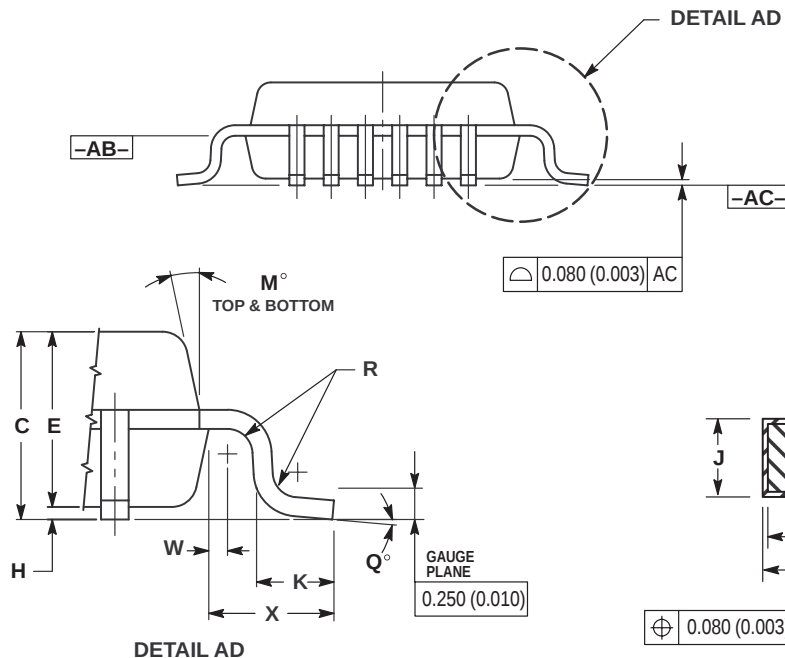


FTA SUFFIX
CASE 977-01
Plastic Package
ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
 4. DATUMS -T-, -U-, AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.
 5. DIMENSIONS S AND V TO BE DETERMINED AT DATUM PLANE -AC-.
 6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
 7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.350 (0.014).
 8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.0003).
 9. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

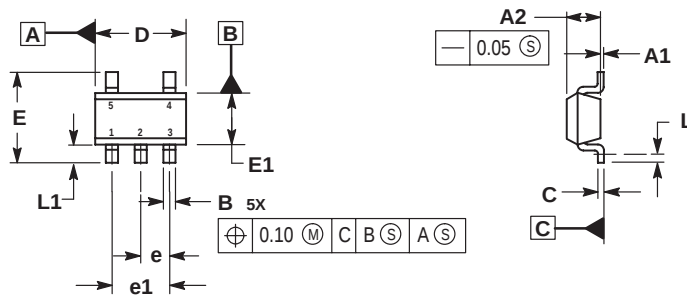
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.000 BSC		0.157 BSC	
A1	2.000 BSC		0.079 BSC	
B	4.000 BSC		0.157 BSC	
B1	2.000 BSC		0.079 BSC	
C	1.400	1.600	0.055	0.063
D	0.170	0.270	0.007	0.011
E	1.350	1.450	0.053	0.057
F	0.170	0.230	0.007	0.009
G	0.500 BSC		0.020 BSC	
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.500	0.700	0.020	0.028
M	12° REF		12° REF	
N	0.090	0.160	0.004	0.006
P	0.250 BSC		0.010 BSC	
Q	1°	5°	1°	5°
R	0.150	0.250	0.006	0.010
S	6.000 BSC		0.236 BSC	
S1	3.000 BSC		0.118 BSC	
V	6.000 BSC		0.236 BSC	
V1	3.000 BSC		0.118 BSC	
W	0.200 REF		0.008 REF	
X	1.000 REF		0.039 REF	



⊕ 0.080 (0.003) ⊙ AC T-U ⊙ Z ⊙

SECTION AE-AE

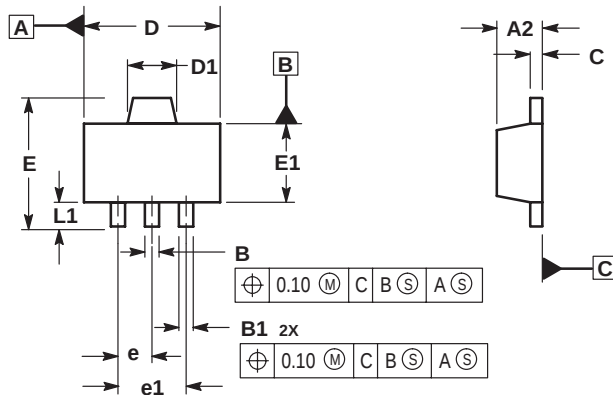
N SUFFIX
CASE 1212-01
 Plastic Package
 (SOT-23)
 ISSUE O



- NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
 3. DATUM C IS A SEATING PLANE.

MILLIMETERS		
DIM	MIN	MAX
A1	0.00	0.10
A2	1.00	1.30
B	0.30	0.50
C	0.10	0.25
D	2.80	3.00
E	2.50	3.10
E1	1.50	1.80
e	0.95 BSC	
e1	1.90 BSC	
L	0.20	—
L1	0.45	0.75

H SUFFIX
CASE 1213-01
 Plastic Package
 (SOT-89)
 ISSUE O



- NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
 2. INTERPRET DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
 3. DATUM C IS A SEATING PLANE.

MILLIMETERS		
DIM	MIN	MAX
A2	1.40	1.60
B	0.37	0.57
B1	0.32	0.52
C	0.30	0.50
D	4.40	4.60
D1	1.50	1.70
E	—	4.25
E1	2.40	2.60
e	1.50 BSC	
e1	3.00 BSC	
L1	0.80	—